# microwave JOURNAL.

DECEMBER 2002 VOL. 45, NO. 12

www.mwjournal.com



**CONTROL DEVICES** 

5 GHz CMOS VCO FOR 802.11A WLANS

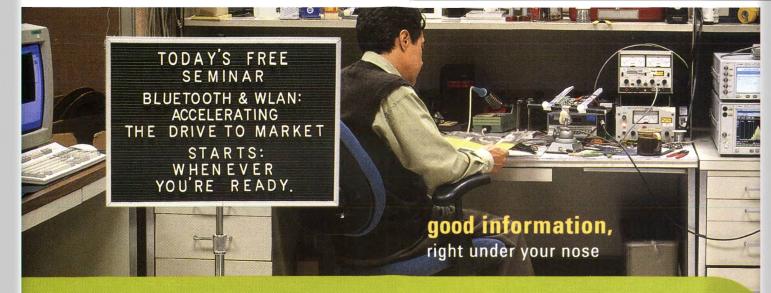
MEASUREMENT-BASED MODEL FOR I/Q MODULATORS

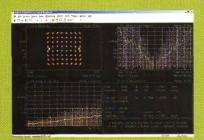
2002 EDITORIAL INDEX

CONTENTS, P. 10

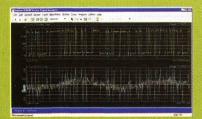
Founded in 1958







For this IEEE 802.11a signal, the overall EVM measurement is acceptable but viewing EVM versus time (lower left) and channel (upper right) shows the effect of a timing error.



The FSK error display can highlight the effects of unwanted frequency modulation, which may indicate the presence of spurious signals in the modulator.

#### www.agilent.com/find/wn

u.s. 1-800-452-4844, ext. 7682 canada 1-877-894-4414, ext. 7686 The original idea was simple: use wireless links to give the wired generation more mobility. Of course, turning *Bluetooth* and Wi-Fi into reality—without much time for analysis—has been anything but simple. Perhaps we can help.

Enhancing interoperability. Many people attribute Wi-Fi's popularity to WECA testing that certifies device interoperability. Those who've passed tell us the roots of success often reach back to early tweaks in their transmitter or receiver designs. For transmitters, error vector magnitude (EVM) versus time or channel is a measure of modulation quality that can highlight underlying problems such as nonlinear distortion, phase noise and spurious signals. Conversely, making receivers more forgiving of nonideal transmitters can come from testing with impaired signals—in hardware, simulation or a system that links both.

Achieving certification. The Agilent Interoperability Certification Labs and Agilent's network of test partners are ready to help, too: they've tested hundreds of Wi-Fi devices and can help you clear the qualification hurdle.

To learn more, please visit www.agilent.com/find/wn, where you can request a FREE CD-ROM packed with articles, solution guides, and application notes such as "RF Testing of Wireless LAN Products" and "Verifying Bluetooth Baseband Signals."



### **Agilent Technologies**

dreams made real

Albania 355-42-23-519 \* Algaria 213-2-608-450 \* Australia 1-800-629-485 \* Australia 1-800-629-48



### Picoprobe elevates probe cards to a higher level...

### (...110 GHz to be exact.)

For 17 years GGB Industries, Inc., has blazed the on-chip measurement trail with innovative designs, quality craftsmanship, and highly reliable products. Our line of custom microwave probe cards continues our tradition of manufacturing exceptional testing instruments.

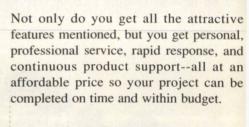


Through unique modular design techniques, hundreds of low frequency probe needles and a variety of microwave probes with operating frequencies from DC to 40, 67, or even 110 GHz can be custom configured to your layout.

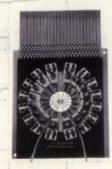


Our patented probe structures provide the precision and ruggedness you require for both production and characterization testing. And, only Picoprobe® offers the lowest loss, best match, low inductance power supplies, and current sources on a single probe card.

Our proven probe card design technology allows full visibility with inking capability and ensures reliable contacts, even when probing non-planar structures.



Typical Specs 10GHz 20GHz 40GHz Insertion Loss 0.6 dB 0.8 dB 1.3 dB Return Loss 22 dB 18 dB 15 dB



For technical assistance, custom product designs, or off-the-shelf delivery, call GGB Industries, Inc., at (941) 643-4400.

#### GGB INDUSTRIES, INC.

- P.O. BOX 10958
- **NAPLES, FL 34101**

- Telephone (941) 643-4400
- Fax (941) 643-4403
- E-mail email@ggb.com
- www.picoprobe.com



Choose from thousands of off-the-shelf models from Mini-Circuits, in stock and immediately available! From 2 and 3way to 48way; 0°, 90°, 180°; 50 &75 ohms covering 2kHz to 10GHz and beyond...all characterized with data and performance curves in our catalog and "The YONI Search Engine" at our web site. Mini-Circuits will also supply your special needs and custom designs such as wider bandwidths, higher isolation, lower insertion loss and phase matched ports...all at catalog prices with rapid turnaround time. Case styles include surface mount, plug-in, flat pack, coaxial connectorized...and custom packages are no problem! Our super-miniature and ultra-low profile Blue Cell<sup>TM</sup> surface mount units provide excellent solutions in cellular, cable, and countless wireless applications. Plus all units come with a 1 year guarantee and skinny 4.5 sigma performance repeatability. Add unsurpassed applications support and value pricing, and the decision is easy. Contact Mini-Circuits today! *Mini-Circuits...we're redefining what VALUE is all about!* 









CIRCLE READER SERVICE CARD

P.O. Box 350166, Brooklyn, New York 11235-0003 (718) 934-4500 Fax (718) 332-4661 For quick access to product information see MINI-CIRCUITS CATALOG & WEB SITE

The Design Engineers Search Engine Provides ACTUAL Data Instantly From MINI-CIRCUITS At: www.minicircuits.com

# MDC has taken Coaxial Components to a Higher Power

MDC offers high power, custom coaxial components for broadband airborne applications and for high power testing.

Directional couplers, combiners, terminations and harmonic absorptive filters are available for power levels from 100-1000 watts cw.

MDC also specializes in broadband waveguide components.











MICROWAVE DEVELOPMENT COMPANY, INC.

Forty One Northwestern Drive Salem, New Hampshire 03079 Sales: (603) 870-6280 • Fax: (603) 870-6210 E-Mail: microway@mdc.usa.com

EST. 1981



K&L MICROWAVE

## Mini-Pack

Minimum Size — Complete Package

A DOVER COMPANY

K&L Microwave introduces its new *Mini-Pack* ...

Compared to standard comblines or interdigitals this new cavity filter offers considerable reductions in volume and weight. The *Mini-Pack* ... is available in a wide range of frequencies from 6 GHz to 18 GHz with up to 10 sections, making it ideal for military applications. By meeting and exceeding the requirements of most military filters, K&L is offering maximum performance in a complete package.

Weight: 2 9ms
Dimensions:

675"x.475"x.160"

Reduction = 75%

Reduction = 98

Sometimes SIZE Is Everything

Filtering/Solutions for Your Global Market

visit us online at www.klmicrowave.com

USA: 410-749-2424 \* sales@klmicrowave.com \* UK: 44-(0)-1908-224746 \* sales@kleurope.com

Click LEADnet at mwjournal.com or Circle 44 on Reader Service Card

### INNOVATIVE



### RF Components

Now entering our fourth decade, JFW Industries is a proven leader in the design and production of innovative RF solutions. Whether your project calls for fixed attenuators and terminations, manually and electronically controlled attenuators, RF switches, power dividers or programmable RF test systems and switch matrices: JFW's dedicated customer service and engineering personnel can provide application specific components and sub-systems at catalog prices with an off-the-shelf attitude. For more information, please contact us or visit our web site at www.jfwindustries.com

### JFW Industries, Inc.

Specialists in Attenuation and RF Switching

TEL (317) 887-1340 Toll Free 1 (877) 887-4539 Fax (317) 881-6790

5134 Commerce Square Dr. • Indianapolis, Indiana 46237

Internet – http://www.jfwindustries.com E-mail – sales@jfwindustries.com ISO 9001 Certified

Click LEADnet at mwjournal.com or Circle 42 on Reader Service Card



- · Built-in LNA for Post Receiver
- In-Situ Calibration
- A Turnkey Approach
- Common C++ Software Platform
- ADS/Microwave Office Data Format
- Application Specific Modules
- Multi-Mode System Architecture
- Fixture and Pad De-Embedding

There has never been a better time to call MAURY for a complete measurement solution; mechanical, solid state, or multi-mode.



### MICROWAVE

CORPORATION

www.maurvmw.com

2900 Inland Empire blvd., Ontario, CA 91764 • USA • Tel: 909-987-4715 • Fax: 909-987-1112 • Email: maury@maurymw.com



For RF Device Measurement Solutions



**DECEMBER 2002 • VOL. 45, NO. 12** 

### **FEATURES**

### TUTORIAL

### 20 High Efficiency Class B, E and F Power Amplifiers: The Magic of Parallel Circuits

Andrei Grebennikov, M/A-COM Eurotec Operations

Use of class B, E and F power amplifiers to develop high efficiency long-term operating conditions in commercial and military communication systems

### TECHNICAL FEATURES

### 56 Understanding W-CDMA Modulation Quality Measurements

Marta Iglesias, Agilent Technologies

Exploration of key transmitter modulation quality conformance measurements for W-CDMA user equipment

### 74 A Fully-integrated 5 GHz 0.18 μm CMOS VCO for 802.11a WLAN Applications

Yuan-Kai Chu and Huey-Ru Chuang, National Cheng Kung University Presentation of a fully-integrated 5 GHz CMOS voltage-controlled oscillator with an output frequency range covering 5925 to 6025 MHz

#### TECHNICAL NOTE

### 82 A Measurement-based Behavioral Model for I/Q RF Modulators

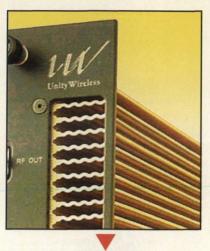
Joel Dunsmore, Greg Jue and John Kikuchi, Agilent Technologies

Description of a nonlinear behavioral modeling technique for application to I/Q modulated communication channels

### SPECIAL REPORT

### 90 2002 Editorial Index

A complete listing of 2002 *Microwave Journal* articles organized by subject and indexed alphabetically by author



### ON THE COVER

A feedforward multi-carrier linear power amplifier with 60 W maximum average output is featured on this month's cover

Cover art courtesy of Unity Wireless Systems Corp.

94

### 45 Years of Publishing Excellence

Microwave Journal (USPS 396-250) (ISSN 0192-6225) is published monthly by Horizon House Publications Inc., 685 Canton St., Norwood, MA 02062. Periodicals postage paid at Norwood, MA 02062 and additional mailing offices.

Photocopy Rights: Permission to photocopy for internal or personal use, or the internal or personal use of specific clients, is granted by Microwave Journal for users through Copyright Clearance Center provided that the base fee of \$5.00 per copy of the article, plus \$1.00 per page, is paid directly to the Copyright Clearance Center, 222 Rosewood Drive, Danvers, MA 01923 USA (978) 750-8400. For government and/or educational classroom use, the Copyright Clearance Center should be contacted. The rate for this use is 0.03 cents per page. Please specify ISSN 0192-6225 Microwave Journal International. Microwave Journal can also be purchased on 35 mm film from University Microfilms, Periodic Entry Department, 300 N. Zeeb Rd., Ann Arbor, MI 48106 (313) 761-4700. Reprints: For requests of 100 or more reprints, contact Kristen Dednah at (781) 769-9750.

POSTMASTER: Send address corrections to *Microwave Journal*, PO Box 3256, Northbrook, IL 60065-3256 or e-mail mwj@omeda.com. Subscription information: (847) 291-5216. This journal is issued without charge upon written request to qualified persons working in that part of the electronics industry, including governmental and university installation, that deal with VHF through light frequencies. Other subscriptions are: domestic, \$120.00 per year, two-year subscriptions, \$185.00; foreign, \$200.00 per year, two-year subscriptions, \$370.00; back issues (if available) and single copies, \$10.00 domestic and \$20.00 foreign.

©2002 by Horizon House Publications Inc.



Horizon House also publishes

Telecommunications®

The Journal of Electronic Defense

[Continued on page 12]

Posted under Canadian international publications mail agreement #0738654

### WIN WITH V8'S POWER COMBINATION

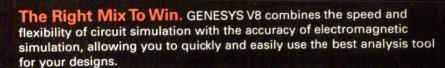
EM-CIRCUIT CO-SIMULATION



(courtesy: Infineon Technologies)



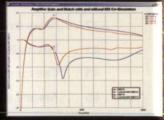
The schematic and layout of a LNA circuit



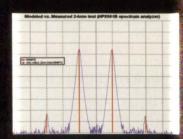
Say goodbye to traditional software that is tedious and error prone when combining EM simulation with circuit simulation.

GENESYS makes it simple. Just ask GENESYS to simulate the layout with the harmonic balance or s-parameter simulator. It automatically runs EM simulation on the layout, runs circuit simulation on the lumped elements, and displays the combined response. Lets you view the effect of layout parasitics quickly and easily. Even better, you can tune the lumped components to compensate for secondary electromagnetic effects in real time.

So Grab a Seat and Hold On! And get the extra power, speed and accuracy of EM-Circuit co-simulation. With co-simulation packages starting at \$6,450 US, you'll be a winner every time.



S-parameters shift slightly when electromagnetic effects are considered



TEST LINK reads measured data and compares results with your model

Phone: +1 678-291-0995

sales@eagleware.com



www.eagleware.com

Fax: +1 678-291-0971



### **FEATURES**

### PRODUCT FEATURES

### 104 New Substrate Technology for High Performance Circuits and Systems

Lamina Ceramics

Development of a low temperature co-fired ceramic on metal substrate technology used to address dense component placement, high heat dissipation and frequencies associated with high performance devices

### 108 RF/Microwave Manipulators for Precise Test Probe Measurements

Micromanipulator Co.

Introduction to a new series of precision microwave manipulators that feature direct leadnut coupled drives and magnetic-assisted vacuum bases

### **DEPARTMENTS**

15 . . . Coming Events

18 . . . Workshops & Courses

37 . . . News from Washington

41 . . . International Report

45 . . . Commercial Market

48 . . . Around the Circuit

112 . . . Web Update

120 ... New Products

126 . . . New Literature

128 . . . The Book End

130 . . . Ad Index

134 . . . Sales Reps

### **LOOKING AHEAD TO NEXT MONTH**

### January 2003: Radar/Antennas

The editorial highlight next month is radar and antennas. With the emergence of compact wireless local area networks and other miniature high frequency applications, innovative new antenna designs have become a necessity. The January issue will feature some of these new trends and highlight some specific antenna designs aimed at the wireless market. A summary of the upcoming events at the Wireless System Design show to be held in San Jose in February will also appear.

Press run for this issue is 52,512 copies

Printed in the USA

### STAFF

PUBLISHER: CARL SHEFFRES

ASSOCIATE PUBLISHER: EDWARD JOHNSON

EDITOR: HARLAN HOWE, JR.

MANAGING EDITOR: KEITH W. MOORE

TECHNICAL EDITOR: FRANK M. BASHORE

ASSOCIATE TECHNICAL EDITOR: DAN MASSÉ

STAFF EDITOR: JAMES T. WALSH

EDITORIAL ADMINISTRATORS: JENNIFER DIMARCO

CONSULTING EDITOR: HOWARD I, ELLOWITZ
CONSULTING EDITOR: THEODORE S, SAAD
CONSULTING EDITOR: PETER STAECKER
INT'L CORRESPONDENT: MARTIN STREETLY
INT'L STAFF EDITOR: STEVE McCLELLAND

INT'L CORRESPONDENT: MARTIN STREETLY
INT'L STAFF EDITOR: STEVE McCLELLAND
ASSISTANT TO THE PUBLISHER: KRISTEN DEDNAH
TRAFFIC MANAGER: EDWARD KIESSLING
TRAFFIC ADMINISTRATOR: KEN HERNANDEZ
DIRECTOR OF PRODUCTION & DISTRIBUTION:

ROBERT BASS

DESIGN DIRECTOR: R.A. PIKE
ART DIRECTOR: BILL HAFF

DTP COORDINATOR: JANET A. MACDONALD
GRAPHIC DESIGNER: SACHIKO STIGLITZ
GRAPHIC DESIGN GROUP:

SANDRA DENEAULT • AMANDA RUPPERT

#### EUROPE

DEPUTY PUBLISHER: SAM BAIRD

EUROPEAN EDITOR: RICHARD MUMFORD

OFFICE MANAGER: EUGENIE HARDY

#### CORPORATE STAFF

CHAIRMAN & EXECUTIVE OFFICER: WILLIAM BAZZY
PRESIDENT: WILLIAM M. BAZZY
VP FINANCE & OPERATIONS: CHARLES A. AYOTTE
CORPORATE VICE PRESIDENT: JOAN B. EGAN

#### **EDITORIAL REVIEW BOARD:**

Dr. S.F. Adam Dr. G.L. Matthaei Dr. I.J. Bahl W.G. Matthei Dr. R.C. Baird Dr. D.N. McQuiddy D.K. Barton Dr. R.L. Metivier Dr. E.F. Belohoubek C.K.S. Miller Dr. C.R. Boyd Dr. F.R. Morgenthaler K.J. Button Dr. N.S. Nahman Dr. K.L. Carr Dr. J.M. Osepchuk H.F. Chapell S.M. Perlow N.R. Dietrich Dr. L.J. Ricardi G. DiPiazza Dr. U. Rohde Dr. Z. Galani Dr. G.F. Ross Dr. J.A. Saloom Dr. F.E. Gardiol Dr. A. Gilardini Dr. P. Staecker Dr. P. Goldsmith H. Stinehelfer Dr. M.A.K. Hamid Dr. H.E. Stockman J.J. Taub J.L. Heaton Dr. J.G. Tenedorio G.D. Vendelin E.E. Hollis Dr. W.E. Hord Dr. L. Lewin Dr. W.A.G. Voss Dr. J.C. Lin Dr. B.O. Weinschel Dr. Stephen Maas Dr. P. Weissglas Dr. R.J. Mailloux Dr. J. Wiltse S. March

#### **EXECUTIVE EDITORIAL OFFICE:**

685 Canton Street, Norwood, MA 02062 Tel: (781) 769-9750 Fax: (781) 769-5037 e-mail: mwj@mwjournal.com

#### www.mwjournal.com

#### **EUROPEAN EDITORIAL OFFICE:**

46 Gillingham Street, London SWIV 1HH, England Tel: Editorial: +44 207 596 8730 Sales: +44 207 596 8740 FAX: +44 207 596 8749

### 18-40 GHz

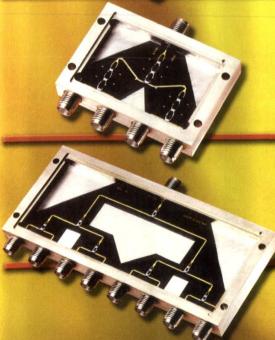
### Features

- Wide Frequency Range . . . 18-40 GHz
- High Isolation .... >17 dB
- Low Insertion Loss ..... 1.6-3.4 dB typ. Input/Output VSWR ..... 1.7:1 typ.
- Amplitude Balance . . . . ±0.4 dB typ.
- Phase Unbalance . . . . . ±2° typ.





RF INPUT PARAMETERS	S UNITS	MINIMUM	MAXIMUM
2 Way Pow	er Divider	- Model DO	289
RF frequency range	GHz	18	40
Insertion loss	dB		1.5
Isolation	dB	17	
Input VSWR	Ratio		1.8
Output VSWR	Ratio		1.7
Phase unbalance	Degrees		±5.0
Amplitude balance	dB		±0.5



4 Way Pow	ver Divider -	Wodel DU2	189
RF frequency range	GHz	18	40
Insertion loss	dB		2.5
Isolation	dB	17	
Input VSWR	Ratio		1.8
Output VSWR	Ratio		1.7
Phase unbalance	Degrees		±5.0
Amplitude balance	dB		±0.5

8 Way Pov	ver Divider -	Model DO	389
RF frequency range	GHz	18	40
Insertion loss	dB		3.5
Isolation	dB	17	
Input VSWR	Ratio		1.8
Output VSWR	Ratio		1.7
Phase unbalance	Degrees		±5.0
Amplitude balance	dB		±0.5

For further information, please contact John Pierro (631) 439-9137 or e-mail ipierro@miteq.com

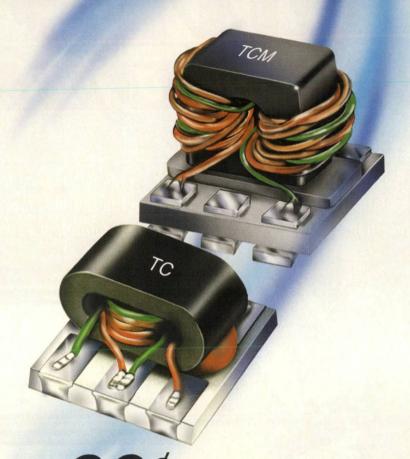




100 Davids Drive, Hauppauge, NY 11788 Tel: 631-436-7400 • Fax: 631-436-7430

www.miteq.com

### RF TRANSFORMERS



.3-2500MHZ as low as 99¢ each (qty. 100

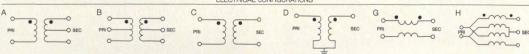
It used to be that small RF transformers with high end performance cost a lot, but not since Mini-Circuits introduced the all ceramic leadless TC and high strength plastic leaded TCM families. Now you can get impedance ratios from 0.1:1 to 16:1 ohms with good return loss and broad bandwidths from 0.3 to 2500MHz at price buster values. Plus, these ultra-small performers are all-welded and have solder plated leads for high reliability and solderability, excellently suited for your automated pick-and-place assembly operations. So have it both ways; high performance AND low price with Mini-Circuits TC and TCM surface mount transformers.

Detailed Performance Data & Specs Online at: www.minicircuits.com/model

	EADLESS (	Ceramic Bas	е		LE LE	EADS Plas	tic Base		
MODEL TC1-1T TC1-1 TC1-15	Ω Ratio & Config. 1A 1C 1C	Freq. (MHz) 0.4-500 1.5-500 800-1500	Ins. Loss* 1dB (MHz) 1-100 5-350 800-1500	Price \$ea. (qty. 100) 1.19 1.19 1.29	(actual size) MODEL TCM1-1 TCML1-11 TCML1-19		Freq. (MHz) 1.5-500 600-1100 800-1900	Ins. Loss* 1dB (MHz) 5-350 700-1000 900-1400	Price \$ea. (qty. 100) .99 1.09 1.09
TC1.5-1 TC2-1T TC3-1T	1.5D 2A 3A	.5-2200 3-300 5-300	2-1100 3-300 5-300	1.59 1.29 1.29	TCM2-1T TCM3-1T TTCM4-4	2A 3A 4B	3-300 2-500	3-300 5-300	1.09 1.09
TC4-1T TC4-1W TC4-14	4A 4A 4A	.5-300 3-800 200-1400	1.5-100 10-100 800-1100	1.19 1.19 1.29	TCM4-1W TCM4-6T	4A 4A	0.5-400 3-800 1.5-600	5-100 10-100 3-350	1.29 .99 1.19
TC8-1 TC9-1 TC16-1T	8A 9A 16A	2-500 2-200 20-300	10-100 5-40 50-150	1.19 1.29 1.59	TCM4-14 TCM4-19 TCM4-25	4A 4H 4H	200-1400 10-1900 500-2500	800-1000 30-700 750-1200	1.09 1.09 1.09
TC4-11 TC9-1-75	50/12.5D 75/8D	2-1100 0.3-475	5-700 0.9-370	1.59 1.59	TCM8-1 TCM9-1	8A 9A	2-500 2-280	10-100 5-100	.99 1.19

Dimensions (LxW): TC .15" x .15" TCM .15" x .16" Referenced to midband loss.

ELECTRICAL CONFIGURATIONS



Mini-Circuits®

CIRCLE READER SERVICE CARD

P.O. Box 350166, Brooklyn, New York 11235-0003 (718) 934-4500 Fax (718) 332-4661 For quick access to product information see MINI-CIRCUITS CATALOG & WEB SITE

The Design Engineers Search Engine Provides ACTUAL Data Instantly From MINI-CIRCUITS At: www.minicircuits.com



Wireless Communications Association Technical Symposium January 13–15, 2003 San Jose, CA

This ninth annual event will convene more than 1000 broadband wireless experts from 20 nations, collocated for the first time with the plenary meeting of the IEEE 802.16 Working Group on BWA. For more information, visit: www.wcai.com or contact: Colleen O'Reilly at colleen@wcai.com.

7th International Commercialization of Military and Space Electronics Conference and Exhibition (CMSE) February 10–13, 2003
Los Angeles, CA

This conference is organized by Components Technology Institute Inc. in cooperation with EIA/ECA, IEEE/CPMT and IMAPS. It will specialize in COTS systems, subsystems, circuit boards and components while also emphasizing new technology, processes and design practices. Emphasis will be placed on practical solutions, new techniques and how to assess the risks of COTS and make cost-effective decisions that meet the mission requirements. Working groups and discussion sessions are planned on specific topics of concern to the industry. New issues identified by the delegates to the previous year's conference will also be addressed. Topics include: design practices, technology trends, applications, case studies/history, obsolescence management, radiation hardness, risk mitigation, selecting COTS and commercial suppliers, testing requirements and results, and constructive and destructive physical analysis. For further information, contact: Dale Stamps or Leon Hamiter at (256) 536-1304 or e-mail: dale@cti-us.com or lhamiter@cti.us.com. Information can also be accessed on-line at www.cti.us.com.

SATELLITE 2003 February 26–28, 2003 Washington, DC

This satellite conference and trade show features satellite operators, end-users, manufacturers, service providers, launch vehicle operators, teleports, consumer service providers and Wall Street financiers. For more information, contact: Cory Butler (301) 354-1669 or visit www.satellite2003.com.

International Conference on Subsurface and Surface Sensing and Imaging IV March 2-6, 2003 San Diego, CA

This conference reports advances and progress in the research and development of subsurface and surface sensing and imaging techniques, sensors and applications, and addresses the technical barriers encountered in multiple domains of subsurface and surface sensing and imaging. Topics include: surface and ground penetrating sensors, signal and data processing and propagation and modeling, material properties and characterizations, and cross-cutting commonalities across subsurface and surface sensing applications. Additional information is available at http://ee.tamu.edu/subsurfacesensing-conference. For further information, contact: Cam Nguyen, Department of Electrical Engineering, Texas A&M University, College Station, TX 77843 (979) 845-6259 or e-mail: cam@ee.tamu.edu.

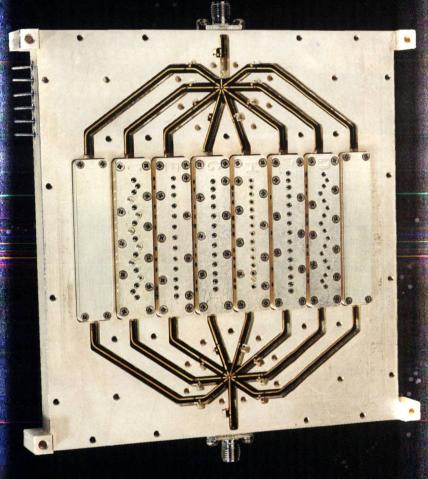
### **COMING EVENTS**

International Wireless Communications Expo (IWCE) March 9-15, 2003 Las Vegas, NV

This show plays host to more than 350 exhibiting companies and 10,000 attendees in the two-way mobile communications industry. Along with base station workshops, the IWCE conference program features the latest developments in business, regulatory, public safety



# REACTEL, INC. LUCIO CLUS COMBINED TO THE STREET COST



ISO 9001 Certified



RBACTEL, INC.

Address > 8031 Cessna Ave. Gaithersburg, MD 20879

Phone > 301.519.3660 Fax > 301.519.2447

Email > reactel@reactel.com

Web Site > www.reactel.com

Any Switch Filter Bank in the smallest package, and fastest solid-state switches in the industry, covering the frequency range from 10 MHz. to 18 Ghz.

Our business is custom building of RF & microwave filters, diplexers, multiplexers, switch filter banks, and mixers at 10 custom building prices.

Talk to any of our experienced engineers about your requirements or Visit OUT Web Site, and see some of the actual performance curves, and spec's for similar units.



and homeland security. For more information visit: www.iwceexpo.com.

IEEE Sarnoff Symposium March 12, 2003 Trenton, NJ

The conference includes an exhibition of components, technologies, systems and services, and also features tutorials. Topics: broadband wireless systems, network security, satellite communications, signal processing for communications, microwave device technology, modeling and simulations, optical networking, ultrawideband systems, VoIP and QoS, military communications, 3G mobile systems and wireless LANs, smart antennas and phase arrays, microwave photonics, and software radio. For additional program and registration information, visit http://ewh.ieee.org/rl/princeton-centraljersey/Sarnoff\_Symposium.htm or contact: Peter Zalud, symposium chair, Sarnoff Corp. at pzalud@sarnoff.com.

CTIA Wireless 2003 March 17-19, 2003 New Orleans, LA

With over 900 exhibitors, 500,000+ square-feet of space and nearly 40,000 attendees, this show is one of the largest and highly attended wireless shows in the telecommunication and computing industries. This event draws not only a traditional wireless audience of network providers, carriers and manufacturers but also brings in the users of wireless such as health care, government, military and automotive. Live Well, Work Smart, Play Hard... Wireless Makes it Possible. For more information, visit the show Web site at www. CTIAshow.com, or e-mail: conventions@ctia.org.

IEEE International Symposium on Electromagnetic Compatibility May 11–16, 2003 Istanbul, Turkey

Sponsors: IEEE EMC Society, URSI Commission E, IEE, EOARD, AEAI. This symposium will provide opportunities for EMC researchers, scientists, engineers and vendors to present the latest research results, discuss problems of current and mutual interest and exchange views and experience related to new EMC components, materials and equipment. Topics: research, development and applications on EMC and related disciplines. Main themes include designing for EMC, signal integrity, RF compatibility and spectrum engineering, test and measurement methods, numerical modeling, and lightning and EMP interactions. For further information, visit www. ortra.com/emc2003. In addition, the symposium will be accompanied by a technical exhibition related to EMC. For exhibition information, contact: Eddie Rosen, ORTRA Ltd., 1 Nirim Street, PO Box 9352, 61092 Tel-Aviv, Israel +972-3-6384444, fax +972-3-6384455, e-mail: emc2003@ortra.co.il or Elya B. Joffe, general chairman, eb.joffe@ieee.org.

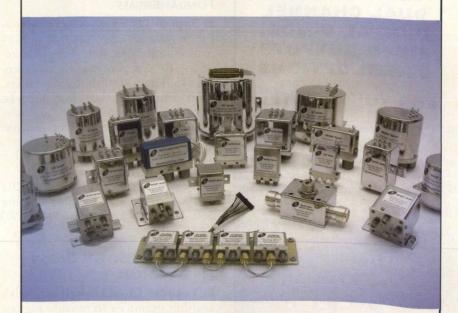
### **COMING EVENTS**

IEEE MTT-S International Microwave Symposium and Exhibition June 8-13, 2003 Philadelphia, PA

This symposium will serve as the centerpiece of Microwave Week 2003. Topics: research, development and application of RF and microwave theory and techniques. In addition to IMS2003, a microwave exhibition, a historical exhibit, the RFIC symposium and the ARFTG conference will be held during Microwave Week 2003. The

technical sessions will run Tuesday through Thursday of Microwave Week. Workshops will be held Sunday through Tuesday, and the ARFTG Microwave Measurements Conference will be held on Thursday and Friday. For further information, contact: Richard V. Snyder, general chair, RS Microwave Co. Inc., (973) 492-1207, e-mail: r.snyder@ieee.org, For exhibition information, contact: Kristen Dednah, Horizon House Publications, 685 Canton St., Norwood, MA 02062 (781) 769-9750 or e-mail: kdednah@mwjournal.com.

### The Right Switch for...



### ...the Right Application

- \* Over 28 Years of Proven Reliability
- \* Dedicated Customer Support
- \* SPST SP10T
- \* 50 ohm and 75 ohm
- \* DC-26.5 GHz
- \* High Power
- \* Comprehensive Testing
- \* Custom Switch Solutions

Do you have our new catalog?





#### DBP Microwave (formerly DB Products, Inc.)

253 N. Vinedo Avenue, Pasadena, CA 91107 626-449-3790 Fax: 626-449-7169 Sales and Information e-mail: info@dbp4switches.com

www.dbp4switches.com

ANY WAY YOU LOOK AT IT.....



FREQUENCY SYNTHESIZERS

SOURCES
TO 6.4 GHz
BROADBAND
NARROW BAND
LOW NOISE
1Hz RESOLUTION
µS SWITCHING
LOW SPURS
MANY MODELS
DUAL CHANNEL
DIGITAL Ø-MOD.
FIXED OUTPUTS
OTHER OPTIONS

**FOR YOUR SYSTEM** 

PTS HAS THE BROADEST LINE OF HIGH-PERFORMANCE SYNTHESIZERS ANYWHERE. HAVING SUPPLIED 30,000+UNITS WORLDWIDE SHOWS OUR TECHNOLOGICAL EXPERTISE AND MANUFACTURING CAPABILITY. CALL ON US FOR ONE UNIT OR 500.



Programmed Test Sources, Inc. Telephone: 978-486-3400 Fax: 978-486-4495

e-mail: sales@programmedtest.com www.programmedtest.com



### **WORKSHOPS & COURSES**

### RF WIRELESS ENGINEERING

- **Topics:** Designed to give electrical engineers the specialized training that they need to achieve competence in RF and wireless engineering. Students learn practical skills, such as component selection and impedance matching network design.
- Site: Atlanta, GA
- **Dates:** January 27–31, 2003
- Contact: Georgia Institue of Technology, 613 Cherry Street, Swann Bldg., 3rd Floor, Atlanta, GA 30332 (404) 385-3541.

### RF WIRELESS SYSTEM DESIGN FUNDAMENTALS

- **Topics:** Digital wireless communication systems concepts and performance limitations, system degradation due to RF components, wireless communication system budget profiles, propagation losses and link budgets, cost vs. performance issues, and performance of differing RF wireless system architecture.
- Site: Sunnyvale, CA
- **Dates:** February 3–5, 2003
- **Contact:** Besser Associates, 201 San Antonio Circle, Building E, Suite 280, Mountain View, CA 94040 (650) 949-3300.

### RF WIRELESS SYSTEM DESIGN FUNDAMENTALS

- **Topics:** Combines theory with real-life examples to provide participants with a complete foundation in digital communication techniques and their effects on RF circuit parameters. Fee: \$1145.
- Site: Phoenix, AZ
- **Dates:** March 10–12, 2003
- Contact: Besser Associates, 201 San Antonio Circle, Building E, Suite 280, Mountain View, CA 94040 (650) 949-3300.

### PHASED ARRAY ANTENNAS FOR COMMUNICATIONS AND RADAR

- **Topics:** The presentation of the necessary theory, basic principles of operation, components, and important design parameters of phased array antennas.
- Site: Davos, Switzerland
- Dates: March 17–21, 2003
- Contact: CEI-Europe AB, PO Box 910, S-612 25 Finspong, Sweden +46-122-175 70, fax +46-122-143 47.

### APPLIED RF TECHNIQUES IN WIRELESS SYSTEMS

- ended and balanced S-parameters, impedance matching, graphical and analytical design methods, discrete and monolithic RF component models, Smith chart techniques, transmission lines and RF CAE, PCB materials.
- Site: Nice, France
- **Dates:** April 7–11, 2003
- **Contact:** CEI-Europe AB, PO Box 910, S-612 25 Finspong, Sweden +46-122-175 70, fax +46-122-143 47.

### ANTENNA ENGINEERING

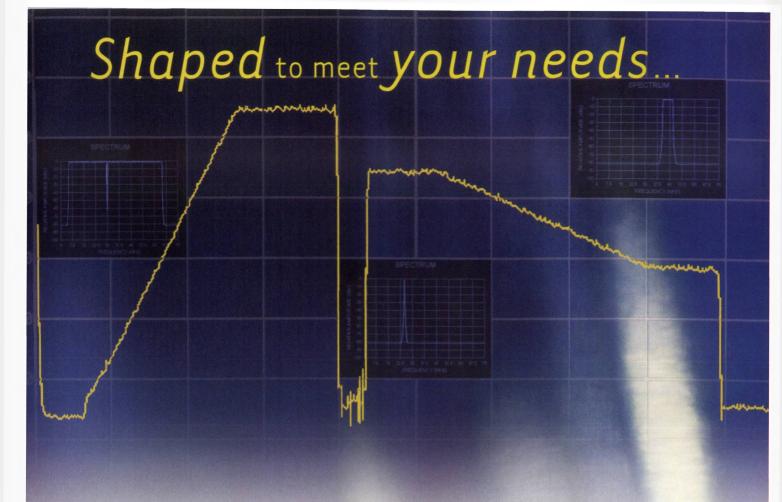
- **Topics:** Presents the theory and practice of antenna engineering covering the range of antenna properties and types from basic to state-of-theart. The antennas presented in the course cover a wide spectrum of frequencies.
- Site: Atlanta, GA
- **Dates:** April 28-May 2, 2003
- **Contact:** Georgia Institute of Technology, Continuing Education, PO Box 93686, Atlanta, GA 30377 (404) 385-3501.

### INTRODUCTION TO ELECTROMAGNETIC COMPATIBILITY DESIGN PRACTICES

- **Topics:** Fundamentals of electromagnetic compatibility (EMC/EMI), and focus on the methodology of how to minimize EMC problems. Attendees will be offered a hands-on personal consultation.
- Site: Northbrook, IL
- Dates: May 5–6, 2003 ■ Contact: DLS Electronic Systems
- Inc. (847) 537-6400.

### RF/MICROWAVE CIRCUIT DESIGN: LINEAR/NONLINEAR THEORY AND APPLICATIONS

- **Topics:** Enhance the design capability of the RF or microwave engineer by introducing modern linear and nonlinear design techniques. Seeks to combine the theory and practice of modern, computer-aided high frequency circuit design with greater intuition and increased insight.
- Site: Cambridge, UK
- **Dates:** May 12–16, 2003
- **Contact:** CEI-Europe AB, PO Box 910, S-612 25 Finspong, Sweden +46-122-175 70, fax +46-122-143 47.



### Simulate Real-World Operating Conditions with Custom Noise and Interference Signals

Introducing Noise Com's flexible, programmable *DNG7500 Digital Noise Generator*.

The Noise Com *DNG7500* generates programmable, user-specified, pseudo-noise and CW signal spectrums for RF, Microwave, and fiber-optic equipment testing. It provides the user with complete programmability of start and stop frequencies, brick-wall filters, tilt, and notch (stop-band) filtering—all with programmable frequency, bandwidth, and depth. Everything you need to precisely emulate real-world noise and interference conditions.

- Easily create custom waveforms using the DNG's proprietary GUI Interface.
- Accepts spectral parameters of noise and signals.
- · Converts spectral parameters into a waveform file.
- · Edit and save the file on the DNG's built-in hard drive.
- Custom frequency converters up to 40 GHz.

Take control of your test and measurement needs.
Call Noise Com for more information on the *DNG7500*Digital Noise Generator or other Noise Com products.



DNG7500 Digital Noise Generator

NOISE COM

A WIRELESS TELECOM GROUP COMPANY

Noise Com E. 64 Midland Ave. Paramus, NJ 07652 Phone: (201) 261-8797
Fax: (201) 261-8339
Email: info@noisecom.com
Web site: www.noisecom.com

Click LEADnet at mwjournal.com or Circle 74 on Reader Service Card

### TUTORIAL



# HIGH EFFICIENCY CLASS B, E AND F POWER AMPLIFIERS: THE MAGIC OF PARALLEL CIRCUITS

odern commercial and military communication systems require high efficiency, long term operating conditions. For this purpose, the power amplifiers, as final and highly current-consuming transmitter elements, are developed using the high efficiency class B, F or E modes of operation, depending on the technical requirements. In class B operation, which is a special case of

class C with a conduction angle of half a period, the collector voltage waveform is pure sinusoidal and harmonics are present in the collector current only. In class F power amplifiers, the fundamental and harmonic load impedances are optimized by using short-circuit termina-

All that is needed to design a high efficiency RF power amplifier is the proper choice of the parameters of the load network parallel circuit.

tion and open-circuit peaking, in order to control the collector voltage and current waveforms to obtain maximum efficiency. In class E amplifiers, an efficiency improvement is achieved by realizing the on/off switching operation with special current and voltage waveforms so that high voltage and high current do not exist at the same time. And if both collector voltage and current waveforms in an idealized class E mode contain all of the harmonics, then in class F only a certain amount of

harmonic content is needed for either collector voltage or current waveforms. For example, only odd harmonic components are necessary to realize the ideal collector voltage form, and even harmonics components to form the ideal current one. As a result, the impedance conditions are different when, for class F operation, there is need to create zero or infinite impedance at any harmonic component, whereas for class E operation, all reactances at the harmonics should be negative.

At first glance, it looks like these high efficiency operation modes do not have anything in common with each other since it is necessary to provide different impedance conditions as well as to apply different circuit design approaches. However, to approximate class F or E modes, it is enough to realize the required impedance conditions only for several harmonics<sup>1</sup> and, more importantly, to apply the same circuit design technique — one or several harmonically tuned parallel circuits or only one parallel circuit mistuned at the fundamental frequency. All that is needed to design a high efficiency RF power amplifier is the proper choice of the parameters of the load network parallel circuit.

[Continued on page 22]

ANDREI GREBENNIKOV
M/A-COM Eurotec Operations
Cork, Ireland

### Stop reinventing the wheel...

We may already have your COUPLER design solution in our extensive design files.

### **Typical Coupler Specifications:**

- Single and Dual Directional Couplers
- Frequency Range: 10 MHz to 40 GHz
- Accurate Coupling
   High Directivity
- Wide Bandwidths Flat Response
- High Power Up to 500 Watts
- Low Insertion Loss & VSWR
- SMA, N, BNC, TNC or Pins
- Low IM Characteristics
- Stripline or Airline
- Surface Mount

Standard or Custom Designs ISO9002 Certified RLC's high volume production capabilities keeps your project cost-effective and on schedule



RLC is your complete Microwave Component source . . . Switches, Filters, Power Dividers, Couplers, Terminations, Attenuators, DC Blocks, Bias Tees and Detectors.

Contact our Technical Service Department for more information where you will find a knowledgeable engineering staff, quick responses, short lead times and competitively priced quality products. Request RLC's catalog!



RLC ELECTRONICS, INC.

83 Radio Circle, Mount Kisco, New York 10549 • Tel: 914-241-1334 • Fax: 914-241-1753 e-mail: sales@rlcelectronics.com • www.rlcelctronics.com

# **QUIET DROS**



The desire for low noise Dielectric Resonator Oscillators to enhance clear communication, spectral purity, continues. Typical phase noise @ 100 KHz offset of -126 dBc/Hz for 10 GHz, -115 for 18 GHz and -108 for 38 GHz are being measure on our production DROs. Harmonics measured between -50 dBc and -80 dBc. Spurious are less than -90 dBc with -120 dBc available by request.

- No Phase Hits
- No Microphonics
- No Data Gaps
- No Interruptions
- · Just Clear, **Reliable Transmission**

Check the Lucix Website for outstanding features of our DROs, such as low power consumption, very small size, high output power, ultra stability. Tell us your special needs.

At Lucix, we listen!



800 Avenida Acaso, Unit E Camarillo, CA 93012 Tel: 805.987.6645 • Fax: 805.987.6145

www.lucix.com

### TUTORIAL

CLASS B

The equivalent circuit of a class B power amplifier with a parallel resonant circuit is shown in Figure 1, where C<sub>b</sub> is the blocking capacitance. The voltage and current waveforms for the active device operating in active and cut-off modes are also shown. The presence of an ideal parallel circuit, tuned at the fundamental frequency, leads to a sinusoidal collector voltage giving a sinusoidal current flowing into the load resistor R, while all harmonic current components are flowing through this parallel circuit having an infinite impedance at the fundamental and zero impedance at all harmonics. If the output device impedance at the required output power level is different from a 50  $\Omega$  load, then it is necessary to incorporate a matching circuit with the appropriate impedance ratio between the parallel circuit and the load.

Analytically, class B operation can be written as

$$\begin{split} i_c = \begin{cases} I_q + I\cos\omega t, & -\theta \leq \omega t < \theta \\ 0, & \theta \leq \omega t < 2\pi - \theta \end{cases} \end{split} \tag{1}$$

where

 $\begin{array}{l} I_{\rm q} = {\rm quiescent~current} \\ I = {\rm fundamental~current~amplitude} \end{array}$ 

 $\theta$  = conduction angle part of the RF current cycle, for which the device conduction occurs and determines the point in time when the collector current ic takes a zero value

At this moment

$$i_c = 0 = I_q + I\cos\theta$$
 (2)

and the conduction angle  $\theta$  can be calculated from

$$\cos \theta = -\frac{I_{q}}{I} \tag{3}$$

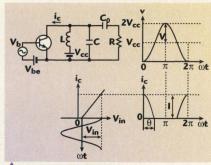


Fig. 1 Equivalent circuit of a class B power amplifier.

Consequently, in a common case

$$i_c = I(\cos\omega t - \cos\theta)$$
 (4)

When  $\omega t = 0$ , the collector current has a maximum amplitude of

$$i_c = I_{max} = I(1 - \cos\theta) \tag{5}$$

From Equation 3 one can obtain the following basic definitions: when  $\theta > 90^{\circ}$ , then  $\cos \theta < 0$ ,  $I_q > 0$  corresponding to class AB operation; when  $\theta = 90^{\circ}$ , then  $\cos \theta = 0$ ,  $I_q = 0$  corresponding to class B operation; when  $\theta$  < 90°, then  $\cos\theta$  > 0,  $I_q$  < 0 corresponding to class C operation.

As a result, the periodic half-cosinusoidal output current ic could be represented as a Fourier series expansion

$$i_c = I_0 + I_1 \cos\omega t + I_2 \cos2\omega t + I_3 \cos3\omega t + \dots$$
 (6)

where the DC, fundamental and harmonic components can be obtained

$$I_0 = \frac{1}{2\pi} \int_{-\theta}^{\theta} I(\cos \omega t - \cos \theta) d(\omega t) = I\gamma_0$$
(7)

 $I_1 =$  $\frac{1}{\pi} \int_{0}^{\pi} I(\cos \omega t - \cos \theta) \cos \omega t d(\omega t) = I\gamma_{1}$ (8)

$$I_{n} = \frac{1}{\pi} \int_{-\theta}^{\theta} I(\cos \omega t - \cos \theta)$$

$$\bullet \cos(n\omega t) d(\omega t) = I\gamma_{n}(\theta)$$
 (9)

where

$$\gamma_0(\theta) = \frac{1}{\pi} \left( \sin \theta - \theta \cos \theta \right)$$

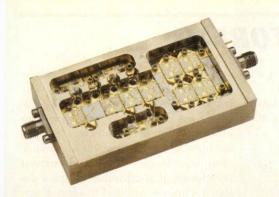
$$\gamma_1(\theta) = \frac{1}{\pi} \left( \theta - \sin \theta \cos \theta \right)$$

$$\gamma_n(\theta) = \frac{2}{\pi} \frac{\sin n\theta \cos \theta - n \cos n\theta \sin \theta}{n(n^2 - 1)},$$

$$n = 2, 3, ...$$

Consequently, in contrast to the class A operation mode where  $\theta =$ 180° and the DC current is equal to the quiescent current during the whole period, for the other abovementioned operating modes with  $\theta$  <

[Continued on page 24]







### CUSTOM MICROWAVE AMPLIFIERS

Exactly What You Need... Exactly When You Need It\*

### Features:

- · Built to order
- Removable SMA connectors
- Competitive pricing
- Compact size

### **Options:**

- · Alternate gain, noise, power, VSWR levels
- Temperature compensation
- · Gain control



ISO 9001

Contact us for a copy of our catalog!

#### **New Contact Information!**





2584 Junction Avenue, San Jose, CA 95134-1902 p: 408 = 919-5300 f: 408 = 919-1505 www.jcatech.com • www.newfocus.com email: jca@jcatech.com

#### Ultra broadband

Model	Freq. Range GHz	Gain dB min	N/F dB max	Flatness +/-dB	1 dB Comp. pt. dBm min	3rd Order ICP typ	VSWR In/Out max	DC Current mA
JCA018-203	0.5-18.0	20	5.0	2.5	7	17	2.0:1	250
JCA018-204	0.5-18.0	25	4.0	2.5	10	20	2.0:1	300
JCA218-506	2.0-18.0	35	5.0	2.5	15	25	2.0:1	400
JCA218-507	2.0-18.0	35	5.0	2.5	18	28	2.0:1	450
JCA218-407	2.0-18.0	30	5.0	2.5	21	31	2.0:1	500

### Multi-octave amplifiers

Model	Freq. Range GHz	Gain dB min	N/F dB max	Flatness +/-dB	1 dB Comp. pt. dBm min	3rd Order ICP typ	VSWR In/Out max	DC Current mA
JCA04-403	0.5-4.0	27	5.0	1.5	17	27	2.0:1	550
JCA08-417	0.5-8.0	32	4.5	1.5	17	27	2.0:1	550
JCA28-305	2.0-8.0	22	5.0	1.0	20	30	2.0:1	550
JCA212-603	2.0-12.0	32	5.0	3.0	14	24	2.0:1	550
JCA618-406	6.0-18.0	20	6.0	2.0	25	35	2.0:1	600
JCA618-507	6.0-18.0	25	6.0	2.0	27	37	2.0:1	800

#### Medium-power amplifiers

Model	Freq. Range GHz	Gain dB min	N/F dB max	Flatness +/-dB	1 dB Comp. pt. dBm min	3rd Order ICP typ	VSWR In/Out max	DC Current mA
JCA12-P01	1.35-1.85	35	4.0	1.0	33	41	2.0:1	1000
JCA34-P02	3.1-3.5	40	4.5	1.0	37	45	2.0:1	2200
JCA56-P01	5.9-6.4	30	5.0	1.0	34	42	2.0:1	1200
JCA812-P03	8.0-12.0	40	5.0	1.5	33	40	2.0:1	1700
JCA1218-P02	12.0-18.0	22	4.0	2.0	25	35	2.0:1	700

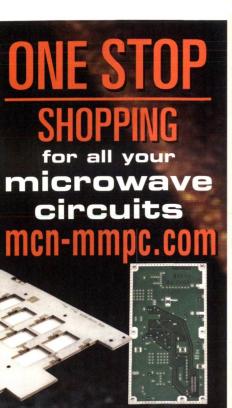
#### Low-noise octaveband LNAs

Model	Freq. Range GHz	Gain dB min	N/F dB max	Flatness +/-dB	1 dB Comp. pt. dBm min	3rd Order ICP typ	VSWR In/Out max	DC Current mA
JCA12-3001	1.0-2.0	40	0.8	1.0	10	20	2.0:1	200
JCA24-3001	2.0-4.0	32	1.2	1.0	10	20	2.0:1	200
JCA48-3001	4.0-8.0	40	1.3	1.0	10	20	2.0:1	200
JCA812-3001	8.0-12.0	32	1.8	1.0	10	20	2.0:1	200
JCA1218-800	12.0-18.0	45	2.0	1.0	10	20	2.0:1	250

#### Narrowband LNAs

Model	Freq. Range GHz	Gain dB min	N/F dB max	Flatness +/-dB	1 dB Comp. pt. dBm min	3rd Order ICP typ	VSWR In/Out max	DC Current mA
JCA12-1000	1.2-1.6	25	0.75	0.5	10	20	2.0:1	80
JCA23-302	2.2-2.3	30	0.8	0.5	10	20	2.0:1	80
JCA34-301	3.7-4.2	30	1.0	0.5	10	20	2.0:1	90
JCA56-401	5.4-5.9	40	1.0	0.5	10	20	2.0:1	120
JCA78-300	7.25-7.75	27	1.2	0.5	13	23	2.0:1	120
JCA910-3000	9.0-9.5	25	1.3	0.5	13	23	1.5:1	150
JCA910-3001	9.5-10.0	25	1.4	0.5	13	23	1.5:1	150
JCA1112-3000	11.7-12.2	27	1.4	0.5	13	23	1.5:1	150
JCA1213-3001	12.2-12.7	25	1.4	0.5	10	20	2.0:1	200
JCA1415-3001	14.4-15.4	35	1.6	1.0	14	24	2.0:1	200
JCA1819-3001	18.1-18.6	25	2.0	0.5	10	20	2.0:1	200
JCA2021-3001	20.2-21.2	25	2.5	0.5	10	20	2.0:1	200

\*Delivery in 2-4 weeks ARO.



### **Mixed Composites**

MCN prides itself by being woman owned, adapting to your needs, incorporating the latest equipment and keeping up to date with state-of-the-art technologies to provide the highest quality for military and commercial applications:

- Fine Line Etching
  (with tolerances to 0.0003")
- Complex Plating
- Tight Tolerance Machining
- · Laser Cutting
- Multi-layer & Hybrid Circuit Boards.

ISO-9002 CERTIFIED

### MODULAR COMPONENTS NATIONAL, INC.

2302 Industry Court, PO Box 453, Forest Hill, MD 21050 410/ 879-6553 Fax: 410/ 838-7629

E-mail: sales@mcn-mmpc.com www.mcn-mmpc.com



### MARYLAND MPC LLO

81 Old Ferry Road, Lowell, MA 01854 978/ 452-9061 Fax: 978/ 441-0004 E-mail: sales@mcn-mmpc.com www.mcn-mmpc.com

Click LEADnet at mwjournal.com or Circle 68 on Reader Service Card

24

### TUTORIAL

180°, the DC current component is a function of the conduction angle  $\theta$ .

The collector efficiency of a class B power amplifier, with an output power  $P_1$ , can be obtained from

$$\eta + \frac{P_1}{P_0} = \frac{1}{2} \frac{I_1}{I_0} \xi = \frac{1}{2} \frac{\gamma_1}{\gamma_0} \xi$$
 (10)

where

 $\xi = V/V_{cc}$  is the collector voltage peak factor

If  $\xi = 1$  and  $\theta = 90^\circ$ , then from Equation 8 it follows that the maximum collector efficiency in class B operation is

$$\eta = \frac{\pi}{4} \cong 0.785 \tag{11}$$

#### CLASS F

As can be seen from class B operation, only one parallel circuit tuned at the fundamental frequency results in insufficient high efficiency operating conditions. Additionally, Equation 11 represents the maximum ideal value, which is unrealizable in practice. Therefore, it is advisable to consider more efficient operation modes, which can ideally provide 100 percent collector efficiency.

First, consider the idealized load network harmonic conditions for class F operation<sup>2</sup>

$$Z_1 = R = \frac{8}{\pi} \frac{V_{cc}}{I_{max}}$$

 $Z_n = 0\Omega$  for even n

$$Z_n = \infty \Omega$$
 for odd n (12)

where

R = load

n = harmonic component

The ideal voltage and current shapes corresponding to the impedance conditions given by Equation 12 are shown in Figure 2. Here, a sum of odd harmonics gives a square voltage waveform and a sum of even harmonics approximates a half-sinusoidal current shape. Based on the analysis of the square voltage and half-sinusoidal current waveforms, it is necessary to provide a peaking of several current and voltage harmonic components in order to achieve a high value of power amplifier efficiency. The better flattening of the voltage waveform provided by high order harmonic components, the less power dissipation is due to the flow of

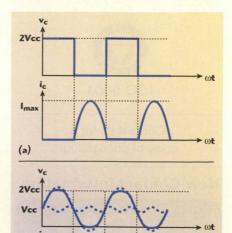
output current when the output voltage is extremely small. To understand the common design principles and to calculate numerically the power amplifier efficiency depending on the appropriate number of the frequency harmonic components of voltage and current waveforms, it is advisable to use a design technique applied to class F approximation with maximally flat waveforms.<sup>3,4</sup>

For example, an ideal class F amplifier with only the second harmonic voltage short-circuited and one third-harmonic current peaked realizes a maximum drain efficiency of 75 percent. In this case, for maximum voltage waveform flatness, the fundamental and third-harmonic voltages should be out-of-phase as shown, and the optimum ratios between voltage and DC current and appropriate harmonic components must be

$$V_1 = \frac{9}{8} V_{cc} \quad V_3 = \frac{1}{8} V_{cc}$$
 (13)

$$I_1 = \frac{4}{3}I_0 \qquad I_2 = \frac{1}{3}I_0 \qquad (14)$$

However, as follows from Equation 9, the current coefficient  $\gamma_3\theta$  becomes negative only for conductance angles of  $\theta > 90^\circ$ , which means class AB operation for a power amplifier with more than 50 percent duty cycle. There are also several other possibilities, like us-



A Fig. 2 Voltage and current waveforms corresponding to class F mode; (a) ideal conditions and (b) with third harmonics out of phase with the fundamental.

Imax

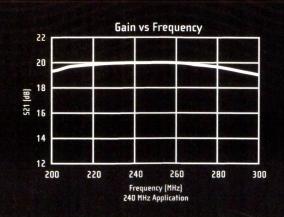
(b)

[Continued on page 26]

### High Gain, High Dynamic Range Amplifier

- 20 dB Gain
- •+40 dBm High OIP3
- 2.5 dB Noise Figure
- Frequency 50-1000 MHz
- •+5 V Supply

W) Communications Inc. is a leading RF semiconductor company focusing on the design and manufacture of high-quality devices and multi-chip modules (MCMs) for telecommunications systems worldwide. W)'s highly reliable amplifier, mixer, RF IC and MCM products are used to transmit and receive signals that enable current and next generation wireless and wireline services. For more information visit www.wj.com or call (408) 577-6200.





### THE COMMUNICATIONS EDGE™

WJ Communications Inc. 800-WJ1-4401 • fax: 408-577-6621 • sales@wj.com

### TUTORIAL

ing a slightly overdriven operation with a non-sinusoidal collector current waveform, including an out-of-phase third-harmonic, or using a non-sinusoidal driving signal containing the third-harmonic at the required amplitude. Nevertheless, in practice, due to the inherent active device nonlinearity, it is enough to choose a class AB mode with a small quiescent current, which is a compromise between power amplifier high efficiency and high gain operation.

The load network design approach for a high efficiency power amplifier can be based completely on using parallel resonant circuits tuned at the required harmonic frequency component. For example, to realize an idealized collector efficiency of 88.4 percent, it is necessary to incorporate an additional parallel circuit L<sub>3</sub>C<sub>3</sub> realizing the infinite impedance at the third-harmonic current component, as shown in Figure 3. In this case, a zero impedance at the second, fourth and higher harmonic components is assumed. The harmonic currents are flowing through the resonant circuit

L<sub>1</sub>C<sub>1</sub> tuned at the fundamental. Further efficiency improvement up to 92 percent can be made with the additional resonant circuit L<sub>5</sub>C<sub>5</sub> connected in series to the collector terminal and tuned at the fifth current harmonic component. At microwave frequencies, all these lumped parallel circuits connected in series should be replaced by a quarter-wave transmission line shortcircuited at the output. Such a circuit can ideally provide 100 percent collector efficiency, due to zero impedance at even harmonics and infinite impedance at odd harmonics. By having its characteristic impedance differ from the load, this transmission line can also realize the impedance transformation.

In reality, both extrinsic and intrinsic transistor parasitic elements have a substantial effect on the efficiency, especially at high frequencies. First, it is necessary to take into account the main influence of the device output capacitance  $C_{\rm out}$ , the collector capacitance  $C_{\rm c}$  for a bipolar device, or drain-source capacitance  $C_{\rm ds}$  for an FET device. For a lumped-circuit power amplifier, in order to approxi-

mate the ideal class F with harmonic impedance conditions of  $Z_1 = Z_3 = \infty$   $\Omega$  and  $Z_2 = 0$   $\Omega$  at the device output terminal by compensating the influence of  $C_{out}$ , it is also advisable to use an additional parallel circuit  $L_2C_2$  connected in parallel, as shown in **Figure 4**, where the series resonant

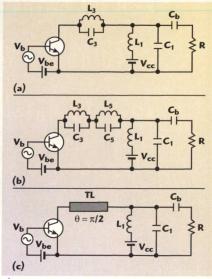
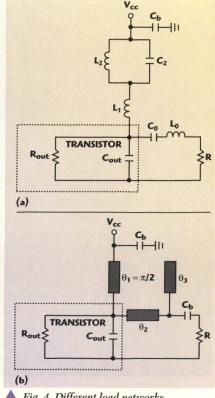
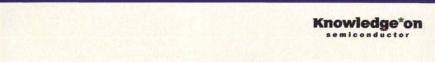


Fig. 3 Class F power amplifiers with different circuit realization (a), lumped parallel circuits (b) and quarter-wave transmission line (c).



▲ Fig. 4 Different load networks for class F power amplifiers; (a) lumped elements and (b) transmission line elements.

[Continued on page 28]



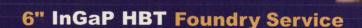
## True BT

Linearity IP3-P1dB=17.8dB

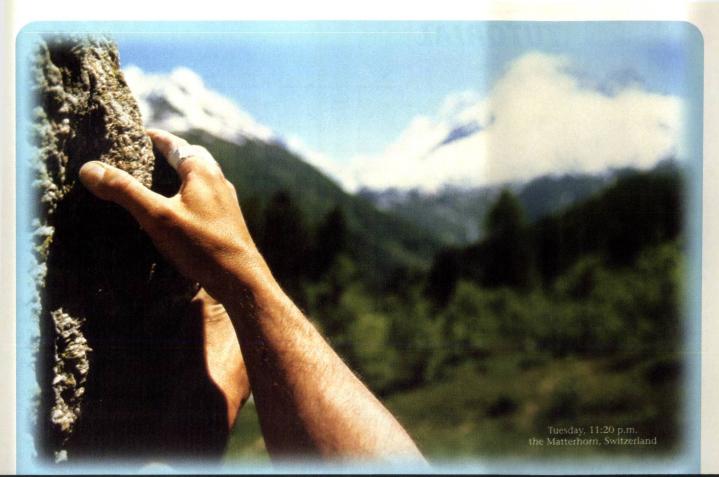
Low Noise NFmin=0.8dB, Gain=17.5dB at 3V, 4mA, f=2~8GHz

Long Lifetime
150 mil. Hrs at T<sub>j</sub> = 125 °C, Vce=3.5V, Jc=25KA/cm<sup>2</sup>

HP (High Power) process available BVceo>23V, fT=34GHz, fmax=73GHz



www.knowledge-on.com | Inquiry to fsm@knowledge-on.com | P.: +82-63-839-1150



### We know you have better things to do...

The RFMD® Advantage

High-performing, reliable, low-cost solutions

Broad technology base

Industry-leading capacity

Design expertise

Knowledgeable sales team

Application and design support

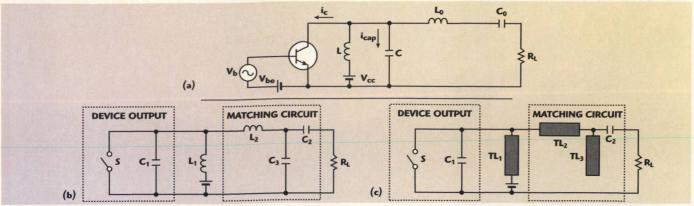
On-time delivery

Our communication solutions will give you a whole new perspective.



www.rfmd.com

### TUTORIAL



▲ Fig. 5 Equivalent circuit of a class E power amplifier with (a) a basic load network, (b) lumped resonant circuit and (c) transmission line elements.

circuit  $L_0C_0$  is tuned at the fundamental. As a result, the optimum ratios between the circuit elements can be calculated from<sup>4,5</sup>

$$L_{1} = \frac{1}{6\omega_{o}^{2}C_{out}},$$

$$L_{2} = \frac{5}{3}L_{1}, \quad C_{2} = \frac{12}{5}C_{out} \quad (15)$$

In order to increase maximum efficiency up to 88.4 percent, it is necessary to provide a short-circuit termination for all even harmonic volt-

age and an open-circuit impedance for the third-harmonic current. Such a class F operation mode is easy to realize by using transmission lines in the output circuit when one of them is connected in parallel to the active device between the output device terminal and voltage supply. Such a circuit schematic is the dual to the one shown in the previous figure, when the transmission line is connected in series, but is more acceptable for practical implementation since no additional losses are due to

the RF current at the fundamental frequency. Thus, for such a microstrip power amplifier, it is quite enough to provide the following electrical lengths of the transmission lines at the fundamental frequency<sup>4,5</sup>

$$\theta_1 = \frac{\pi}{2}, \ \theta_2 = \frac{1}{3} \tan^{-1} \left( \frac{1}{3 Z_o \omega_o C_{out}} \right),$$

$$\theta_3 = \frac{\pi}{6}$$
(16)

where

 $Z_0$  = characteristic impedance of each microstrip line

#### CLASS E

Switched-mode class E tuned power amplifiers are widely used in different frequency ranges and output power levels beginning from several kilowatts at low RF frequencies to approximately one watt at microwave frequencies. In such class E power amplifiers, the load network usually consists of a shunt capacitance and a series inductance, which allow operating the transistor as an on-off switch under optimum values of load network elements.6 The ideal shapes of the collector current and voltage waveforms demonstrate a condition when the high current and high voltage do not overlap simultaneously, that minimize the power dissipation and maximize the power amplifier efficiency up to 100 percent. However, such a load network configuration is not unique. For example, the switched-mode class E tuned power amplifiers with a parallel circuit, shown in Figure 5, can be an alternative to the class E tuned power amplifiers with a shunt capacitance,

[Continued on page 31]

Model Number	Frequency Range (GHz)	Gain (dB min)	Flatness (±dB max)	Noise Figure (dB max)	P-1dB (dBm min)	IP3 (dBm) typ	DC Current (mA nom) +15 Vdc
ML300K3P3001	300KHz - 3GHz	30	1.5	4.0***	20	30	370
ML001P1001	0.5 - 200MHz	10	0.5	5.5	30**	48	450
ML0016P0901	0.01 - 6.0	9	0.5	6.5*	25	36	320
ML0016P2001	0.01 - 6.0	20	1	3.2*	23*	36	480
ML0022P3601	0.02 - 2.5	36	0.75	3.8***	20	30	250
ML012P3801	0.1 - 2.0	35	1	2.7	26	36	450
ML052L1501T	0.5 - 2.0	15	0.5	0.9	9	18	65
ML0120L2403	0.1 - 20.0	24	1.5	3.0***	17	27	250
ML0123L2101	0.1 - 23.0	21	1.5	4.0***	8	18	170
ML0518P3202	0.5 - 18.0	32	2.0	3.5	22	32	360
ML218P2504	2.0 - 18.0	25	1.5	3.5	22	32	320
ML618P3301	6.0 - 18.0	33	2	3.0	30	40	1040
	amplifier BAND amplifiers				om		ing at 50
The same		P		1		OPTIO	



### ...than to worry about your next GSM power amplifier solution.

RFMD sets the standard when it comes to providing handset designers exactly what they need – highly integrated power amplifier solutions. That's why our engineers used our advanced third-generation GaAs HBT and silicon CMOS process technologies to design the RF3140 – RFMD's highest performing quad-band power amplifier module with integrated power control circuitry. The RF3140 is part of RFMD's second-generation PowerStar™ family of power amplifier modules with integrated power control. Our PowerStar™ solutions provide handset manufacturers reduced component count, improved production yield, simplified phone calibration and faster time-to-market – giving you more free time to reach new heights.

#### The RF3140 Features

- Integrated Power Control
  - Optimized Integrated Power Control
  - Power Ramping Utility Calculates Required Ramps
  - External Control Loop Components Eliminated
- Over 60% System Efficiency for GSM
- Over 55% System Efficiency for DCS
- 0 dBm Drive Level
- Superior Forward Isolation
- +35 dBm GSM Output Power at 3.5V
- +33 dBm DCS/PCS Output Power at 3.5V
- 10mm x 10mm x 1.4mm Leadless Package

### **Typical Applications**

- 3V Quad-Band GSM Handsets
- Commercial and Consumer Systems
- Portable Battery-Powered Equipment
- GSM850/EGSM900/DCS/PCS Products
- GPRS Class 12 Capable
- Part of the POLARIS™ TOTAL RADIO SOLUTION™

For sales or technical support, contact **336.678.5570** or **callcenter@rfmd.com**.

COMA COMAZOOD EDGE





HEE ROPITS TOMA TIMES WODMA



ProvidingCommunicationSolutions™

www.rfmd.com

Click LEADnet at mwjournal.com or Circle 81 on Reader Service Card



Marki Microwave



### DC BLOCK

1 kHz to 65 GHz



Click LEADnet at mwjournal.com or Circle 47 on Reader Service Card

FOR DETAILED SPECS, VISIT OUR WEBSITE

www.MarkiMicrowave.com

phone 408.778.4200 fax 408.778.4300 e-mail Mixers@MarkiMicrowave.com



### TUTORIAL

also realizing the high efficiency operation mode.<sup>4,7</sup> The load network with a parallel circuit consists of a parallel capacitance and a parallel inductance with an additional series filtering circuit to provide a high level of harmonic suppression.

The basic circuit of a switchedmode tuned parallel-circuit class E power amplifier is shown in the diagram. The load network consists of a parallel inductance L, a parallel capacitance C, a series  $L_0\hat{C}_0$  resonant circuit tuned at the fundamental frequency  $\omega_0 = 1/\sqrt{L_0C_0}$  and a load R. In a common case, a parallel capacitance C can represent the intrinsic device output capacitance and the external circuit capacitance added by the load network. The active device is considered to be an ideal switch that is driven in such a way as to provide the device switching between its onand off-state operating conditions. The loaded quality factor QL of the series resonant L<sub>0</sub> C<sub>0</sub> circuit should be high enough for the output current to be sinusoidal.

(a)

(a)

(b)

(b)

(c)

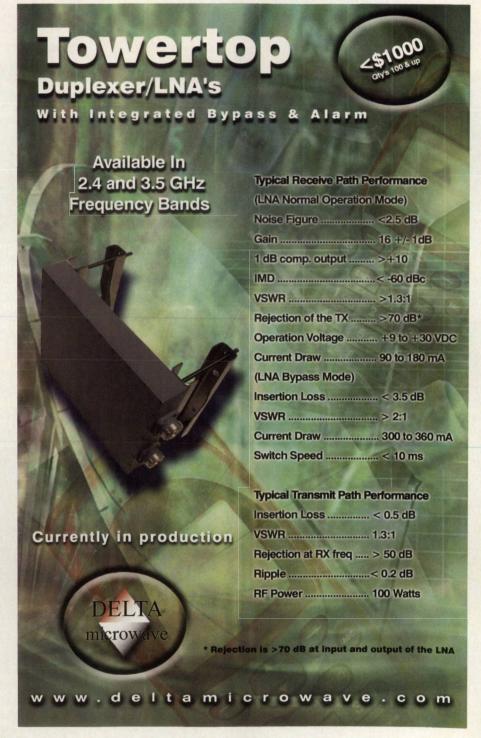
Fig. 6 Normalized collector voltage (a) and current (b) waveforms and (c) current through the load network capacitance for an idealized optimum class E amplifier.

The normalized collector (a) current and (b) voltage waveforms for an idealized optimum parallel-circuit class E operating mode are shown in *Figure 6*. From the collector voltage and current waveforms, it follows that, when the transistor is turned on, there is no voltage across the switch and the current i<sub>c</sub> consisting of the load sinusoidal current and an inductive current flows through the device.

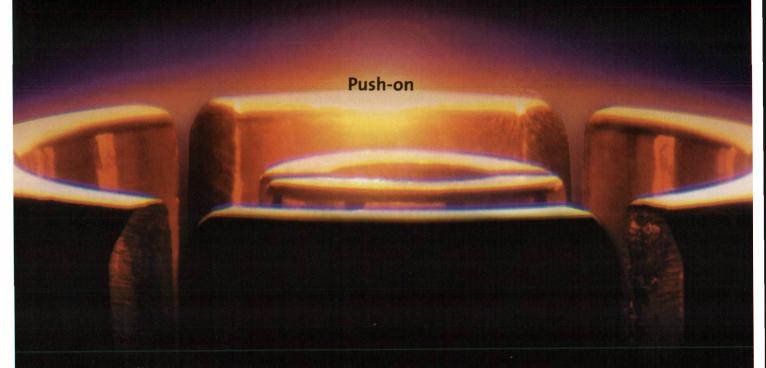
However, when the transistor is turned off, this current now flows through the parallel capacitance C. As a result, there is no nonzero voltage and current simultaneously, which means a lack of power losses and gives an idealized collector efficiency of 100 percent.

The optimum load network parameters can be obtained from<sup>4,7</sup>

[Continued on page 33]



### Changing the world is easier than you might think.



All you need are the right connections. Like GPO™ and GPPO™ designs that give you powerful, reliable performance and reduce your manufacturing complexity. In fact, we know a lot about revolutionizing with GPOs and GPPOs. After all, we invented them. And we continue to offer the broadest array of available designs in the industry—with an incredible frequency range of up to 65 GHz—so we can quickly meet your specific package requirements. With the right connections, who knows how far your design can go? Push-on, with Corning Gilbert.

Visit us online at www.corning.com/corninggilbert to view our standard product catalog of high performance GPOs and GPPOs or call us today at 1-800-651-8869, ext. 400.

Precision. Performance. Push-on.

ISO 9001 Certified

CORNING
Discovering Beyond Imagination

phone:

800 651 8869 ext 400 (U.S. and Canada)

(01) 623 845 5613 (International)

website: e-mail: www.corning.com/corninggilbert pushon-info@corning.com

Click LEADnet at mwjournal.com or Circle 15 on Reader Service Card

### TUTORIAL

$$L = 0.732 \frac{R}{\omega} \tag{17}$$

$$C = \frac{0.685}{\omega R} \tag{18}$$

whereas the optimum load resistance for the specified values of supply voltage  $V_{cc}$  and output power  $P_{out}$ , taking into account that  $R = V_R^2/2P_{out}$ , can be calculated from

$$R = 1.365 \frac{V_{cc}^2}{P_{out}}$$
 (19)

The phase angle between the fundamental frequency voltage and current seen by the switch terminal is equal to

$$\phi = 34.244^{\circ}$$
 (20)

which means that the load network is slightly mistuned with respect to the fundamental frequency and the values of the load network parameters should be chosen to create an inductive reactance at the fundamental frequency and capacitive reactances at the harmonic components.

For high power or low voltage power amplifiers, it is very important to know how small the value of the required load resistance is, since the higher its value, the easier to provide impedance matching to a conventional 50  $\Omega$  load. Thus, for the same output power with the same supply voltage, the ratio between load resistances  $R^{(B)}$  in class B,  $R^{(F)}$  in class F and  $R^{(E)}$  in parallel-circuit class E can be written as<sup>4</sup>

$$R^{(F)} = \frac{4}{\pi} R^{(B)}$$
 (21)

$$R^{(E)} = 2.729R^{(B)} \tag{22}$$

which clearly shows that, for parallelcircuit class E power amplifiers, the design output matching procedure can be significantly simplified. If the calculated value of the resistance R for the optimum parallel-circuit class E power amplifier is too small or differs from the required load resistance R<sub>L</sub> significantly, it is necessary to use an additional matching circuit to provide maximum output power to the load. In this case, the first series element of such matching circuits should be an inductance to provide high impedance conditions for harmonics.

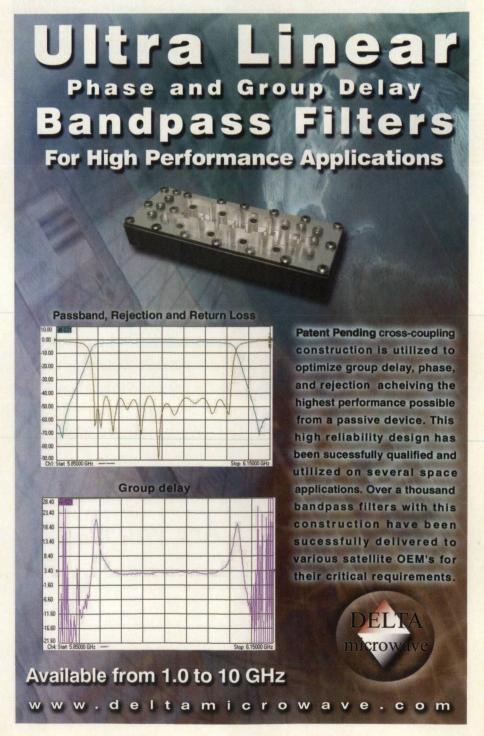
For a microwave power amplifier, usually all the inductances in the output matching circuit should be realized with transmission lines, in order to reduce the power losses. Therefore, for a parallel-circuit class E power amplifier, the parallel inductance L should be replaced by the short-length transmission line  $TL_1$  with the optimum parameters obtained from

$$\tan \theta = 0.732 \frac{R}{Z_0} \tag{23}$$

where

$$\begin{split} Z_0 &= \text{characteristic impedance of the} \\ &\quad \text{transmission line } TL_1 \\ \theta &= \text{electrical length of the} \\ &\quad \text{tramission line } TL_1^8 \end{split}$$

[Continued on page 34]

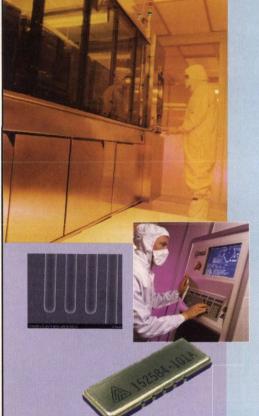


### TUTORIAL

Thus, a parallel circuit, being a very simple electrical structure, in reality represents a powerful means for increasing power amplifier efficiency operation. Therefore, in class B, the load network contains a parallel circuit tuned to the fundamental frequency providing also sufficient harmonic suppression. In class F, to approximate a 100 percent collector

efficiency, one or several parallel circuits tuned at the harmonic components or a quarter-wave transmission line are used as the parallel circuit single-frequency equivalent. In class E, it is enough to use a slightly mistuned parallel circuit having an inductive reactance at the fundamental frequency and capacitive reactances at the harmonic components.

### **SAW Foundry Services**



Our new world-class
SAW manufacturing
facility is fully equipped...

- 4" SAW Wafer Processing
- Quartz, LiNbO<sub>3</sub> or LiTaO<sub>3</sub> substrates
- Die Linewidths down to 0.35 μm
- Single Wafer runs to Volume Production

We're ready to combine top notch customer service with competitive pricing...

Are you ready?



www.saw-devices.com

155 Sheldon Drive Cambridge, Ontario Canada N1R 7H6
T 647-887-SAWS F 519-622-1691
E saws@comdev.ca

#### References

- 1. F.H. Raab, "Class E, Class C and Class F Power Amplifiers Based Upon a Finite Number of Harmonics," *IEEE Transactions on Microwave Theory and Techniques*, Vol. MTT-49, August 2001, pp. 1462–1468.
- H.L. Krauss, C.W. Bostian and F.H. Raab, Solid State Radio Engineering, John Wiley & Sons Inc., New York, NY 1980.
- & Sons Inc., New York, NY 1980.

  3. F.H. Raab, "Class F Power Amplifiers with Maximally Flat Waveforms," *IEEE Transactions on Microwave Theory and Techniques*, Vol. MTT-45, November 1997, pp. 2007–2012.
- A.V. Grebennikov, RF and Microwave Power Amplifiers and Oscillators: Theory and Design, Noble Publishing, 2002.
- A.V. Grebennikov, "Effective Circuit Design Techniques to Increase MOSFET Power Amplifier Efficiency," *Microwave Journal*, Vol. 43, No. 7, July 2000, pp. 64–72.
- F.H. Raab, "Idealized Operation of the Class E Tuned Power Amplifier," *IEEE Transactions on Circuits and Systems*, Vol. CAS-24, December 1977, pp. 725–735.
- A.V. Grebennikov and H. Jaeger, "Class E with Parallel Circuit — A New Challenge for High Efficiency RF and Microwave Power Amplifiers," IEEE MTT-S International Microwave Symposium Digest, 2000.
- A.V. Grebennikov and H. Jaeger, "Transmission-line Tuned Switching Power Amplifier," US patent (pending).



Andrei Grebennikov received his Dipl. Ing. degree in radioelectronics from the Moscow Institute of Physics and Technology, and his PhD degree in radio engineering from the Moscow Technical University of Communications and

Informatics in 1980 and 1991, respectively. He joined the scientific and research department of the Moscow Technical University of Communications and Informatics as a research assistant in 1983. His scientific and research interests include the design and development of power RF and microwave radio transmitters for base station and handset applications, hybrid integrated circuits and MMICs of narrow- and wide-band, low and high power, high efficiency and linear microwave and RF amplifiers, and single-frequency and voltagecontrolled oscillators using any type of bipolar and field-effect transistor. From 1998 to 2001, Grebennikov was a member of the technical staff at the Institute of Microelectronics, Singapore, responsible for the design and development of the LDMOS FET high power amplifier module. Since January 2001, he has been with M/A-COM Eurotec (Cork, Ireland), where he is involved in the design and development of 3G handset InGaP HBT power amplifiers and low noise VCOs.

## 2W & 5W DC to 18GHz ATTENUATORS



Rugged Stainless Steel Construction, High Repeatability, Miniature Size, Low Cost, and Off-The-Shelf Availability are some of the features that make Mini-Circuits "BW" family of precision fixed attenuators stand above the crowd! This extremely broad band DC to 18GHz series is available in 5 watt Type-N and 2&5 watt SMA coaxial designs, each containing 15 models with nominal attenuation values from 1 to 40dB. Built tough to handle 125 watts maximum peak power, these high performance attenuators exhibit excellent temperature stability, 1.15:1 VSWR typical, and cover a wealth of applications. So contact Mini-Circuits today, and capture this next generation of performance and value!

Mini-Circuits...we're redefining what VALUE is all about!

2W SMA		5W SMA	5W Type-N	Attenuation (dB)		
	\$29.95	\$44.95	\$54.95	Nominal	Accuracy*	
	S1W2	S1W5	N1W5	1	±0.40	
	S2W2	S2W5	N2W5	2	±0.40	
	S3W2	S3W5	N3W5	3	±0.40	
	S4W2	S4W5	N4W5	4	±0.40	
	S5W2	S5W5	N5W5	5	±0.40	
	S6W2	S6W5	N6W5	6	±0.40	
	S7W2	S7W5	N7W5	7	±0.60	
	S8W2	S8W5	N8W5	8	±0.60	
	S9W2	S9W5	N9W5	9	±0.60	
	S10W2	S10W5	N10W5	10	±0.60	
	S12W2	S12W5	N12W5	12	±0.60	
	S15W2	S15W5	N15W5	15	±0.60	
	S20W2	S20W5	N20W5	20	±0.60	
	S30W2	S30W5	N30W5	30	±0.85	
	S40W2	S40W5	N40W5	40	±0.85	

At 25°C includes power and frequency variations up to 12.4GHz.
 Above 12.4GHz add 0.5dB typ. to accuracy.

DC-18GHz Adapters NOW AVAILABLE!

SMA-F to SMA-M \$895 ea.(1-49)





For detailed adapter specs visit: www.minicircuits.com/adapter.html





CIRCLE READER SERVICE CARD

P.O. Box 350166, Brooklyn, New York 11235-0003 (718) 934-4500 Fax (718) 332-4661 For quick access to product information see MINI-CIRCUITS CATALOG & WEB SITE

The Design Engineers Search Engine Provides ACTUAL Data Instantly From MINI-CIRCUITS At: www.minicircuits.com



### High Performance EM Simulation and Optimization and Electronic Design Automation

Zeland Software has been recognized as a leading developer to provide unparalleled high-frequency electromagnetic simulation and design tools for microwave, semiconductor, wireless, and telecom industries, government laboratories, and universities around the world.

Applications of Zeland's Software include MMICs, RF ICs, LTCC circuits, 3D IC interconnects and packages, high-speed digital circuits, multilayer PCBs, MCMs, HTS circuits and filters, microstrip antennas, wire antennas, conical and cylindrical helix antennas, inverted-F antennas, antennas on finite ground planes, other RF antennas, waveguides, EMC/EMI, biomedical effects of electromagnetic waves, and many more.

We are committed to satisfying our customers with high performance software and quality technical support. We love to discuss design challenges with customers and provide our input. We welcome any feedbacks or tough EM simulation and design problems from customers.

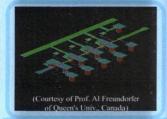
### IE3D

### **PRODUCTS**

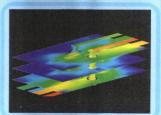
Planar and 3D Electromagnetic Simulation and Optimization Package



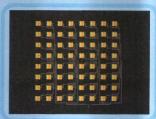
A Spiral Inductor with Thickness on a Semiconductor Substrate



IE3D Simulation of an Entire Low-Noise Amplifier



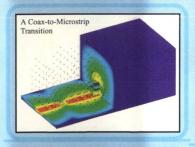
A Multilayer PCB with Vias in High-Speed Circuits

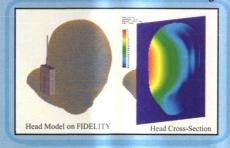


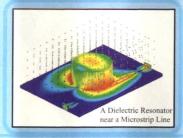
An 8-by-8 Patch Antenna

### FIDELITY

Full 3D Finite-Difference Time-Domain Electromagnetic Simulator

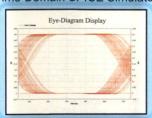






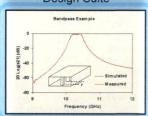
### MDSPICE

Mixed Frequency- and Time-Domain SPICE Simulator



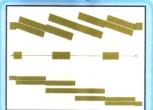
#### COCAFIL

Waveguide Coupled Cavity Filter
Design Suite



### **FILTERSYN**

Planar Filter Synthesis Package



#### LINEGAUGE

Transmission Line
Design Tool



Zeland Software, Inc. is also the North American exclusive representative of AC Microwace GmbH for its high-frequency circuit simulator, LINMIC.

### ZELAND SOFTWARE, INC.

39120 Argonaut Way, PMB 499, Fremont, CA 94538, U.S.A., Tel: 510-623-7162 Fax: 510-623-7135 E-mail: zeland@zeland.com

Web Site: http://www.zeland.com

Click LEADnet at mwjournal.com or Circle 103 on Reader Service Card



#### **NEWS FROM WASHINGTON**

# Raytheon Delivers First Production Evolved SEASPARROW to US Navy

Raytheon Co. delivered the first production Evolved SEASPARROW Missile (ESSM) to the US Navy, defining the future of ship defense. "ESSM provides improved ship selfdefense capabilities against faster, lower, smaller and more maneuverable antiship missile threats as well

as increased firepower," said Capt. Ken Graber, the

NATO SEASPARROW project manager.

ESSM is an international cooperative upgrade of the RIM-7 NATO SEASPARROW Missile. SEASPARROW is already the most widely deployed ship-defense missile system in the world. The new missile will provide the primary air defense for the capital ships of the 10 participating NATO navies. Discussions are under way to outfit the ships of at least six other navies as well. The program is managed by the NATO SEASPARROW Consortium, a 32-year-old organization described as "NATO's largest and most successful cooperative weapons project." Raytheon's Missile Systems business unit in Tucson, AZ, is leading the team of 18 companies from 10 countries in developing and producing this next generation SEASPARROW ship self-defense system. The other nations participating in ESSM's development include Australia, Canada, Denmark, Germany, Greece, the Netherlands, Norway, Spain and Turkey. ESSM has the speed, agility and accuracy to engage threats to the launching vessel at maximum range and in the most challenging of conditions. The final phase of the missile's flight test program is scheduled for the early spring of 2003 when performance with the AEGIS Fire Control System of the US Navy's Arleigh Burke class of guided missile destroyers will be verified.

Airborne
Surveillance System
Keeps Security
Forces Safe

Air Force Security
Forces personnel supporting Operation Enduring Freedom have been
equipped with the latest in
Unmanned Aerial Vehicle
(UAV) technology, the
Force Protection Airborne
Surveillance System
(FPASS). The system allows security forces to see

beyond base perimeters and can provide a rapid visual assessment of detected threats.

The Electronic Systems Center's Force Protection System Program Office recently completed delivery of the initial Force Protection Airborne Surveillance System to deployed security forces personnel supporting Operation Enduring Freedom. "This system adds an enhanced layer of protection for bases around the world by allowing forces personnel to see beyond base perimeters," said Colonel Howard Borst, director, Force Protection System Program Office.

Each system consists of a ground station — computer, displays, recorder and communication equipment; six UAVs; a remote imagery viewing terminal; interchangeable payloads of color cameras and thermal imagers for day and night time imagery; in addition to transportation cases and launch equipment. "The system is not intended to be 'backpackable' but it is easily transported by a general purpose vehicle," said Major John Crennan, Delay Denial Systems Division Chief. The UAV, dubbed "Desert Hawk" by Lt. General T. Michael Moseley, commander, 9th Air Force and US Central Command Air Forces, is small in size, light weight and very simple to operate. The airframe is manufactured from damage resistant molded material that is designed for limited field repair. Desert Hawk is able to operate from a  $100 \times 100$  m clearing without a runway. "FPASS was specifically designed to be used by cops," said Major Mike Giger, FPASS program manager. "It extends the range that security forces can monitor without putting troops into harms way," he said. "This system is not intended to replace troops, it is a critical surveillance tool that will protect and save lives by providing essential real time information on potential threats," said Borst. A two-man crew operates the system. To launch the UAV, operators use a bungee cord catapult. The system is powered by rechargeable batteries that have a one-hour life span or if available, can also be operated by using commercial AC power. The UAV is designed to fly primarily at altitudes of 300-500 feet and sends back to the operators' real time overhead video data.

Space System/Loral
Selected for Navy's
Communication
System

oral Space and Communications announced that the US Navy's Space and Naval Warfare Systems Command (SPAWAR) has awarded a Space Systems/Loral (SS/L) team, led by Raytheon, a \$40 M Component Advanced Development (CAD) contract to develop the US Navy's \$6

B, next-generation, satellite-based mobile communications system, the Mobile User Objective System (MUOS).

CAD is a 14-month effort aimed at reducing risk and advancing system design concepts that stem from MUOS' recently completed 1999-to-2002 Concept Exploration Phase (CEP). SPAWAR tapped the Raytheon-SS/L team for CAD based on the team performance during the earlier CEP program. The latest award reflects SPAWAR's selection of two teams, which will work in parallel until 2004, when one team will be selected to lead future MUOS efforts.

SS/L is part of a Raytheon-led team that also includes TRW Astro Aerospace and Honeywell. The two teams have been funded by SPAWAR to compete for a system design and development contract to be awarded in January 2004, for construction of the first MUOS satellite, which will be launched in 2008. Subsequently, the MUOS Program Production and Deployment contract will be



#### **NEWS FROM WASHINGTON**

awarded in mid-2006 and continue through 2023. As part of the newly awarded development program, SS/L will be adapting its highly successful commercial 1300 spacecraft platform for the MUOS narrowband tactical communications System.

"The combination of SS/L's heritage satellite bus with the payload technology and expertise of our team members provides our government with cost-effective improvements in its satellite communications Systems," said C. Patrick DeWitt, president of SS/L. "MUOS will ensure its users an uninterrupted communication link, without concern for the location, weather or local geography."

MUOS will be a narrow band satellite communication (SATCOM) system that supports a worldwide, multi-service/multi-national population of mobile and fixed-site war fighter terminals. Its capabilities will provide a considerable increase in throughput over the current Ultra High Frequency (UHF) Follow-on (UFO) narrow band satellite communications system. It will also provide greater flexibility through improved link performance for users such as Navy Seals and other special forces to operate in difficult environments. SS/L MUOS design is based on the company's space-proven 1300 geostationary satellite platform, which has an excellent record of reliable operation and is highly adaptable to a wide variety of payloads. Over the past 45 years, SS/L satellites have amassed well over 900 years of on-orbit services.

BAE Systems
Demonstrate
Guided Rocket

BAE Systems successfully launched a 2.75" laser guided rocket using a unique mid-body, finmounted, guidance system, scoring a "bull's-eye" hit on a small target more than three miles away from its launch point. The control test vehicle (CTV) was fired Sept. 29 at the Army's

Yuma Proving Ground in Arizona for the Army's low cost

precision kill (LCPK) program.

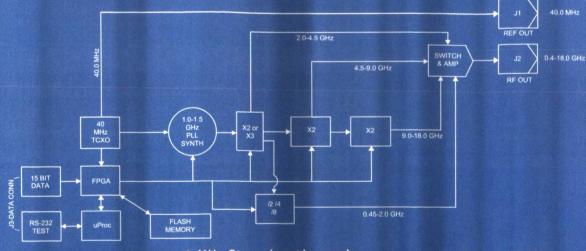
During the rocket's flight, the CTV completed a series of preprogrammed flight maneuvers, demonstrating real-time aerodynamic control by the autopilot and inertial sensor. The test vehicle was launched with a fully integrated guidance and control system and semi-active laser seeker to evaluate subsystem performance in flight. The shot followed extensive hardware in the loop testing at the Army's Missile Research and Development Engineering Center facility, Huntsville, AL. The LCPK program is an advanced technology development program to develop prototype laser-based 2.75" guidance sections. BAE Systems Information and Electronic Warfare Systems, Nashua, NH, is working under a \$5 M contract to design and develop the guided rocket.



complete package.



Microwave Synthesizer (0.4-18.0 GHz)



- 1 MHz Steps (continuous)
- RS-232 Test Feature
- Clock multiplied
- < 10 Watts</p>
- Hermetically sealed enclosure
- Power ≈ +10dBm
- Parallel load control
- Internal TCXO
- Tuning speed < 75 microseconds</p>
- 9.25"x 7.65"x 1.3"

SALISBURY ENGINEERING, INC.



38166 Old Stage Rd. P.O. Box 480, Delmar, DE 19940-0480 302 846 27**50 • fa**x 302 846 3888 Email: Sales@Salisbury-Engineering.com

800 **9**89 2141

www.salisbury-engineering.com

Click LEADnet at mwjournal.com or Circle 83 on Reader Service Card



#### FIXED ATTENUATORS

#### **Broadband**

- Up to 26.5 GHz
- 2 Watts average power
- SMA, 2.9mm, & N (to 18 GHz) connectors

#### General Purpose

- Up to 6 GHz
- SMA, N, TNC, 7/16, & BNC connectors
- Most available from stock

Emerging Wave in C

in Component

Model 351-013-010

DC-18 GHz, 10 dB, SMA

1-9 pieces \$28.50 each

All standard dB values available
at this price! (3, 6, 10, 820 dB)

2900 Graham Road, Suite B Franklin, IN 46131

www.BroadWaveTech.com

tel: 317.346.6101 fax: 317.346.6995

sales@BroadWaveTech.com

Click LEADnet at mwjournal.com or Circle 10 on Reader Service Card



## BAE Systems C41SR Delivers First Skynet 5 Terminals

K contractor BAE Systems Command, Control, Communications, Computing, Intelligence, Surveillance and Reconnaissance (C4ISR) has delivered the first batch of six Talon satellite communications terminals to Paradigm Secure Communications for eventual use in the

UK's Skynet 5 military communications satellite system. In all, 15 such terminals will be acquired, with second and third tranches being scheduled for delivery during December 2002 and August 2003, respectively. Skynet 5 (scheduled for introduction by 2010) is being procured via the UK's Private Finance Initiative and will see (as a beginning) the transfer of the existing Skynet 4 from UK Ministry of Defence control to that of Paradigm. This transfer is scheduled to take place during mid-2003.

BAE Systems C4ISR describes Talon as being a lightweight, deployable terminal that is man-portable, makes use of carbon fibre in its construction and can be configured to operate in the C- (4 to 8 GHz), X- (8 to 12.5 GHz), Ku- (12.5 to 18 GHz) and Ka- (26.5 to 40 GHz) bands. Here, the necessary changes are described as being simple and involving the introduction of frequency specific feed arms and some key electronic components. Talon is further noted as being fitted with either a 1.2, 1.9 or 2.4 m antenna dish, with an X-band 1.9 m configuration noted as being able to deliver a G/T value of better than 21 dB/k. The standard terminal includes all the functionality needed to support the required communications link (including antenna control and tracking, frequency conversion and the requisite modem functions) and is packed in four modular cases that can include heaters and cooling elements as required. Again using the 1.9 m dish configuration as an example, the equipment can be set-up in wind speeds of up to 15 m/s, can be operated in winds of up to 16 m/s and will survive gusts of up to 27 m/s.

# Sensitive Gamma Ray Observatory Ever Built

Billed as the most sensitive gamma ray observatory ever built, the European Space Agency's (ESA) INTErnational Gamma-Ray Astrophysics Laboratory (INTEGRAL) was launched into an eccentric, 72-hour, 9000 to 155,000 km orbit around the Earth on 17 October 2002. De-

signed to provide new insights into celestial objects such as black holes, neutron stars, active galactic nuclei and supernovae, the 2 tonne INTEGRAL vehicle is equipped with a payload that includes a spectrometer (known as the SPectrometer on INTEGRAL — SPI), an imager (the Imager on Board the INTEGRAL Satellite — IBIS), an X-Ray monitor (the Joint European X-ray Monitor —

#### INTERNATIONAL REPORT

Martin Streetly, International Correspondent

JEM-X), an Optical Monitoring Camera (OMC) and an Integral Radiation Environment Monitor (IREM).

Of these, the SPI is designed to perform spectral analysis of gamma-ray point sources and extended regions in the 20 keV to 8 MeV energy range, with a resolution of 2.2 keV at 1.33 MeV. As such, the SPI device incorporates an array of 19 hexagonal, high purity, germanium detectors that are cooled to an operating temperature of 85 K by a Stirling engine. A hexagonal coded aperture mask is located 1.7 m above the detection plane in order to image a 16° section of the sky with 2° angular resolution. In order to reduce background radiation, the detector assembly is shielded by an anti-coincidence system that includes limiting the aperture to approximately 30° and the provision of a plastic veto below the mask to further reduce the 511 keV background. For its part, the IBIS provides fine imaging, source identification and spectral sensitivity to both continuum and broad lines over the 15 keV to 10 MeV energy range. Within the device, a tungsten codedaperture mask is located 3.2 m above its detection plane and is optimised for high angular resolution. The IBIS detector uses two planes, namely a 2600 cm2 front layer (made up of  $4 \times 4 \times 2$  mm pixels) and a 3100 cm<sup>2</sup> back layer  $(9 \times 9 \times 30 \text{ mm pixels})$  that are 90 mm apart. The use of a two-layer detector allows photon paths to be tracked in 3-D as they scatter and interact with more than one element of the array. Events can be categorised and the device's signal-to-noise ratio is improved by rejecting those responses (usually towards the high end of the energy range) that are unlikely to correspond to real celestial photons. The IBIS aperture is restricted by a lead shielding tube and is shielded in all other directions by an active scintillation veto system.

The JEM-X X-ray monitor supplements the SPI and IBIS instruments and is used to detect and identify gamma-ray sources and in the analysis and interpretation of acquired gamma-ray data. Accordingly, JEM-X takes readings simultaneously with those of the SPI and IBIS devices and provides imagery with arcminute angular resolutions within the 3 to 35 keV prime energy band. Its baseline photon detection system consists of two identical high pressure imaging microstrip gas chambers (1.5 bar pressure and made up of 90 percent xenon and 10 percent methane), at a nominal gas gain of 1500. Each detector views the sky through a codedaperture mask that is located approximately 3.2 m above

aperture mask that is located approximately 3.2 m above the detection plane.

JEM-X itself is supported by the OMC which is used to observe optical emissions from INTEGRAL's prime targets at the same time as those targets are being ob-

served by the SPI, IBIS and JEM-X. The remaining instrument — the IREM — is described as performing a wide range of in-orbit radiation monitoring functions and downloading the acquired data via the INTEGRAL vehicle's telemetry system. Overall, the satellite's orbit is designed in such a way as to keep it at an altitude of 40,000 km or above for as long as possible in order to minimise

km or above for as long as possible in order to minimise background radiation effects from the Earth's own radiation belts. INTEGRAL's unit cost is put at ¤ 330 million in

year 2000 values.



## Philips Launches TPMS Chip Solution

#### INTERNATIONAL REPORT

n order to meet upcoming US 2004 legislation and a wider perceived global market, Netherlands contractor Royal Philips Electronics has launched a chip-based Tire Pressure Monitoring System (TPMS) that provides the automobile driver with measurements of individual tire pressures and no-

tification of pressure/inflation problems as they arise. TPMS applications have major safety and cost implications in terms of tire-related accidents, levels of tire wear and fuel consumption values. Goodyear calculates that at any given time, one in five vehicular tires is under-inflated by as much as 40 percent. Such irregularities lead to significant alterations in road-holding and braking characteristics, a significant shortening of tire life and an increase in fuel consumption of roughly one percent for every three pounds/in² of under-inflation.

The Philips TPMS uses a direct monitoring approach and takes the form of a Tire Module (TM) that broadcasts RF data to a central receiver. Each TM typically comprises an analogue piezo-resistive pressure sensor, a pressure sensor signal conditioning chip and an RF transmitter unit. As applied to the tire, the TM has to withstand a

temperature range of from as low as -40° to as high as +150°C and acceleration rates of up to 2000 G. Functionally, the signal from the pressure sensor is amplified and digitised and the full device calibrated and initialised. A P2SC signal processing chip picks up the signal from a sensor bridge, digitises it, measures chip temperature and performs all the required calibration and initialisation. The P2SC chip includes a field proven Reduced Instruction Set Computer (RISC) microcontroller core, minimum power consumption and a wheel identification feature to solve issues of auto-rotation.

After calibration and initialisation, each tire sends its pressure data to the automobile's dashboard and a controller recognises which tire the signal is coming from. A low frequency wake-up approach has been used for tire location and is described as providing immediate and reliable identification. Small, 125 kHz wheel arch antennas are used to send the wake-up signal to the specific TM, which responds via the RF link. Each tire is woken up each time the ignition is switched on. Thereafter, tire pressure is checked at regular intervals and in the event of a sudden pressure drop, a warning is relayed to the driver without the need to wake the system up. Looking to the future, Philips notes that Bluetooth<sup>TM</sup> technology could have a TPMS application, as could inductive coupling on passive GHz technologies to overcome the need for internal batteries.

#### Test Cable Assemblies DC to 18GHz



Low cost, high quality, flexible test and interconnect cable assemblies now in stock

ASK ABOUT OUR NEXT DAY DELIVERY SERVICE\*

Low loss, triple screen construction, Phase stable, SMA plug to SMA plug, N plug to N plug, 7mm to 7mm Standard lengths: 0.5, 1.0, 1.5 and 2.0 Metres. \*subject to availability.



#### **MIDWEST MICROWAVE**

**UK and Europe** 

Tel: +44(0) 1245 359515 Fax:+ 44(0) 1245 358938 e: sales@midwest-microwave.ltd.uk www.midwest-microwave.ltd.uk **United States** 

Tel: 00 1 734 429 4773 Fax: 00 1 734 429 1415 e: sales@midwest-microwave.com www.midwest-microwave.com

Manufacturers of custom RF cable assemblies (semi rigid and flexible), delay lines and passive microwave components

#### Super Fast Very High Isolation

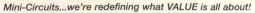
# SVITCHES



SPDT, DC-4.5GHz From ea. (10,000)

Very high isolation up to 65dB at 1GHz typical. Integral TTL driver with blazing fast 10nsec switching speed. The ability to withstand severe operating temperatures ranging from -40°C to +85°C. That's what's great about Mini-Circuits wideband DC to 4.5GHz SPDT switches. But that's not all! Reflective and

absorptive configurations come in two different low profile plastic packages to suit your design layout requirements; the 3x3mm MCLP™ package with exposed metal bottom for excellent grounding and heat dissipation, and the industry standard SOIC-8. No matter which model you choose, you'll get strong performance and rugged reliability at a price that crushes the competition. Just check the specs, then contact Mini-Circuits today for our fast response!





	Model	Freq. (GHz)	In-Out Isol. dB(typ)	Ins. Loss dB(typ)	1dB Comp. dBm(typ)	Price \$ea. (Qty. 10)		
	M3SW-2-50DR M3SWA-2-50DR	DC-4.5 DC-4.5	60 65	0.7 0.7	25 25	4.95 <b>*</b> 4.95 <b>*</b>		
	SWM-2-50DR SWMA-2-50DR	DC-4.5 DC-4.5	55 65	0.7 0.7	25 25	5.30 5.30		
Ī	Supply voltage +5V, -5V. TTL control. Switching time 10nsec (typ).							

Reflective Absorptive



Detailed Performance Data & Specs Online at: www.minicircuits.com/switch.html







CIRCLE READER SERVICE CARD

P.O. Box 350166, Brooklyn, New York 11235-0003 (718) 934-4500 Fax (718) 332-4661 For quick access to product information see MINI-CIRCUITS CATALOG & WEB SITE The Design Engineers Search Engine Provides ACTUAL Data Instantly From MINI-CIRCUITS At: www.minicircuits.com

# Kicking The Competition's Tail For 200 Watt Testing.



#### The 200S1G4

The world's only 200-watt, 0.8 to 4.2 GHz, all-solid-state amplifier. Exceptional linearity. Unequaled harmonic performance. 100% mismatch tolerant. Unbeatable technology and design. An advanced instrument for 200-watt testing, this is the amplifier of choice for EMC and linear wireless applications, with digital front panel displays and AR's famous three-year warranty. And remember, every AR product and system is backed by our world class "Mark of Performance." Look for the 200TS1G4 and our new 240-watt, .8 to 3 GHz 240S1G3 at www.amplifiers.com/microwave.asp.

Check Out Our New Site With New Features!



Copyright@ 2002 Amplifier Research. The orange stripe on AR products is Reg. U.S. Pat. & Tm. Off.



The Force Behind The Field.



#### THE COMMERCIAL MARKET

#### **Bluetooth to Ramp** Up in Market **Outside of Mobile** Handsets

hile mobile handsets are expected to account for approximately two-thirds of the Bluetooth devices that will ship in 2002, and cordless headsets will also be a growing category, Allied Business Intelligence's (ABI) new Bluetooth report notes that there are significant oppor-

tunities for Bluetooth semiconductor vendors in other

markets, especially computing.

ABI projects that computing devices will account for 21 percent of all Bluetooth-enabled devices that will ship in 2003, with a 27 percent share by 2007. The coming wave of Bluetooth cordless input devices including mice and keyboards will be an important factor in driving PC OEMs to embed Bluetooth functionality. Cordless computing peripherals have shown tremendous growth in recent years and Bluetooth will increasingly displace IrDA and proprietary RF technologies as Bluetooth chipsets continue to drive down the cost curve and exhibit improved power efficiency.

The Wireless Home **Network: Room for Multiple** Wireless Technologies?

According to a report by In-Stat/MDR, over the last three years, a very rapid wireless evolution has occurred in the home. In 1999 and 2000, the guestion was whether HomeRF or 802.11 would win in the home. In 2001, the main issue was whether 802.11a (5 GHz Wi-Fi) or 802.11g

(2.4 GHz Wi-Fi, higher speed version of 802.11b) would be the technology of choice for the connected home of the future. In 2002, the wireless home landscape has broadened, with a handful of solid wireless technologies showing significant potential for specific applications in the home.

The vision of wireless home networking in the future involves the PC cluster of devices (broadband modem, router/AP device, desktops, laptops, PDAs, Web tablets) becoming wirelessly connected to the entertainment cluster of devices, i.e. audio and visual equipment such as TVs, DVD players, MP3 players, gaming devices and home theater devices such as high end displays and DVRs. Another step in networking the home is home automation, i.e. being able to monitor temperature, security and white goods from a central location. Promising home wireless technologies include Wi-Fi, UWB (Ultra-Wideband), Zigbee (the core technology behind IEEE 802.15.4), wireless 1394, and mesh networking technology.

For the purpose of rapid data transmission across LANs, IEEE 802.11b has gained the hearts and minds of many residential end-users. 802.11b, now in its third year of market shipments, has wowed the home market, pushing HomeRF squarely out of the picture. Low end networking vendors were quick to enter the 802.11b market, bringing with their efforts the two most important features of a home networking technology: (1) low cost and (2) easy configuration. Although the easy configuration feature may be arguable in some cases, most of the low end networking equipment vendors are in their second or third generation of 802.11b products and, after being blasted in many user reviews for configuration difficulties, have improved on their software significantly. Also, now Microsoft, the software giant himself, has entered the home 802.11b hardware fray, citing its user-friendly software configuration layer as its main differentiator.

For the latest coverage of the dynamic home networking market from In-Stat/MDR, check out: http://www.

instat.com/catalog/Neatalog.asp?id=99.

**MEMS Offer** a Possible Silver Lining for Semiconductor **Equipment Suppliers** 

iven the down turn in the semiconductor equipment market, suppliers are now focusing more intently on the compelling opportunity MEMS fabrication is presenting, according to In-Stat/MDR. There are some 60 MEMS fab/foundries, several hundred start-ups (many of

which have their own in-house prototyping and/or fabrication facilities), as well as countless universities and government labs worldwide researching MEMS technology. The high tech market research firm reports that continued unit growth and device diversity, as well as this large potential customer base, is making the MEMS sector a progressively more attractive market for semiconductor equipment manufacturers.

"Equipment for MEMS fabrication is now more available than ever before, ranging from dual purpose (for both semiconductor and MEMS processing steps) to purely MEMS-specific," says Marlene Bourne, a senior

analyst with In-Stat/MDR.

One of the biggest competitive factors in the MEMS fabrication equipment market will come from the suppliers themselves — in the form of used equipment. While many start-ups may have funds to install in-house facilities, they often purchase used, rather than new, equipment. As a result, equipment suppliers are finding themselves buying their own old equipment to re-sell it to this particular market sector.

More semiconductor equipment manufacturers are involved in MEMS-specific equipment than would be expected. Several of the top suppliers now have divisions focused solely on MEMS solutions, and no doubt more will emerge in time. There are even several start-ups who have developed and are offering equipment specifically for the MEMS market. Toolsets range from those for deposition, lithography and etching, to wafer bonders, dryers and other equipment.

#### CTT Microwave Subassemblies

- ✓ Frequency Coverage from 0.5 to 40 GHz
- ✓ Subsystem Integration to 26 GHz
- ✓ Proprietary Component Library
- ✓ MIC Thin-Film Based Design for High Reliability
- Military & Commercial Expertise

CTT integrated subassemblies are designed for flexibility to ensure ease of manufacturing by utilizing thin-film circuits that incorporate the latest in GaAs FET device technology.

These amplifier-driven assemblies are designed for use in applications including broadband EW systems, as well as high power, high dynamic range radar systems in addition to high reliability, cost-effective, commercial

communication systems and MW radios.

CTT subsystems may include the integration of detectors, couplers/power dividers, attenuators, limiters, switches, filters, mixers, LNAs, amplifier gain blocks, power amplifiers, oscillators, and equalizers.

CTT has the in-house design and manufacturing capabilities, skills and experience in performing the integration of subsystems in a timely and cost-effective manner.

Our goal is to be the number one supplier of microwave amplifiers and subassemblies in the marketplace.

Give us a call today and find out how our products

and service can support your success.

3005 Democracy Way, Santa Clara, CA 95054, Phone: 408-988-8521, Fax: 408-986-9097, E-mail: sales@cttinc.com

Click LEADnet at mwjournal.com or Circle 17 on Reader Service Card





### THE COMMERCIAL MARKET

Cellular
Infrastructure
Manufacturers
to Face Tough
18 Months

The total worldwide count of analog, CDMA, TDMA, GSM, PDC, PHS and UMT base stations will grow at a compound annual growth rate (CAGR) of a mere 13.7 percent through 2006, according to In-Stat/MDR. The high tech market research firm finds that, dur-

ing this same period, UMTS will lead the growth with 110 percent, with CDMA and GSM expected to come in at a not so very close second and third. All other air links will

experience either flat or negative growth.

According to Ray Jodoin, director of In-Stat/MDR's wireless research group, "Over the next 18 months, there might be significant short term delays due to equipment shortages and problems, as well as a significant lack of funding. In addition, a considerable infrastructure manufacturer retrenchment will also occur, and could lead to additional delays because of the necessity to renegotiate contracts." In Stat/MDR also reports that, one year from now, a minimum of two infrastructure manufacturers, in each major market, will no longer be in business and that significant carrier consolidation will also occur during this period. "While the forecast indicates year-to-year growth, 2002 and 2003 should be viewed as extremely volatile," says Jodoin. "If the carrier CAPEX continues to slip, 2002 and 2003 new base station deployment will be down considerably from initial forecasts."

#### In-Stat/MDR has also found that:

• In 2006, there will be only two major air links deployed on a worldwide basis; CDMA at 20.8 percent share of the market (SOM) and GSM at 69.2 percent SOM. UMTS will have only a 4 percent SOM at that time.

• GSM will dominate with almost 94 percent of deployed European base stations in 2006. However, previous rapid growth is beginning to ebb as subscriber growth

diminishes.

• Base station developments in the US will experience a dramatic decline in 2003 as a result of not only the new order downturn that occurred in 2002, but also an anticipated delay in the change over from TDMA to GSM. While activity will occur throughout 2003, systems will not be operational until early 2004.

• Unlike North America, Latin America is expected to continue to depend heavily upon analog and TDMA through 2006. Unless there is a radical transitioning of TDMA to GSM-850, CDMA will be the primary air link

at the end of the forecast period in Latin America.

• While PDC will still dominate the Japanese landscape in 2006, NTT DoCoMo and J-Phone will be making rapid market advances with UMTS. Based on current plans, all CDMA deployments will be upgraded to at least 1xEV-DO in order to offer direct competition to UMTS data speeds. ■









Our Commitment...
The Perfect Relationship



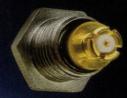


We supply a broad range of SMP products for cable assemblies, press-fit, screw-in, float mount, flange, hermetic and shroud types. If your interconnect applications require a modified SMP (0.135 dia.) or smaller connectors, DYNAWAVE offers SMP hybrid design options and a mature line of SSDP (0.095 dia.) and DSSS (0.085 dia.) products.

Put your requirements in a trusted relationship today!

Dynawave designs, develops & manufactures RF & microwave interconnect solutions. Our product diversity includes connectors, attenuators, adapters, delay lines, harnesses and low cost test & system cable assemblies.

135 Ward Hill Avenue PO Box 8224 Haverhill, MA 01835 978.469.0555 Fax: 978.521.4589 www.dynawave.com





#### **INDUSTRY NEWS**

- Endwave Corp. has acquired certain wireless infrastructure assets of Signal Technology Corp.'s Wireless Group. The acquisition includes customer contracts, equipment, inventory, product designs and other intellectual property, and key personnel needed for the ongoing operation of the business unit. The purchase is expected to enhance Endwave's focus on the commercial wireless infrastructure market.
- Sirenza Microdevices has completed the acquisition of Xemod, a designer and supplier of RF amplifier modules for the wireless communication market. Xemod technology extends Sirenza's power component product line to significantly higher power levels and operating voltages for wireless network equipment applications.
- M-tron Industries Inc. has reached an agreement in principle to acquire the assets of Champion Technologies Inc., a manufacturer of crystals and crystal oscillators, from US Bank. The financial details of the agreement were not disclosed.
- Inc. have signed a definitive agreement to merge the two companies. The new company will retain the Superconductor Technologies name, and will combine the talent, technologies and assets of the two companies. In addition the companies have secured firm commitments through existing shareholders and affiliated entities for a \$15 M investment through a private placement in the combined company, contingent upon the close of the merger.
- Yokogawa Corp. of America has acquired all of the outstanding shares of stock of Measurementation Inc. from its affiliated holding company, Yokogawa USA Inc. The Yokogawa Group began a relationship with Measurementation in 1997 by purchasing an interest in the analytical systems integrator. Measurementation will operate as a separate division of Yokogawa Corp. of America.
- Amphenol Corp.'s Industrial Operations Division has completed the acquisition of the RADSOK® business unit of K&K Stamping. RADSOK technology allows higher amperages to be used in electrical connectors with lower insertion forces, which helps to alleviate millivolt drop and associated temperature rise.
- Sensors Unlimited will purchase certain assets and accept certain liabilities from Finisar Corp.'s Sensors Unlimited subsidiary for \$6.1 M in cash. The new company will assume the name Sensors Unlimited and the existing management team and employees will remain in place.
- Anaren Microwave has opened an all-new facility in the Suzhou Industrial Park in Suzhou, China, near Shanghai. Called Anaren Communciations Suzhou Co. Ltd., the operation will be staffed by both local talent and personnel relocating from the company's headquarters in

#### AROUND THE CIRCUIT

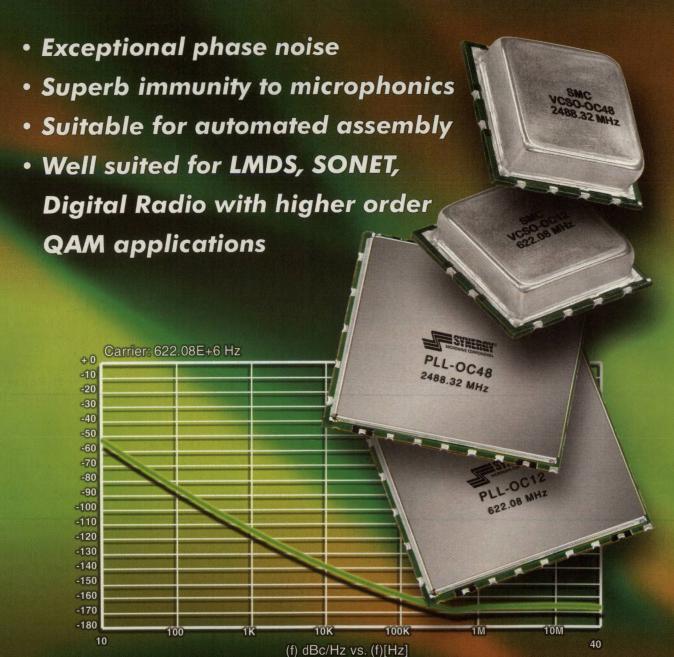
East Syracuse, NY. In related news, the company's recently acquired Almelo, Netherlands-based subsidiary **Anaren Europe BV** (formerly 5m Co.) has returned to full-scale operation following a fire in July of 2001. The completely renovated plant features nearly \$8 M in leading-edge circuit board production equipment.

- Mimix Broadband Inc. has relocated its corporate headquarters to a new facility in Houston, TX, where it will continue to operate an ISO 9001 certified manufacturing, assembly, test and management facility. The 15,000-square foot facility includes a newly constructed Clean Room used for wafer probe testing of MMICs, die attaching and wire bonding.
- **EXEL Microwave Inc.**, a subsidiary of the **Dover Corp.**, has opened a production facility in Nanjing, China. The facility is located in the Nanjing Economic & Technological Development Zone, one of China's major high technology industrial parks. The location allows for rapid movement of products to all parts of China.
- Lamina Ceramics has opened a state-of-the-art manufacturing facility in Westampton, NJ, to increase production of components, modules, circuit boards and packages utilizing the company's proprietary LTCC-M technology. The 50,000-square foot facility will initially include two production lines.
- Chipcon Group AS has opened a fully-owned subsidiary, Chipcon Inc., in Cupertino, CA. The primary goal of Chipcon Inc. is to expand the presence of the Chipcon Group in the US and to intensify the sales and marketing of Chipcon products in North America.
- agreed to enter into a strategic relationship for silicon manufacturing and development. Under the agreement, RF Micro Devices will obtain a guaranteed, lower cost source of supply for wafers fabricated utilizing Jazz Semiconductor's manufacturing processes, including SiGe, BiCMOS and RF CMOS. In related news, RF Micro Devices has begun high volume production shipments of two power amplifiers and a triple-band LNA/mixer to **Sanyo** for use in the new Sanyo SCP-4900 CDMA 2000 1X handset. Shipments began in the June quarter and have reached a multi-million dollar level.
- **Dow-Key Microwave**, a subsidiary of the **Dover Corp.**, has entered into a strategic marketing and distribution alliance with **Teravicta Technologies** to offer Teravicta's RF MEMS switches worldwide.
- **Xanoptix** and **Tyco Electronics** announced a multiyear, multi-million dollar joint strategic business agreement to promote Xanoptix's XTM Series of optical transceiver products. The alliance enables the companies to provide the next generation of parallel optics transceiver modules, utilizing optically integrated circuit technology with fused silicon chips and high performance active optics.

[Continued on page 50]

## SAW

#### OSCILLATORS

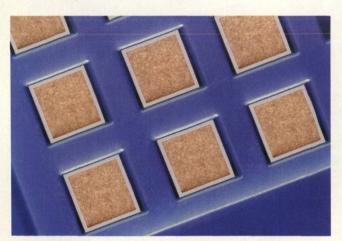


For additional information, contact Synergy's sales and application team.
201 McLean Boulevard, Paterson, NJ 07504
Phone: (973) 881-8800 Fax: (973) 881-8361 E-mail: sales@synergymwave.com
World Wide Web: www.synergymwave.com



#### **AROUND THE CIRCUIT**

- Spectrum Control and Littelfuse Inc. have entered into a teaming agreement. This agreement will create a synergism of the two organizations in the development of a series of integrated passive electromechanical solutions.
- Anritsu Co. has formed a partnership with Centro de Tecnologia de las Comunicaciones SA that creates a complete Bluetooth test solution incorporating Anritsu's model ME7865A Bluetooth pre-qualification test system and a discounted qualification process through CETE-COM, a Bluetooth Qualification Test Facility. In related news, Anritsu's model ME7808A broadband vector network analyzer (VNA) has earned two marketing engineering awards from Frost & Sullivan. The awards recognized the product as the year's most innovative test instrument overall as well as the top VNA, according to independent analysts who conducted extensive evaluations and research on leading measurement instruments.
- Advanced Analogic Technologies Inc. (Analogic-Tech) has entered into a distribution agreement with Future Electronics. Under terms of the new agreement, Future Electronics will sell and support Analogic Tech's entire Total Power Management product line, including its PowerManager,™ PowerLinear™ and SmartSwitch™ product families.
- Ansoft Corp. has formed an educational partnership with Carnegie Mellon University's Center for Wireless



#### Broadband Single Layer Ceramic Capacitors

- Stable Performance From 1 Mhz 40 GHz
- Maximum Values in Small Chip Sizes
- Temperature Stable ±15% (-55 to125°C)
- Thin-Film Terminated with Borders
- Request Samples On-line

Visit our website today for complete details



johanson technology.com camarillo california 805.389.1166

- and Broadband Networking by donating advanced software for the virtual design of high frequency technology. The in-kind contribution, which begins a three-year partnership between the two, includes an initial donation of Ansoft's HFSS™ and Ansoft Designer™ packages as well as support. In related news, Ansoft launched a campaign to expand the use of its electromagnetic and electrostatic simulation software by offering a free subset of the company's commercially available Maxwell 2D. The software, marketed at Maxwell SV, can be downloaded at www.ansoft.com/maxwellsv.
- Texas Instruments Inc. (TI) has been appointed to the board of directors of the Wi-Fi Alliance as the organization's latest sponsor member helping to promote and expand the global Wi-Fi market. TI has been a contributing general member of the Wi-Fi Alliance since its acquisition of Alantro Communications in September 2000.
- The microwave antenna products formerly produced by **TriPoint Global Communications'** Mark Antenna business will be manufactured under the Prodelin brand. The company will discontinue the use of the Mark Antenna name and brand.
- **AMI Semiconductor** announced that its operation in Belgium achieved ISO/TS 16949 certification. ISO/TS 16949, coupled with customer-specific requirements, defines quality system requirements for use in the automotive supply chain.
- Sprague-Goodman Electronics Inc. recently commemorated its 30th anniversary with a celebration ceremony at the company's Westbury, NY, headquarters.
- Cole Tubes Ltd. is offering to help customers of the precision drawn products manufacturer H Rollet and subsidiary Blackheath Tube, which went into receivership on September 5, 2002.

#### FINANCIAL NEWS

- Linear Technology Corp. reports sales of \$142.01 M for the first quarter ended September 29, 2002, compared to \$120.10 M for the same period in FY 2002. Net income was \$53.8 M (17¢/diluted share), compared to \$45.2 M (14¢/diluted share) for the first quarter of last fiscal year.
- **RF Micro Devices Inc.** reports sales of \$119.7 M for the second quarter ended September 30, 2002, compared to \$98.3 M for the same period in 2001. Net income was \$6.5 M (4¢/diluted share), compared to \$1.5 M (1¢/diluted share) for the second quarter of last year.
- **TESSCO Technologies Inc.** reports sales of \$70.4 M for the second quarter ended September 29, 2002, compared to \$62.0 M for the same period in 2001. Net income was \$1.2 M (26¢/diluted share), compared to \$900 K (20¢/diluted share) for the second quarter of last year.
- **REMEC Inc.** reports sales of \$53.5 M for the second quarter ended August 3, 2002, compared to \$60.4 M for the same period in 2001. Net loss was \$16 M (35¢/diluted share), compared to a net loss of \$15.4 M (34¢/diluted share) for the second quarter of last year.

[Continued on page 52]

# GAAS SWITCHES

SPDT + SP4T, 6T, 8T + DIVERSITY + MATRIX

HMC284MS8 45~50 dB Isol. 0.5 dB LOSS DC - 3.5 GHz



HI-ISOLATION SPDTS FROM

- Broadband to 15 GHz
- +3V Diversity & T/R
- Multi-Throws w/ **Integrated Drivers**
- Reflective & Non-Reflective
- Excellent Linearity, up to +65 dBm IP3

#### A SELECTION FROM OUR BROAD GAAS IC SWITCH LINE

	PART NUMBER	FUNCTION	FREQUENCY RANGE (GHz)	LOSS / ISOL. (dB)	P1dB (dBm)	USD @ 10K PCS
	HMC197	SPDT	DC - 3.0	0.4 / 28	30	\$0.61
	HMC284MS8G	SPDT	DC - 3.5	0.5 / 45	25	\$0.68
	HMC270MS8G	SPDT	DC - 8.0	1.2 / 48	23	\$1.21
NEW!	HMC347LP3	SPDT	DC - 15.0	1.6 / 44	23	CALL
	HMC226	SPDT T/R	DC - 2.0	0.5 / 20	35	\$0.40
	HMC174MS8	SPDT T/R	DC - 3.0	0.5 / 25	39	\$0.92
	HMC224MS8	SPDT T/R	5.0 - 6.0	1.2 / 31	33	\$1.29
	HMC199MS8	BY-PASS DPDT	DC - 2.5	0.3 / 25	23	\$1.04
NEW!	HMC427LP3	TRANSFER	DC - 8.0	1.3 / 42	26	CALL
NEW!	HMC436MS8G	DIVERSITY	5.1 - 5.9	1.0 / 23	30	\$1.86
	HMC241QS16	SP4T	DC - 3.5	0.5 / 45	25	\$2.55
	HMC345LP3	SP4T	DC - 8.0	2.2 / 35	21	\$7.10
	HMC252QS24	SP6T	DC - 3.0	0.8 / 41	24	\$2.65
	HMC253QS24	SP8T	DC - 2.5	1.1 / 36	23	\$3.66
	HMC321LP4	SP8T	DC - 8.0	2.5 / 35	23	\$9.26
	HMC276QS24	4x2 MATRIX	0.7 - 3.0	5.8 / 33	26	\$3.66

SELECT PRODUCTS AVAILABLE IN DIE FORM. ALL DATA IS MID-BAND TYPICAL.

ACTUAL SIZE

SOT26







www.hittite.com





**Corporate Headquarters** 

12 Elizabeth Drive, Chelmsford, MA 01824

HMC Europe, Ltd. Ph +44(0) 1256-817000 Fax +44(0) 1256-817111 europe@hittite.com HMC Deutschland GmbH Ph +49 8031-97654 Fax +49 8031-98883 germany@hittite.com HMC Asia Co., Ltd. Ph +82-2 559-0638 Fax +82-2 559-0639 asia@hittite.com



**ORDER ON-LINE:** 

ISO 9001

Distributed in the Americas and Asia by Future Electronics Ph (800) Future-1, ext. 2754 Americas & ext. 5284 Asia www.futureelectronics.com/rl

#### **AROUND THE CIRCUIT**

- Stratex Networks Inc. reports sales of \$52.6 M for the second quarter ended September 30, 2002, compared to \$60.9 M for the same period in FY 2002. Net loss was \$4.4 M (5¢/share), compared to \$56.5 M (72¢/share) for the second quarter of last fiscal year.
- Cree Inc. reports sales of \$48.8 M for the first quarter ended September 29, 2002, compared to \$43.2 M for the same period in FY 2002. Net income was \$3.9 M (5¢/share), compared to \$6.5 M (9¢/share) for the first quarter of last fiscal year.

#### CONTRACTS



▲ Harry Cunningham & Jim Zanello

Point to Point Radio

Frequencies from

350MHz to 50GHz

and Band Reject

Band Pass, Low Pass

Satellite

Stability

**Broadband Wireless Access** 

High Accuracy, Tuning Free Designs

With Excellent Temperature

MMDS, LMDS, UMTS, GSM

Harry Cunningham and Jim Zanello have accepted consulting contracts with Thunderline-Z. After selling the co-owned Thunderline-Z business to the Fusite Division of Emerson in 2000, Cunningham and Zanello will be working in consultative VP of sales and engineering roles. The two started Thunder-

line-Z in 1984. Terms and financial details of the contracts were not disclosed.

**Boonton Electronics**, a wholly-owned subsidiary of Wireless Telecom Group Inc., has been awarded an ad-

Microwave & RF

Filters & Diplexers

ditional contract with the Federal Aviation Administration (FAA) for Boonton's 4530 series RF peak power meter, supporting the FAA's latest projects on air traffic control. The power meter is utilized by the FAA for its newest beacon system, ATCBI-6, for transponder queries in airplanes.

Nurad Technologies has been awarded a contract by Lockheed Martin to provide antennas and radomes for the Peace Marble V F-16 program. Nurad, part of the Chelton Microwave Group, will design and develop this antenna suite, which will interface with the electronic warfare system.

#### PERSONNEL

- Terry Nisbet joined United Monolithic Semiconductors (UMS) as chief operating officer. He will be a member of the management board of UMS and his main tasks will be to help the company adapt to the challenges of the market place, strengthen its position and to improve the support UMS gives to customers.
- Modelithics Inc. has named Jerry Schappacher to its company board of directors. Shappacher brings more than 20 years of engineering and entrepreneurial experience. He is the founder and current president of J-micro Tech-
- RF Micro Devices Inc. has appointed Frederick J. **Leonberger** to its board of directors. Leonberger is a senior VP and chief technology officer of JDS Uniphase Corp.
- StratEdge announced that Ralph Nilsson has been appointed the new president of the company's Taunton, MA, division. The Taunton Division designs and manufactures hermetic glass-to-metal seal, flatpack, plastic equivalent packages and metal packages for telecommunications. Nilsson has 20 years of experience working in engineering, manufacturing and assembly, sales and marketing, operations, and quality control for microwave products.
- MEMGen Corp. has appointed **Kang Sun** as VP, business development. With 15 years of experience growing companies and building strategic alliances worldwide, Sun will lead the company's sales and strategic partnership efforts.



A Paul Leo

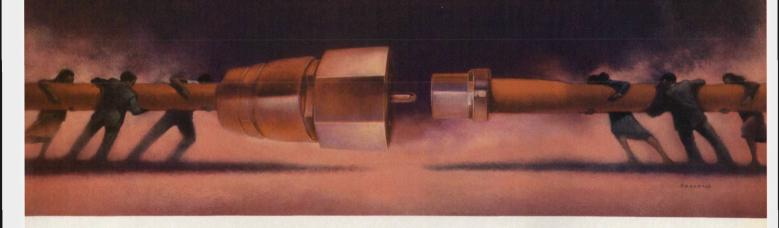
Paul Leo has joined Spectrum Control as director of new business development for the new Spectrum FSY Microwave line of products. In this position he is responsible for all sales activities and business growth related to the company's microwave product line. Prior to joining Spectrum, Leo was employed for over 17 years at K&L Microwave, most recently holding the position of director of new business development.

Analog Devices Inc. has appointed Serge Recoules as managing director of European sales and marketing. Re-

[Continued on page 55]

Battle Road · Heathfield · Newton Abbot · Devon TQ12 6XU · England Tel: +44 (0)1626 834222 Fax: +44 (0)1626 832994

# CALLTRUOR SUFFICES.



From cable assemblies and connectors to custom design services, consulting and training, you're making the wrong call if you're not calling TRU. We're more than just connectors. That's why we've changed our name from Tru-Connector to TRU Corporation.

TRU Corporation offers an unmatched selection of custom-engineered and build-to-print interconnect solutions. Our leading-edge technology and custom design/manufacturing capabilities help you say good-bye to production delays and cost overruns. Order quantity is never a problem.

Tired of all the reasons you can't get your cable assembly when and how you want it? End your suffering today. Call Brenda Wheeler at 1-800-COAX-TRU (1-800-262-9878) or visit us on the Web at www.trucorporation.com.



The Custom Interconnect Leader ™

©2002 TRU Corporation, 245 Lynnfield Street, Peabody, Massachusetts 01960

# VALUED PRODUCT TO VALUED CUSTOMER

- 38 YEARS EXPERIENCE IN RF CONNECTORS
- CAPABILITY AND FACILITIES

  Fully computerized MRP and MIS systems

  State-of-the-art equipment
- 100 sets CNC turning center

   R&D

Professional designing capability

New product development capability

- QUALITY
- ISO-9001 qualified
- SERVICE

Quick response
On-time delivery



@ 14 CENTS US DOLLARS
BNC CRIMP PLUG CONNECTORS
FOR RG58U CABLE
VSWR 1.3 AT 4 GHz





















CHIN NAN®PRECISION ELECTRONICS CO., LTD.

NO. 22-1 JEN-HO ROAD, TAINAN, TAIWAN, TEL:886-6-2678303 FAX:886-6-2678337 E-Mail:sales@chinnan.com.tw www.chinnan.com.tw

#### **AROUND THE CIRCUIT**

coules will be responsible for leading the company's European sales effort, managing an experienced team of sales people across the region.



▲ Stuart Hendry

- Link Microtek has promoted **Stuart Hendry** to the position of sales manager. Hendry joined the company in 1996 as sales manager for the North and Midlands.
- Ceramaseal has named **Grant Schrag** its product development engineer at the New Lebanon, NY,-based facility. Previously, Schrag worked 12 years with MDC Vacuum Prod-

ucts Corp. and more specifically the Insulator Seal Division.

#### REP APPOINTMENTS

- MICRO-COAX, Pottstown, PA, has appointed Promark Electronics Inc. as its exclusive distributor for Canada. Promark will represent MICRO-COAX's full line of semi-rigid products.
- Phase One Microwave Inc., Rocklin, CA, has made a series of rep appointments. Technology Marketing Associates will handle the Carolinas, Tennessee, Mississippi, Alabama, Georgia and general accounts in Florida, while Microwave Component Sources will handle specific target accounts in Florida. TriTex Technical Sales will cover Texas, Oklahoma, Arkansas and Louisiana, and Calin-Southwest will be responsible for Arizona, New Mexico and El Paso. Rep Sales will handle Utah, Colorado, Wyoming and eastern Idaho.
- Plextek Ltd. has signed a UK distribution agreement with Admiral Microwave Ltd. Admiral will be promoting Plextek's wide ranging electronics to microwaves design expertise and will now be in a position to offer a complete service to customers looking for system and RF subsystem solutions or an extended component characterization.
- AMCOM Communications Inc. has made a series of representative appointments. E-Squared Marketing Inc. will handle New York/Long Island, northern New Jersey and southern Connecticut. Internationally, Nexos Electronic Systems SrI will be the exclusive representative for Italy and Matec Electronique for France.

#### **WEB SITE**

■ PolarFab has launched a new, fully upgraded Web site at www.polarfab.com. Designed to provide technical and real-time manufacturing information to fab-lite, fables and independent device manufacturers, the site features an easy-to-use, secure customer access center for customers to view current inventory status and testing data. The site also provides extensive technical information such as application notes for each of the company's bipolar and BiCMOS process technologies.



55

### UNDERSTANDING W-CDMA MODULATION QUALITY MEASUREMENTS

There are many ways of characterizing W-CDMA transmitter performance. However, the Third Generation Partnership Project (3GPP) specifications require two measurements to verify the in-channel modulation quality of W-CDMA transmitters - error vector magnitude (EVM) and peak code domain power (peak CDE). This article explores the purpose behind these key transmitter modulation quality conformance measurements for W-CDMA user equipment, why they are important and the relationship between them.

In constant-amplitude modulation schemes such as Gaussian minimum shift keying (GMSK), phase and frequency error are the metrics for modulation quality. However, this metric is not very effective for non-constant amplitude modulation formats that can also have errors in amplitude. The accuracy of non-constant amplitude modulation schemes such as quadrature amplitude modulation (QAM) and quadrature phase-shift keying (QPSK) can be assessed effectively by looking at the constellation of the signal. Signal impairment can be objectively evaluated by taking the displacement of each measured symbol from the reference position as an error vector (or phasor). The error vector is the vector difference between the measured and reference vectors, and the reference position is determined from a reference signal that is synthesized by demodulating the data bits from the received signal and remodulating these bits "perfectly."

The EVM is defined as the square root of the ratio of the mean error vector power to the mean reference power, expressed as a percentage:

$$EVM = \sqrt{\frac{\sum_{n=0}^{N-1} \left| error vector(n) \right|^{2}}{\sum_{n=0}^{N-1} \left| reference vector(n) \right|^{2}}} \bullet 100\%$$

When evaluating the modulation accuracy of W-CDMA signals, it becomes evident that this definition of EVM, while sufficient for ordinary QPSK or QAM, needs further elaboration. Questions arise such as whether EVM should be measured at the chip or at the symbol level, whether it should be measured for a signal with a single dedicated physical data channel (DPDCH) or with another channel configuration, and how the reference should be calculated. As a result, there are three types of EVM measurements — OPSK EVM. composite EVM and symbol EVM.

The EVM measurement described in the 3GPP specifications corresponds to a composite EVM measurement. Although QPSK EVM and symbol EVM are not required, they can be useful when designing and troubleshooting a W-CDMA transmitter. The differences and benefits of each EVM measurement are ex-

plained below.

#### **QPSK EVM**

A W-CDMA uplink signal can consist of one dedicated physical control channel (DPCCH) and several DPDCHs. Each channel is binary

[Continued on page 59]

MARTA IGLESIAS Agilent Technologies Barcelona, Spain

#### Look what our engineers have been up to!



#### **NEW!** Warning to traditional LNAs: Meet your worst nightmare!

It's new. It's balanced, It's low noise, It's a compact surface mount. And it comes in a 50Ω-matched, fully integrated, highly-repeatable Xinger®-brand package... In other words, our new LNA officially makes traditional, discrete LNA solutions dinosaurs:

- Superior input/output return loss better than 20dB
- Performance fit for all your DCS, PCS, and 3G apps
- Measures only 1.0 x 0.65 x 0.10" (25.4 x 16.5 x 2.6mm) - a huge space savings over traditional designs
- No expensive PCB needed: Just use FR4 and still achieve an 0.8 dB noise figure with this unit as your 1st stage LNA!
- Incorporates the latest, Agilent ePHEMT technology
- Only requires a single, "positive" polarity supply voltage (nothing negative about this LNA!)

So, reduce your component count, vendor base, time-to-market, and headaches caused by "non-core" competencies... Switch to a Xinger-brand LNA today by calling for a quick-quote - or e-mailing xlna@anaren.com



#### At 800/900 MHz, our wayeasy-to-work-with circulator just got way-more-economical, too!

If you liked our revolutionary Xinger®-brand circulators but wanted a lower frequency, even lower-cost part... Here you go!

- Now available in 800 and 900 MHz
- SM package measures 1.0 x 1.0 x 0.299" (25.4 x 54.4 x 7.59 mm) on tape and reel
- Ideal fit for MCPAs/SCPAs
- Delivery from multiple global manufacturing locations for added convenience
- Low insertion loss of 0.25 dB/typ
- Low return loss of 27 dB/typ
- High isolation of 27 dB/typ
- Matched RF Power-brand terminations and attenuators ready to go!
- Cost-conscious assembly: Lead-free solder compatible to 265°, extremely repeatable, no machined heat-sinks, simple load-change for design reuse, and more!

Call for a quick-quote, app notes, and evaluation board - or e-mail 800xcirculator@anaren.com.



#### NEW! Let our Amitron unit's worldclass LTCC service get you a prototype ASAP!

Need a dense multilayer network for a high-density, high-frequency app? Looking at a complex design full of interconnects? Our Amitron subsidiary will do the job right — and right quick!

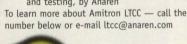
- \$1 million in new, world-class LTCC equipment manned by an experienced staff
- 200 mm format capability
- Established DuPont, Ferro & Heraeus materials and systems
- Stringent process control quarantees performance
- For added integration, we also offer:
  - High-performance, advanced etched photolithography conductor processing
  - Passive element tuning by YAG lasers
  - Gold and solder plating for robust manufacturing
  - 100% continuity testing & brazing capabilities
  - Plus world-renowned microwave-circuit design and testing, by Anaren



#### "B-style" couplers from RF Power: The lowest-loss parts in their class. Period.

Working on a high-power amp? Balanced amplifier? Signal distribution platform? Have we got a high-power, very low-loss coupler for you!

- True SM, on tape and reel measures 1.0 x 0.5" (25.4 x 12.7 mm)
- Insertion loss as low as 0.15 dB!
- Power handling from 100 to 300 Watts
- Frequency ranges from 400 to 2300 MHz
- Supports: UHF, AMPS, GSM, DCS, PCS,
- Arrives 100% tested, for best-possible-yield Call for a quick-quote — or e-mail rfpbcoupler@anaren.com



What'll we think of next?

800-411-6596 > www.anaren.com
In Europe, call 44-2392-232392 > 150 9001 certified
Visa/MasterCard accepted (except in Europe)

Click LEADnet at mwjournal.com or Circle 4 on Reader Service Card

# MEGAPHASE \* Cercove Tube \* Technology

Use GrooveTube® for your ATE or VNA:

For Consistent Measurements. Every Time, All The Time.
The Best Phase and Amplitude Stability. Period.
Save Money Over OEM Test Cables.



# Recovery -6 DC 10 20 30 40 50 Frequency (GHz)

Typical Phase vs. Flexure

# Typical Amplitude vs. Flexure 20 (a) 10 Recovery Novement -20 DC 10 20 30 40 50 Frequency (GHz)

#### **GrooveTube® Test Cable Products**

Your Application •	VNA High Performance Test Cable	MegaRED™ Bench Test Cable	SightLine™ Field & Prod. Test Cable	Superflex Low Loss Test Cable
MegaPhase® Series	VN Series	TM Series	SL Series	SF Series
DC - 4 GHz	VN4	TM4	SL4	SF4
DC - 8 GHz	VN8	TM8	SL8	SF8
DC - 18 GHz	VN18	TM18	SL18	SF18
DC - 26 GHz	VN26	TM26	SL26	SF26
DC - 40 GHz	VN40	TM40	SL40	10
DC - 50 GHz	VN50	TM50	SL50	
Max. Frequency		50 GHz		26.5 GHz
Inner Conductor		Solid		Stranded
Dielectric		Solid PTFE		PTFE Tape
Outer Conductor	Super-Fle	xible Copper Gr	ooveTube® by Me	gaPhase®
Finished Outer Diameter	0.625 in. 15.88 mm	0.285 in. 7.24 mm	0.500 in. 12.70 mm	0.285 in. 7.24 mm
Ruggedization	Metal Braid over Metal Armor	Metal Braid	Metal Braid over Metal Armor	Metal Braid
Outer Jacket	PET Braid	Polyolefin	Neoprene	Polyolefin
Bend Radius	1.5 in. 38.1 mm	0.5 in. 12.7 mm	1.5 in. 38.1 mm	0.5 in. 12.7 mm
Flexibility Rating – Highest = 5.0	4.0	4.5	4.0	5.0

For data on the full line of MegaPhase® products:

MegaPhase.com

1-877-MegaPhase / 570-424-8400

GrooveTube@MegaPhase.com

Repeatable & Consistent Measurements: GrooveTube\* is a super-flexible copper outer conductor that maintains its geometry – flexure after flexure. GrooveTube\* doesn't cage, kink and fatigue like traditional braid/foil outer conductors. As a result calibrations won't degrade over time.

Superior Phase & Amplitude Stability to 50 GHz:

GrooveTube\* outer conductor is the industry's best phase & amplitude performance vs. flexure. When flexed, the inner conductor stays dead center.

Cost Savings vs. OEM
Test Cables:

Save your budget dollars – GrooveTube\* test cables feature the lowest cost per measurement: fewer calibrations, longer life and less procurement. MegaPhase\* rugged test cables feature precision connectors, ISO-level quality, and fast deliveries.



Broadband Probe Station Adapter



Testing, Connecting, and Enabling Electronic Systems from DC-50 GHz.

Click LEADnet at mwjournal.com or Circle 49 on Reader Service Card

phase-shift keying (BPSK) encoded, assigned to either the I or the Q paths, and spread with an orthogonal variable spreading factor (OVSF) code. The individual BPSK channels for each path are typically added at this point, and the complex-valued chip sequence is hybrid phase-shift keying (HPSK) scrambled. The resulting chip sequence is then root raised cosine (RRC) filtered, and the result is applied to the QPSK modulator. Since multiple amplitude levels are applied to the I and Q paths of the modulator, the final constellation does not usually look like QPSK or any other known constellation.

However, there are a few channel configurations that map onto a QPSK constellation. A single DPCCH (or DPDCH), for example, results in a QPSK constellation after the HPSK scrambling. A signal with a DPCCH and a DPDCH at the same power level maps onto a 45° rotated QPSK constellation. The rotation is caused by the complex scrambling. Since the receiver does not care about the absolute phase rotation, it effectively sees a QPSK con-

stellation. The modulation quality of a single-channel signal (or other simple channel configurations) can be evaluated at the scrambled chip level with a QPSK EVM measurement.

The QPSK EVM actually compares the measured filtered samples with the filtered samples for an ideal QPSK reference. The filtered sample reference signal is calculated by obtaining the ideal scrambled chips. The QPSK EVM measurement does not descramble and despread the signal into symbols and back into chips to calculate the reference. Consequently, the ideal scrambled chips that are obtained are really uncoded chips.

The signal under test is downconverted (the baseband I and Q signals are recovered and sampled), and passed through an RRC receiver filter. In order to calculate what the ideal chips are, the measurement algorithm assumes that they are going to map onto a QPSK constellation, so the measured samples go through a decision process that can be considered a QPSK decoder. This process samples the chip timing and decides to which QPSK

state they correspond. This is equivalent to obtaining the "ideal" chips. Like any other QPSK decoder, the algorithm assumes that the error will be small enough for the sample to fall onto the correct quadrant. Once the ideal uncoded chips are obtained, they are QPSK encoded again (assigned to the reference QPSK states), and passed through a raised cosine (RC) filter that is equivalent to the filtering experienced by the measured signal.

The QPSK EVM measurement is the starting point for the RF engineer. Before all the baseband algorithms are ready, the RF designer can evaluate the performance of the RF section by analyzing the trajectory of the baseband samples. Errors such as phase modulation or in-channel spurious content can be detected by looking at displays such as the constellation, phase error versus time, or error vector spectrum. The QPSK EVM measurement can also identify I/Q errors and linear impairments in the baseband filtering.

The QPSK EVM measurement can also be used by the system integrator to

[Continued on page 61]

# WE COULD TRY TO MAKE OUR DIVIDERS LOOK MORE EXCITING.



(But their performance is excitement enough.)



We'll leave flashy product colors to those who lack the substance of Narda. For over 40 years, we've delivered products with such unmatched unit-to-unit repeatability that quality has become a Narda trademark. Just look at our dividers/combiners. They offer performance advantages in everything from superior isolation to excellent phase and amplitude balance. Ask about our custom capabilities, too. Call today at 631-231-1700. You'll be pleased with our competitive prices. Delighted with the fast delivery. And thrilled with Narda's quality. Now, with excitement like that, who needs to be wowed by the paint job?

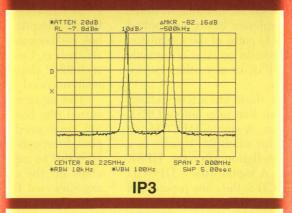


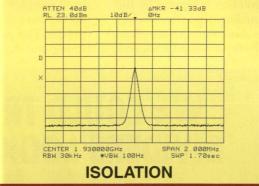
# SV MICROWATE® RF Connectors & Components

## High IP3 Mixers

HIGH PERFORMANCE + HIGH VOLUME + HIGH VALUE







When it comes to Signal Processing Components, SV Microwave sets the standard.

- + IP3 to +40 dBm
- + Low Loss 6.5 dB
- Isolation 40 dB
- Low Noise 7 dB
- + No DC Bias Required
- Custom Frequency to 12 GHz
- Military and Commercial Applications

www.SVMicrowave.com

800.313.2120



troubleshoot the design when other measurements are failing. This may occur, for example, if the spreading and scrambling algorithms or the synchronization algorithms are not working properly. A correct QPSK EVM measurement will confirm that the problem does not occur in the RF section, so it must lie somewhere in the spreading or scrambling algorithms.

#### **COMPOSITE EVM**

Although measuring EVM for a signal with a single DPCCH (or other simple channel configuration) may be useful, in general the overall modulation quality of the transmitter for any channel configuration is the point of interest. The constellation of this signal will vary depending on its channel configuration. The composite EVM measurement evaluates the modulation quality of the signal regardless of its channel configuration. To synthesize a reference signal for the uplink signal, the active channels must be identified and despread to the encoded bit level, and EVM is calculated only for the scrambled chip samples.

After the baseband I and O signals are recovered and filtered, the signal is descrambled and the active channels are identified, despread and BPSK-decoded to bits. The BPSK decoding refers to the assignment of "0"s and "1"s for either the I or Q path depending on the symbol amplitude values obtained for that path after the despreading. It actually corresponds to a bit detection process. The composite EVM measurement algorithm does not perform the complete decoding (deinterleaving, etc.) of the encoded bits. Instead, the reference signal is built from those encoded bits assumed to be correct. So if errors occur during the signal coding and interleaving, they will not be reflected in the measurement result.

In order for the measurement to identify the active channels and despread the channels correctly, it must synchronize to the DPCCH pilot sequence. A correct DPCCH pilot bit pattern is essential to make accurate measurements. As required by the WCDMA 3GPP specifications, "the square root of the ratio of the mean power of the error signal to the mean

power of the reference signal" is computed and expressed as a percentage EVM. In other words, EVM is defined as the ratio of the RMS power of the error vector to the RMS power of the reference signal. The error vectors are calculated only for the samples at the chip times. The algorithm described in the specifications includes descrambling and despreading of the signal, so it is suitable for measuring composite signals, and the specifications require an EVM measurement interval of one time slot.

The 3GPP specifications also describe the channel configuration to perform the modulation quality conformance test (EVM). The channel configuration is the 12.2 kbps uplink reference measurement channel, which consists of a DPDCH and a DPCCH. The DPCCH is –5.46 dB lower than the DPDCH. The specifications require an EVM better than 17.5 percent. The modulation quality test of the 12.2 kbps uplink reference measurement channel, as required by the specifications, is shown in

[Continued on page 63]

# WE COULD TRY TO MAKE OUR SWITCHES LOOK MORE EXCITING.



(But their reliability is excitement enough.)



Maybe our competitors should dress their products in hot, new colors because they'll never match Narda's quality. For over 40 years, we've delivered products with such unmatched unit-to-unit repeatability that quality has become a Narda trademark. Just look at our switches. You can choose from more than 30 distinct models. Plus a wide range of custom switches for virtually any requirement. Ask about our custom capabilities, too. Call today at 631-231-1700. You'll be pleased with our competitive prices. Delighted with the fast delivery. And thrilled with our quality. And with that kind of excitement, who needs a jazzy paint job?





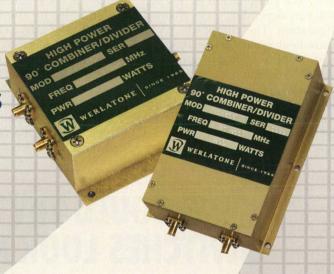
Werlatone, Inc. 2095 Route 22 PO Box 47 Brewster, NY 10509 845.279.6187 FAX.279.7404

Directional Couplers Combiners Dividers 90°/180° Hybrids

# WHEN EVERY WATT COUNTS!

90°
High Power
Combiners & Dividers

- Multi-Octave Performance
- Low Insertion Loss
- Designed to Withstand Severe Input Unbalances



Model	Frequency (MHz)	Power (Watts CW)	Insertion Loss (dB Max.)	VSWR (Max.)	Phase Balance (Deg. Max.)	Isolation (dB Min.)
QH6306	0.5 - 1.6	50	0.4	1.30:1	± 6	20
QH6307	0.5 - 1.6	1500	0.5	1.30:1	± 6	20
QH6212	2 - 30	80	0.3	1.25:1	±5	25
QH6213	2 - 30	1200	0.3	1.25:1	±5	25
QH6312	10 - 150	10	0.6	1.30:1	± 5	20
QH6313	10 - 150	250	0.6	1.30:1	± 5	20
QH6030	20 - 500	10	0.5	1.40:1	±8	20
QH6031	20 - 500	200	0.6	1.40:1	±8	20



www.werlatone.com

Figure 1. In addition to conformance testing, there are several main applications for which the composite EVM measurement (and its related displays and metrics) would be used instead of a QPSK EVM measurement.

#### EVALUATION OF THE QUALITY OF THE TRANSMITTER FOR A MULTI-CHANNEL SIGNAL

This is particularly important for RF designers, who need to test the RF section (or components) of the trans-

Fig. 1 Modulation quality test of the 12.2 kbps uplink reference measurement channel.



mitter using realistic signals with correct statistics. In general, the peak-to-average power ratio of the signal increases as the number of channels increases. By measuring modulation quality on a multi-channel signal, the performance of the RF design for W-CDMA uplink signals with different loading can be evaluated. An example of a composite EVM measurement on a signal with the DPCCH and three DPDCHs is shown in *Figure 2*.

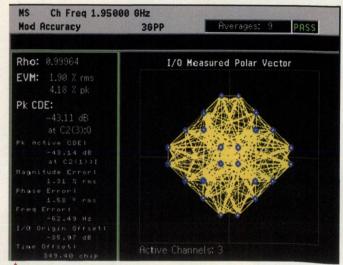


Fig. 2 Example of a composite EVM measurement on a signal with the DPCCH and three DPDCHs.

[Continued on page 65]



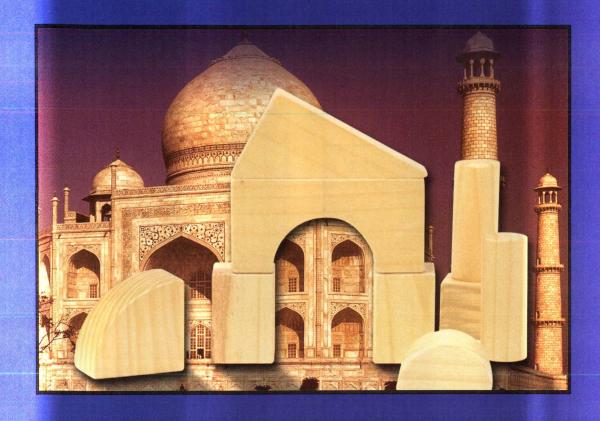


(But their reliability is excitement enough.)



Maybe our competitors should try making their products look pretty in pink because they'll never match Narda's quality. For over 40 years, we've delivered products with such unmatched unit-to-unit repeatability that quality has become a Narda trademark. Just look at our couplers. Their superior frequency response and exceptional directivity make them an indispensable measurement tool. Ask about our custom capabilities, too. Call today at 631-231-1700. You'll be pleased with our competitive prices. Delighted with the fast delivery. And thrilled with Narda's quality. Now, with excitement like that, who needs a glitzy paint job?





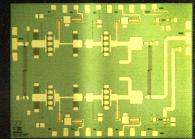
#### FEEL LIKE YOU'RE TRYING TO BUILD THE TAJ MAHAL WITH BEGINNER BLOCKS?

If yesterday's limited building blocks don't work... If your product hinges on superior intermodulation performance to achieve high data rates, every time...

Consider that Mimix Broadband, Inc. makes a wide selection of highly linear power amplifiers designed for superior operation in high index modulation schemes. They set a new standard for third

order intercept point performance and are loaded with features such as an on-chip temperature compensated power detector and excellent input/output return loss. And we guarantee the IP3 performance.

Mimix Broadband provides high performance MMICs for applications operating at 17 to 44+ GHz. Learn more about us at mimixbroadband.com.





Mimix Broadband, Inc. 520 W. NASA Road One Webster TX 77598 U.S. 281.526.0536 ©2002 All rights reserved. Mimix Broadband, Inc.

#### ANALYZING ERRORS THAT CAUSE A HIGH INTERFERENCE LEVEL IN THE SIGNAL

If the interference level is too high, the QPSK EVM algorithm may not be able to determine the ideal reference. In this case, QPSK EVM is not accurate. The composite EVM measurement descrambles and despreads the signal, so it takes advantage of its spreading gain. The true reference is recovered even when the signal is well beyond the interference level that will cause multiple chip errors. This allows system integrators to verify the minimum allowable modulation quality of the transmitter in order for the BTS (signal analyzer) to demodulate the signal in realistic field environments.

#### DETECTING SPREADING OR SCRAMBLING ERRORS

Depending on the degree of the spreading or scrambling error, the test equipment may show an intermittent or permanent unlocked condition for the composite EVM measurement. When this problem occurs,

the QPSK EVM measurement can be used to confirm that the rest of the transmitter is working as expected. If the scrambling or spreading error does not cause an unlocked composite EVM measurement condition, the error vector versus time display can be used to find the problematic chip. This is mainly useful to baseband engineers and system integrators.

#### SYMBOL EVM

Symbol EVM provides the constellation and EVM for a specific code channel at the symbol level, even in the presence of multiple codes. An impairment that affects symbol EVM will also affect the composite EVM. For example, an amplifier compression problem will appear both in the composite EVM and in the symbol EVM measurement. However, because of the spreading gain, symbol EVM will attenuate the impairment. Symbol EVM is used because it provides the bridge between RF and the demodulated bits. Since it includes the spreading gain, it provides a measure of modulation quality

that determines the error rate for that code channel.

The relationship between symbol EVM and EVM at the chip level depends on the spreading factor. At low spreading factors (high data rates), chip modulation errors have a significant effect on symbol EVM, but at high spreading factors, chip modulation errors have very little effect on symbol EVM. In that sense, symbol EVM is particularly useful for baseband engineers for evaluating symbol quality and analyzing how specific impairments affect the quality of dedicated physical channels at different data rates.

Another advantage of symbol EVM versus composite EVM is that the former typically provides analysis over longer periods of time. For the same amount of measurement points, the symbol EVM measurement covers longer periods of time than the single slot composite EVM conformance measurement. In the case of symbol EVM, the measurement in-

[Continued on page 67]

# WE COULD TRY TO MAKE OUR ATTENUATORS LOOK MORE EXCITING.



(But their dependability is excitement enough.)



Maybe our competitors should try making their products look fabulous in fuchsia because they'll never match Narda's quality. For over 40 years, we've delivered products with such unmatched unit-to-unit repeatability that quality has become a Narda trademark. Just look at our variable and fixed attenuators. They offer an almost limitless combination of dependable physical and electrical performance characteristics. Ask about our custom capabilities, too. Call today at 631-231-1700. You'll be pleased with our competitive prices. Delighted with the fast delivery. And thrilled with Narda's quality. Now, with excitement like that, who needs a flashy paint job?





#### The Wireless World in Your Lab



#### Ease of Simulation with Uncompromized Performance

The new integrated design of PROPSim C2 introduces unprecedented ease of use, flexibility of test set up and measurement accuracy to radio channel simulation. Be it for R&D or conformance testing, PROPSim C2 helps to reduce time-to-market, improve design quality and save in wireless product development costs.

#### Also available from Elektrobit:

PROPSim C8 - wideband multichannel simulator
PROPSound - multi-dimensional radio channel sounder

- RF, analog and digital baseband interfaces
- 3GPP conformance and deployment models
- Internal channel splitting/combining
- Internal noise source
- Internal local oscillator
- Touch screen operation

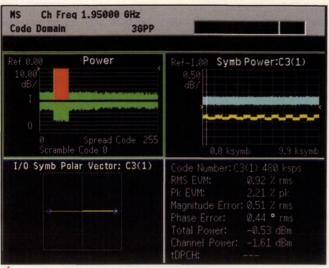


www.propsim.net



terval can usually be selected from 1 time slot to 30 or 60, depending on the number of frames captured. The time slot offset can also be selected.

For example, *Figure 3* shows the code domain power and symbol EVM for a W-CDMA uplink signal with a DPDCH and a DPCCH and with a periodic phase instability problem. The symbol EVM measurement is per-



▲ Fig. 3 Code domain power for a W-CDMA uplink signal with a DPDCH and a DPCCH and a periodic phase instability problem.

formed on the DPDCH for one time slot. *Figure 4* shows the symbol EVM measurement for the following time slot. In this case, the symbol EVM result varies a lot from time slot to time slot (0.92 versus 8.67 percent), an indication that the signal should be analyzed over a longer peri-

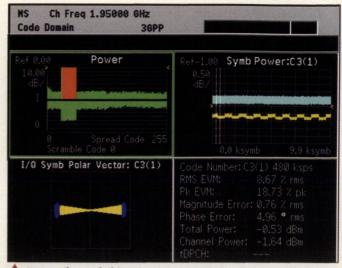


Fig. 4 The symbol EVM measurement for the succeeding time slot.

[Continued on page 68]

# WE COULD TRY TO MAKE OUR CONTROL PRODUCTS LOOK MORE EXCITING.



(But their quality is excitement enough.)



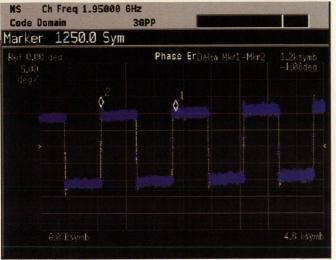
We'll leave the glitzy, day-glo product colors to those who lack the substance of Narda. For over 40 years, we've delivered products with such unmatched unit-to-unit repeatability that quality has become a Narda trademark. Just look at our control products. They feature high performance designs with high power ratings and low insertion loss. Ask about our custom capabilities, too. Call today at 631-231-1700. You'll be pleased with our competitive prices. Delighted with the fast delivery. And thrilled with Narda's quality. Now, with excitement like that, who needs to be dazzled by the paint job?



od of time. *Figure 5* shows the phase error versus time display for the DPDCH over 15 time slots. The period of the interfering signal that is causing the phase problem can be calculated from this display. In this case, the interfering signal is a square wave and its frequency is 400 Hz.

#### **PEAK CDE**

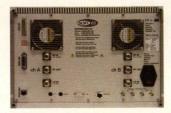
In W-CDMA systems, the composite EVM measurement has been supplemented by peak CDE, which specifies a limit for the error power in any one code. In the



▲ Fig. 5 Phase error vs. time for the DPDCH over 15 time slots.



The Radio Channel Simulator for GSM, 3G and CDMA2000



a proven cost effective solution
zero insertion loss design
digital performance

3 years warranty

Email: sales@sofimation.com Phone: +358-9-670 370 Fax: +358-9-670 208

www.sofimation.com

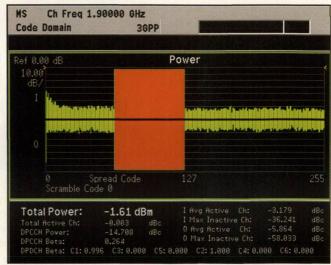
Click LEADnet at mwjournal.com or Circle 87 on Reader Service Card

case of phone conformance testing, this test is only required when multi-code transmission is provided. The phone must be configured with the UL 768 kbps reference measurement channel (which is the only UL reference measurement channel with two DPDCHs).

CDE is a projection of the error vector in the code domain. The projection of the error is interesting because it shows how the error power is distributed in the code domain. In general, Gaussian noise is distributed evenly throughout the code domain (both in active and inactive channels). Instead, transmitter impairments cause an uneven CDE distribution, where the larger errors concentrate on active channels, or in the case of a few specific impairments, in certain inactive channels. The error power should be evenly distributed throughout the code domain (as Gaussian noise), rather than concentrated in a few codes to avoid code-dependent channel quality variations.

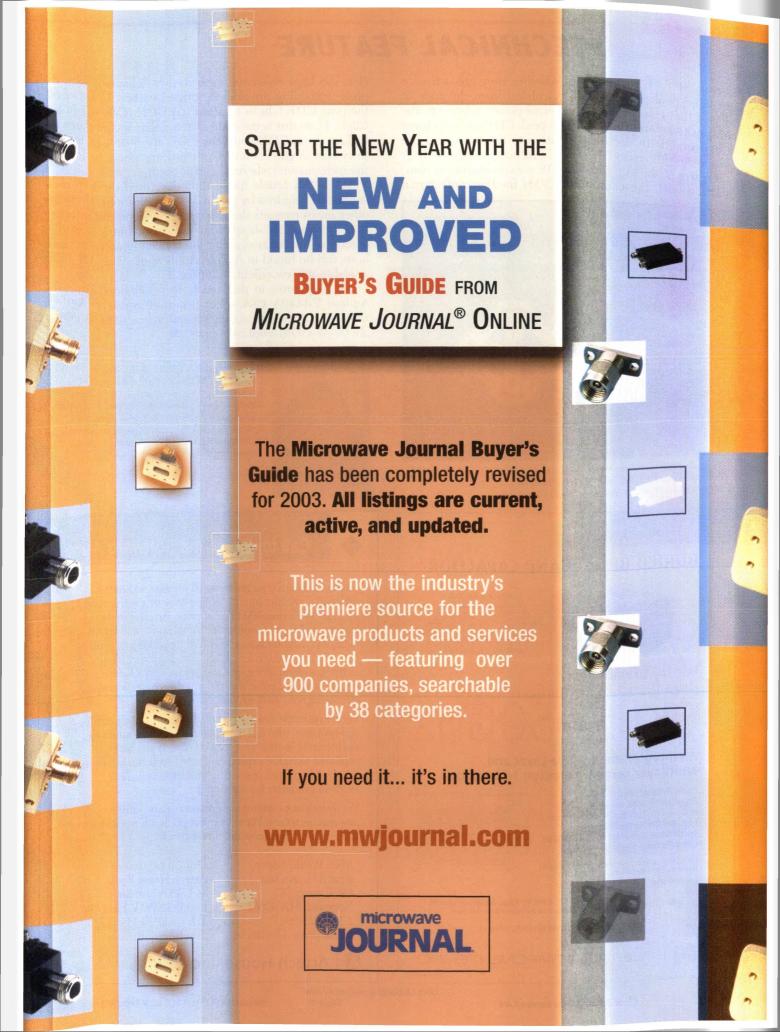
One cause of unequal distribution of error power is LO instability. In essence, energy is lost from the active channels and appears in those channels with codes that are closely related to the active channel codes. In the case of OVSF codes, LO instability results in higher code domain noise for channels with the same codes as the active code channels but with different I/Q path. The error energy may also fall in channels consecutive to the active code channels, whether at the same or different I/Q paths, as shown in *Figure 6* for a UL 768 kbps reference measurement channel (one DPCCH and two DPDCHs) signal with an LO phase instability problem.

The algorithm to calculate the CDE first goes through the composite EVM measurement. As part of this measurement, the error vector at the scrambled chip level is generated. This error vector is a composite error, so in order to obtain the error energy for each code channel, the composite error must be projected onto the code domain. As requested by the W-CDMA user equipment (UE) conformance test specifications for the peak CDE test, the projection is only performed for a spreading factor SF = 4. The error will thus be projected onto the four code chan-



▲ Fig. 6 Code domain power display for a signal (UL 768 kbps reference measurement channel) with a phase instability problem.

[Continued on page 70]



nels at SF = 4, regardless of whether they are active or not. The peak CDE is then calculated from the code at SF = 4 that returns the largest error power relative to the composite reference signal. The peak CDE measurement is expressed (in decibels) relative to the power of the composite reference. The error must not exceed -15 dB.

Figure 7 shows the peak CDE measurement (in combination with the composite EVM) for the same signal

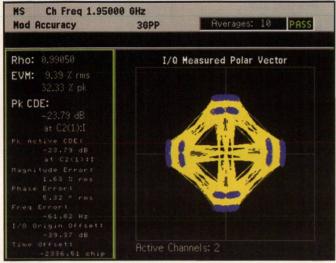


Fig. 7 Peak CDE measurement (in combination with the composite EVM) for the UL 768 kbps reference measurement channel signal of Figure 6.

(UL 768 kbps reference measurement channel) with the phase instability problem described earlier. In this case, the peak CDE falls in an active DPDCH (Cch, 4,1 in I or C2(1): I), so this is the code channel that accumulates the highest error. CDE and peak CDE are mainly of interest to system engineers and baseband engineers to identify the code channel where the error occurs.

While this article has mainly described the two measurements required by the 3GPP specifications, there are other measurements that also can provide useful information. Information about these measurements, as well as additional information about the measurements discussed here, can be found in Agilent Application Note AN-1356, available at www.agilent.com/find/3G.

All the figures in this article were obtained from the Agilent E4440A PSA spectrum analyzer. The Agilent E4438C ESG vector signal generator was used to generate the W-CDMA uplink signals.



Marta Iglesias holds her BSEE degree from the Universitat Politecnica de Catalunya, Spain. She has performed technical support for RF and microwave spectrum analyzers, and is currently a wireless industry marketing engineer for Agilent Technologies, where she is responsible for understanding the test needs of the wireless communications industry.



#### Call for Book and Software Authors

You can enhance your professional prestige and earn substantial royalties by authoring a book or a software package. With over 400 titles in print, Artech House is a leading publisher of professional-level books in microwave, radar, and telecommunications. We are seeking to publish new microwave engineering books and software in such areas as wireless communications, microwave and RF device design, advanced radar and antenna design, semiconductors, electromagnetic analysis, and more.

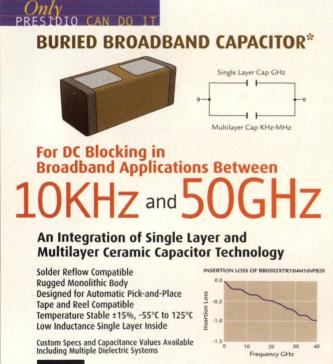
We are currently seeking potential authors among engineers and managers who feel they can make a contribution to the literature in their areas of expertise. If you have published technical papers, conducted professional seminars, or solved important real-world problems, you are an excellent candidate for authorship.

We invite you to submit your manuscript or software proposal for review. For a complete publications catalog and Author's Questionnaire please contact:

Mark Walsh, Editor Artech House, Inc. 685 Canton St. Norwood, MA 02062 1-800-225-9977 mwalsh@artechhouse.com

Dr Julie Lancashire Artech House Books 46 Gillingham Street London SW1V 1AH UK Tel: +44(0)20 7596 8750 ilancashire@artechhouse.co.uk

Artech House, Inc. BOSTON . LONDON



www.presidiocomponents.com/mwj

Call us today at 858 578-9390 for a free evaluation sample,

PRESIDIO COMPONENTS, INC.



From the company that brought you HFSS™...





...comes a new era of electromagnetically charged EDA software. Ansoft Designer's world-class circuit, system, and electromagnetic technology will redefine the way you design.



#### ANSOFT DESIGNER™

**Electromagnetically Charged EDA Software** 

### MODELING

Ansoft Designer integrates multiple electromagnetic solver technologies to provide the most complete physical design solution available. Ansoft Designer significantly improves accuracy while saving considerable time over traditional empirical characterization methods.

...ACCURATE...

### **SIMULATION**

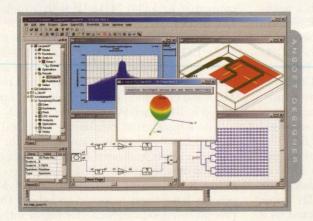
Ansoft Designer's time, frequency, and system analysis empower engineers to investigate all electrical performance criteria operating in real world conditions. True performance is understood and improved upon before committing to fabrication.

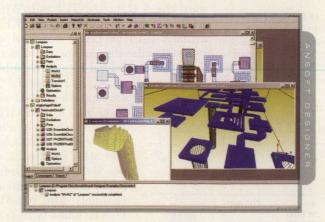
...FAST...

### **AUTOMATION**

Ansoft Designer can address all communication, IC, and PCB applications with its fully integrated layout editor, supported Java® and Visual Basic® scripting, advanced library management, and third-party links.

... EFFICIENT...







To learn more, visit

www.ansoft.com/ansoftdesigner

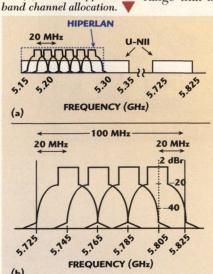
### REVIEWED PROPERTY OF THE PROPE

### TECHNICAL FEATURE

## A FULLY-INTEGRATED 5 GHz 0.18 µm CMOS VCO FOR 802.11A WLAN APPLICATIONS

This article presents a fully-integrated 5 GHz CMOS voltage-controlled oscillator (VCO) for a U-NII band 802.11a WLAN application. The VCO core circuit uses only PMOS fabricated with the 0.18  $\mu m$  1P6M standard CMOS process to obtain better phase noise performance since PMOS has a lower 1/f noise level than NMOS. The circuit measurement is performed using an FR-4 PCB test fixture. The power consumption of the VCO, excluding buffer amplifiers, is 8.1 mW at  $V_{DD}$  = 1.8 V. The output frequency of the VCO varies from 5860 to 6026 MHz giving a 166 MHz tuning range. The phase noise is -95.6 dBc/Hz at a 300 kHz offset.

Fig. 1 IEEE 802.11a and HIPERLAN frequency allocations; (a) 802.11a and HIPERLAN overlap, and (b) 802.11a upper sub-



ue to the fast growing demand for broadband wireless communications, the operating frequency is moving toward the 5 GHz U-NII band. With a maximum data rate of 54 Mbps, the IEEE 802.11a wireless LAN (WLAN) standard specifies a 300 MHz allocation of spectrum in the 5 GHz range that is divided into three sub-bands, as

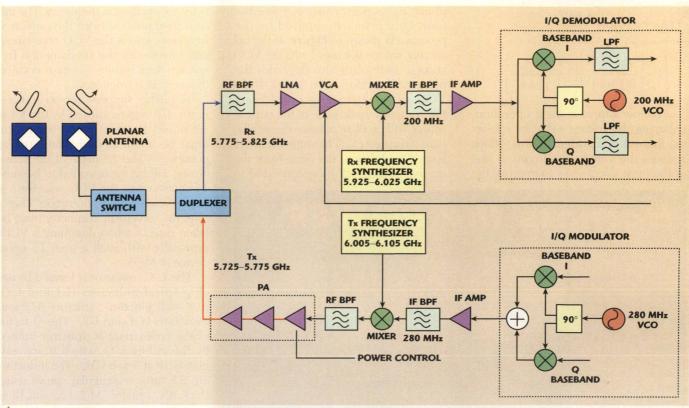
shown in *Figure 1*. The lower and middle U-NII sub-bands, from 5.15 to 5.35 GHz, accommodate eight channels in a total bandwidth of 200 MHz. The 100 MHz bandwidth of the upper U-NII band, from 5.725 to 5.825 GHz, accommodates four channels. The 100 MHz lower U-NII band is restricted to a maximum power output of 40 mW, and the middle and upper sub-bands are restricted to 200 and 800 mW, respectively. The 802.11a WLAN frequency allocation overlaps with HIPER-LAN from 5.15 to 5.3 GHz.

The proposed heterodyne transceiver architecture for an

802.11a WLAN application (5.725 to 5.825 GHz) is shown in *Figure 2*. In the receive mode, the RF (5.725 to 5.825 GHz) is down-converted to a 200 MHz IF with a high side LO (5925 to 6025 MHz). In addition, the center frequency is translated to zero by a 200 MHz LO to produce the I and Q baseband components. In the transmit mode, the I and Q baseband signals are first upconverted to 280 MHz and combined together, and then upconverted to RF by a 6.005 to 6.105 GHz LO.

The advantage of combining baseband and the RF front-end on one single chip for cost savings is strongly desired for highly integrated systems-on-chip (SOC) applications. Recently, many RF circuits realized in the CMOS process have been reported and the 0.18  $\mu$ m process is a good candidate for highly integrated SOC applications. The requirements of low power and low cost push the trend toward a single radio chip. A fully-integrated voltage-

YUAN-KAI CHU AND HUEY-RU CHUANG National Cheng Kung University Taiwan, ROC



▲ Fig. 2 Transceiver architecture for an 802.11a WLAN upper sub-band application.

controlled oscillator (VCO) is one of the most important and challenging

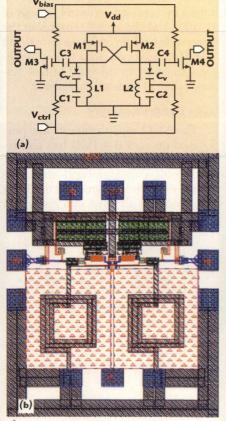


Fig. 3 A 5 GHz L-C tank CMOS VCO's (a) circuit schematic and (b) layout.

building blocks in an RF transceiver. With the demand for low power and low cost, an on-chip VCO with no external components is the best choice. However, the low Q on-chip passive components such as inductors will degrade the VCO phase noise performance.

This article presents a fully-integrated 5 GHz VCO fabricated by a TSMC 0.18 µm standard CMOS process. The VCO output frequency covers the 5925 to 6025 MHz range and is applicable to the front-end receiver with an IF of 200 MHz with a high side LO.

### **CIRCUIT DESIGN**

The transistor's flicker noise (1/f) is the cause of the phase noise near the carrier with a 1/f³ shape. In the CMOS process, the transistor's 1/f noise is generally high, causing serious degradation of VCO phase noise performance. However, the PMOS 1/f noise is usually lower than for the NMOS by one order of magnitude. A low 1/f noise active port reduces not only the magnitude of phase noise in the 1/f³ and 1/f² regions, but also lowers the corner frequency between the 1/f³ and 1/f² regions. To obtain better phase noise performance, PMOS

transistors were used in the VCO core.2 The circuit and layout of the VCO, fabricated by the 0.18 µm CMOS process with a chip area of  $790 \times 1020 \, \mu m^2$  including pads, is shown in Figure 3. The Agilent Advanced Design System (ADS) is used for design simulation of the VCO. The cross-coupled connection of the PMOS transistors M<sub>1</sub> and M<sub>2</sub> form a positive feedback loop to provide negative resistance to compensate for the loss in the L-C tank circuit. The source and gate voltages of M1 and  $M_2$  are 0 V and  $V_{DD}$  (1.8 V), respectively, without any extra current source. This bias scheme reduces the transistor width requirement for the oscillation to start and maximizes the oscillator signal peak-to-peak amplitude. The supply voltage for the 0.18 um standard CMOS process is 1.8 V, which is fairly small. If the cross-coupled pair is biased via a current source, the allowable oscillator voltage swing will be further restricted and cause a poorer phase noise performance. According to the Leeson-Cutler phase noise model, the phase noise, which is the ratio of singlesideband-noise to carrier, is inversely proportional to the signal power.<sup>2</sup>

[Continued on page 76]

### TECHNICAL FEATURE

$$\mathcal{L}(\Delta\omega) = 10\log\left[\frac{1}{2}\frac{FkT}{P_2}\right]$$

$$\left\{1 + \left(\frac{\omega_0}{2Q\Delta\omega}\right)^2\right\} \left[1 + \frac{\Delta\omega_{1/f^3}}{|\Delta\omega|}\right]$$
 (1)

For low supply voltage operation, enlarging the voltage swing by removing the use of a current source, which reduces the voltage headroom, is one of the most direct ways to improve the phase noise performance, since the tank Q is primarily limited by the process. As shown in Figure 4, the tail current source not only limits the VCO voltage swing but also degrades the phase noise performance as well. If the VCO differential pair is unbalanced, the common-mode node of the current source will oscillate at twice the oscillation frequency. Through channel length modulation, the noise from the current source will be upconverted to

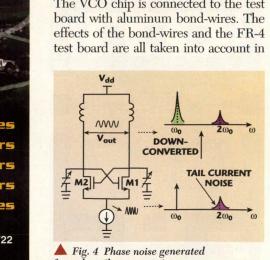
twice the oscillation frequency. The upconverted noise at twice the oscillation frequency enters the VCO core circuit and mixes with the fundamental frequency, and results in phase noise at the oscillation frequency.

To further suppress the phase noise in the 1/f3 region, caused by the MOS 1/f noise, the oscillation waveform must be made as odd-symmetric as possible.<sup>3,4</sup> The 1/f noise of the active device will be upconverted to become 1/f<sup>3</sup> noise when the VCO waveform is not sufficiently odd-symmetric. Therefore, the waveform symmetry must be taken care of when designing a VCO, especially with such a high 1/f noise device as MOS.

The L-C resonator is formed by onchip spiral inductors (L1 and L2), p+/n-well junction varactors (C<sub>v</sub>) and capacitors (C1 and C2). The Q-factor of the tank circuit is primarily limited by the inductor Q, which is approximately 10 at 5 to 6 GHz. The inductors are 2.5 turn, rectangular spirals using thick AlCu metal (Metal-6) and their inductance is approximately 2.3 nH. The series connections, C1-C, and C2-C<sub>v</sub>, resonate with L1 and L2, respectively, to determine oscillation frequency. The VCO output frequency is tuned by applying a control voltage of 0 to 1.8 V at the n-well terminal of the reverse biased junction varactors. M3 and M4 form open drain buffer amplifiers in order to drive 50  $\Omega$  test systems, such as a spectrum analyzer.

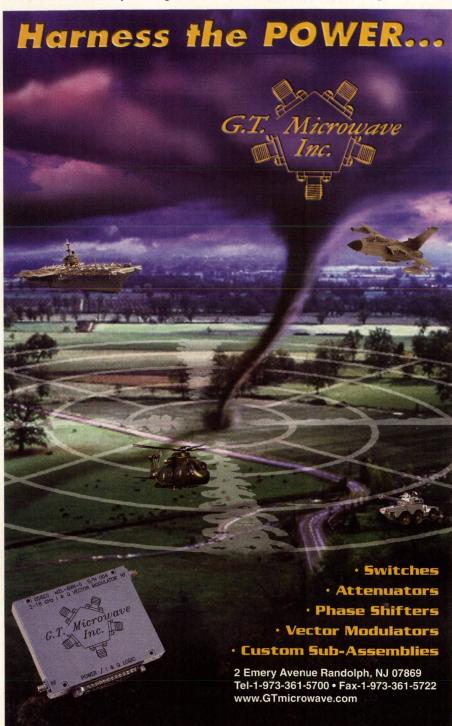
### **MEASURED RESULTS**

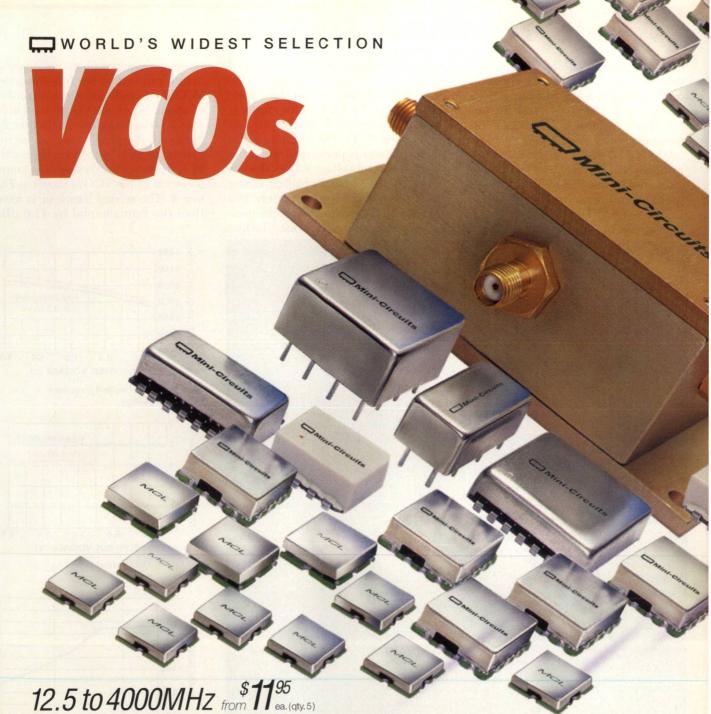
The VCO measurements are performed on an FR-4 PCB test fixture. The VCO chip is connected to the test



from the tail current noise.

[Continued on page 78]





Want a miniature surface mount, shielded plug-in, or rugged coaxial voltage controlled oscillator with the right stuff for your project? Contact Mini-Circuits! From custom designs to standard catalog models *always in stock*, we'll supply extra robust, 100% tested VCO solutions you need at a price you can afford. Choose from narrow to broad to octave band widths. Select linear tuning, low phase noise, and 5V models optimized for PLLs and synthesizers. And pick from an innovative array of miniature SM packages as small as 0.370" square for a variety of designs and applications. You can quickly find the model you need using

"The YONI Search Engine" at the Mini-Circuits web site. Just enter your specs...click...and immediately start evaluating suggested VCO solutions using the actual measured performance data displayed. But perhaps you need a custom design. Not a problem! Contact us for our lightning fast response, low prices, and quick turnaround. Give the competition real competition... specify Mini-Circuits VCOs!

New 2001 VCO Handbook...FREE!





CHICLE READER SERVICE CARD

P.O. Box 350166, Brooklyn, New York 11235-0003 (718) 934-4500 Fax (718) 332-4661 For quick access to product information see MINI-CIRCUITS CATALOG & WEB SITE

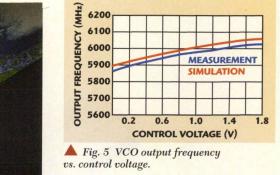
The Design Engineers Search Engine Provides ACTUAL Data Instantly From MINI-CIRCUITS At: http://www.minicircuits.com

### TECHNICAL FEATURE

the simulations. The bond-wires and the FR-4 test board do not affect the oscillation frequency and phase noise performance; they only lower the output signal amplitude. The VCO core and each buffer amplifier dissipate 8.1 mW and 22.5 mW from a 1.8 V supply, respectively. The measured oscillation frequency of the VCO is 5860 to 6026 MHz when the control voltage varies from 0 to 1.8 V. The VCO tuning range measurement and simulation results

are shown in *Figure 5*. The measured output power is approximately -4 dBm, as shown in *Figure 6*. The phase noise at a 300 kHz offset from the carrier is measured to be -95.6 dBc/Hz, as shown in *Figure 7*. The VCO phase noise measurement is performed when the applied control voltage is 0 V, which is when the VCO has its highest tuning sensitivity  $K_{vo}$  (approximately 180 MHz/V) and therefore where the measured phase noise is the worst. The free

running measured phase noise performance proves that the fully-integrated VCO is adequate for wireless communications. When the VCO is used in future 5 GHz frequency synthesizer applications, the phase noise can be further suppressed by the loop filter of the PLL frequency synthesizer. The output spectrum of the VCO is shown in *Figure 8*. The second harmonic is lower than the fundamental by 41.6 dBc,



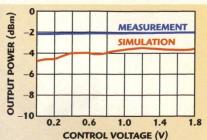
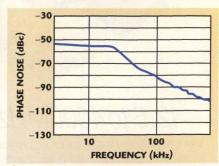


Fig. 6 VCO output power vs. control voltage.



▲ Fig. 7 Measured VCO phase noise.

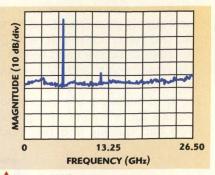
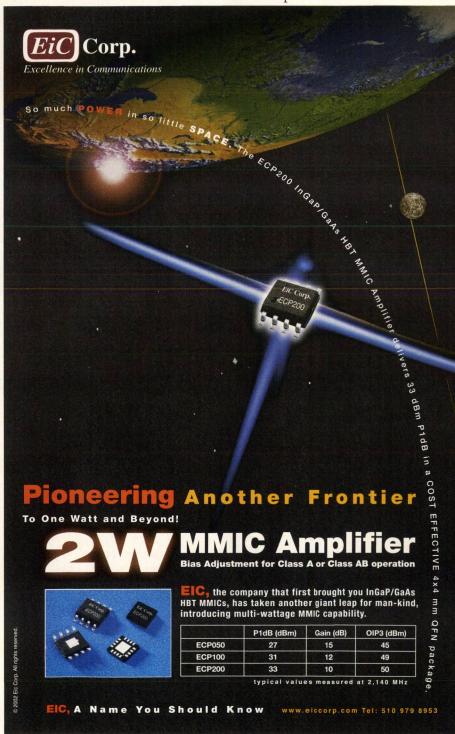
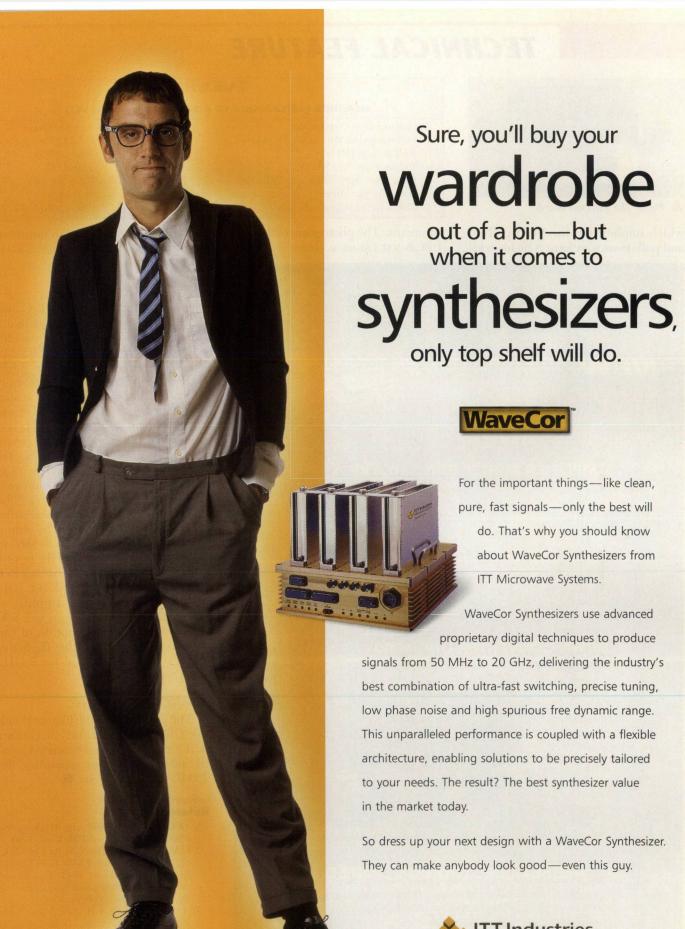


Fig. 8 VCO output spectrum.

[Continued on page 80]





### TECHNICAL FEATURE

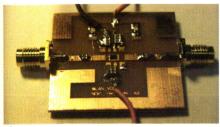


Fig. 9 The VCO test board.

which implies that the VCO pull up and pull down waveform is highly odd-

### TABLE I

### MEASURED PERFORMANCE OF A 5 GHz 0.18 µm CMOS VCO

	- circ kill civics rec
Control voltage/bias current	0 V to 1.8 V/4.5 mA
Buffer amp bias current (each) (mA)	12.5
Tuning range (MHz)	5860 to 6026
Tuning sensitivity (MHz/V)	50 to 180
Phase noise (with buffer amp) (dBc/Hz)	–95.6 @ 300 kHz
Output power (dBm)	-4
Chip area (including pads) (µm²)	$790 \times 1020$

symmetric. The photograph of the FR-4 PCB test fixture is shown in Figure

9. Table 1 summarizes the measured performance of the designed 5 GHz CMOS VCO.

### CONCLUSION

A fully-integrated 5 GHz L-C tank VCO, fabricated in a TSMC 0.18 µm standard CMOS process, is presented. Made for an IEEE 802.11a WLAN application (5.725 to 5.825 GHz), the VCO output frequency covers 5925 to 6025 MHz and is adequate for the front-end receiver application, with an IF of 200 MHz and a high side LO. The VCO core circuit uses only PMOS to achieve better phase noise performance. The VCO output frequency is tuned by on-chip p+/n-well junction varactors. The measurements are performed using an FR-4 PCB test fixture. The output frequency of the VCO is from 5860 to 6026 MHz with a 166 MHz tuning range, and the phase noise is -95.6 dBc/Hz at a 300 kHz offset. The VCO, excluding buffer amplifiers, consumes 8.1 mW at  $V_{DD} = 1.8 \text{ V}$ . The low power consumption of the VCO suggests that the 0.18 µm CMOS process is useful for 5 GHz WLAN applications.

### **ACKNOWLEDGEMENT**

The authors would like to thank the Chip Implementation Center (CIC) of the National Science Council, Taiwan, ROC, for supporting the TSMC CMOS process. ■

### Reference:

- 1. IEEE Standard 802.11a: High Speed Physical Layer in the 5 GHz Band, 1999.
- 2. C.M. Hung, B.A. Floyd, N. Park and K.K. O, "Fully-integrated 5.35 GHz CMOS VCOs and Prescalers," *IEEE Transactions* on Microwave Theory and Techniques, Vol. 49, No. 1, January 2000, pp. 17-22
- 3. A. Hajimiri and T.H. Lee, "Oscillator Phase Noise: A Tutorial," *IEEE Journal of* Solid-State Circuits, Vol. 32, No. 3, March 2000, pp. 326-336.
- 4. T.H. Lee, The Design of CMOS Radio-fre-quency Integrated Circuits, Cambridge University Press, New York, NY 1998.

### NEW

**HIGH PERFORMANCE** 26 GHz to 40 GHz LNAs & FREQUENCY CONVERTERS



### AMPLIFIER MODEL SAN-39001KK

Frequency Range: Gain: Noise: VSWR ((In & Out):

Impedance: Output IP3: Output: Connectors:

Operating Temperature: Power Supply:

MTBF @ +60°C: Module Size:

38 GHz ±1 GHz 20 dB (minimum) 3 dB (maximum) 2:1 (maximum)

50 Ω

+23 dBm (minimum) +5 dBm @ PldBGC K-Type (female) or WR28

-20°C to +70°C +3VDC @ 80 mA (maximum)

948,385 Hours AUC 60 x 45 x 10 mm

### DOWN CONVERTER UDC-40001 Input Frequency: 30 GHz - 40 GHz (±1 GHz)

IF Frequency: IF RF Gain: Gain Flatness: Input IP3: Image Rejection: RF Return Loss: LO Return Loss: IF Return Loss: Connectors: MTBF @ +60°C: Module Size:

1.5 GHz (typical) 12.5 dB (minimum) 1.5 dB (maximum) -11.5 dB (minimum) 27 dBm (minimum) 11 dB (minimum) 14 dB (minimum) 20 dB (minimum)

K-Type (female) or WR28 520, 284 Hours AUC 70 x 35 x 17 mm

ISO 9001 ■ DC TO 40 GHz AMPLIFIERS ■ UP/DOWN FREQUENCY CONVERTERS # FREQUENCY SYNTHESISERS # PHASE SHIFTERS

### **WESSEX ELECTRONICS LIMITED**

114-118 NORTH STREET ■ DOWNEND ■ BRISTOL BS16 5SE ■ UK Web: www.wessexelectronics.co.uk ■ Email: Sales@wessexelectronics.co.uk Phone: (0117) 957 1404 Fax: (0117) 957 3843 (Int Fax: 44 117 957 3843)

### DYNAMIC MICROCIRCUITS DIVISION

20 Woodward Avenue ■ Westerleigh Business Park ■ Yate ■ Bristol BS37 5YS, UK

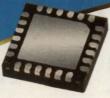
### VCOS & DIVIDERS

GAAS HBT MMICS FOR SYNTHESIZERS TO 40 GHZ

HMC431LP4

VCO + Buffer Amp 5.5 - 6.1 GHz F +3V @ 27mA 4x4mm LPCC





HMC432, 433, 434 ÷ 2, 4 or 8 DC - 8 GHz Fin +3V Bias SOT26 Package



Low Power VCOs FROM

@ 10K PCS

+3V DIVIDERS FROM

@ 10K PCS

Standard Product Plastic SMT MMIC VCOs\* NO EXTERNAL COMPONENTS REQUIRED!

Standard Product Plastic SMT Dividers\*

Part Number	Output Freq. (GHz)	Phase Noise @ 100K Offset	VCO Output Power (dBm)	USD @ 10K PCS	Part Number	Freq. (GHz)	Divide Ratio	Phase Noise @ 100K Offset	USD @ 10K PCS
HMC430LP4	5.0 - 5.5	-103 dBc/Hz	+2	\$7.00	HMC432	DC - 8.0	2	-148 dBc/Hz	\$2.21
HMC431LP4	5.5 - 6.1	-102 dBc/Hz	+2	\$7.00	HMC364S8G	DC - 12.5	2	-145 dBc/Hz	\$5.25
1114005014000	50.00	-110 dBc/Hz	A 2 May /	Selector.	HMC437MS8G	DC - 8.0	3	-148 dBc.Hz	\$8.94
HMC358MS8G	5.8 - 6.8	(at C-band)	+11	\$5.63	HMC433	DC - 8.0	4	-150 dBc/Hz	\$2.48
1111010100100	100 105	-105 dBc/Hz	c la long la se		HMC365S8G	DC - 13.0	4	-151 dBc/Hz	\$5.25
HMC401QS16G	13.2 - 13.5	(at Ku-band)	-7	CALL	HMC438MS8	DC - 8.0	5	-150 dBc.Hz	\$8.94
		-110 dBc/Hz	man 1	de la constante de la constant	HMC434	DC - 8.0	8	-150 dBc/Hz	\$2.77
HMC398QS16G	14.0 - 15.0	.0 - 15.0 (at Ku-band)	+6.0	CALL	HMC363S8G	DC - 12.0	8	-153 dBc/Hz	\$5.25

\*SELECT PRODUCTS AVAILABLE IN DIE FORM. ALL DATA IS MID-BAND TYPICAL.

Contact us to discuss your custom VCO ASIC & PLO Module requirements!

**ACTUAL SIZE** 

SOT26 9mm<sup>2</sup>

14 8mm





QS16









29.4mm



16mm<sup>2</sup>



**ORDER ON-LINE:** 



**Corporate Headquarters** 

12 Elizabeth Drive, Chelmsford, MA 01824

HMC Europe, Ltd. Ph +44(0) 1256-817000 Fax +44(0) 1256-817111 europe@hittite.com HMC Deutschland GmbH Ph +49 8031-97654 Fax +49 8031-98883 germany@hittite.com HMC Asia Co., Ltd. Ph +82-2 559-0638 Fax +82-2 559-0639 asia@hittite.com



www.hittite.com

Distributed in the Americas and Asia by Future Electronics Ph (800) Future-1, ext. 2754 Americas & ext. 5284 Asia www.futureelectronics.com/n

### TECHNICAL NOTE



## A MEASUREMENT-BASED BEHAVIORAL MODEL FOR I/Q RF MODULATORS

This article describes a nonlinear behavioral modeling technique for application to I/Q modulated communication channels. The model data was gathered by independent measurements of an I/Q modulator and amplifier, using vector signal generators and analyzers. Concatenating the models in simulation and verifying by measurement validated the technique. The method was applied to a W-CDMA transmit chain. The resulting error vector magnitude (EVM) and adjacent channel leakage ratio (ACLR) levels predicted by simulation closely matched the measurements.

The W-CDMA standard expresses transmit quality in terms of EVM and ACLR, and receive quality in bit error ratio (BER). These quality measurements are simple scalar numbers representing a very complicated system. Modern communications channels (still) consist of a number of concatenated functions such as baseband (BB) processor, DAC, modulator and amplifier. Each function contributes to the global figure of merit. A method needs to be found to capture the performance of each block in a behavioral model that, when concatenated, gives useful and accurate information on the overall system performance. The behavioral model of each block may be generated either from precise (circuit-based) simulation or by measurement.

An advantage of a behavioral model is the more compact representation it provides for a circuit, allowing the circuit to be simulated much more quickly, using less memory. This makes it more desirable for doing higher level circuit or system design. Since a component can be treated as a block and an equivalent circuit structure does not need to be known, it is potentially easier to generate a behavioral model than a circuit model. Another advantage is that a component vendor can supply a behavior

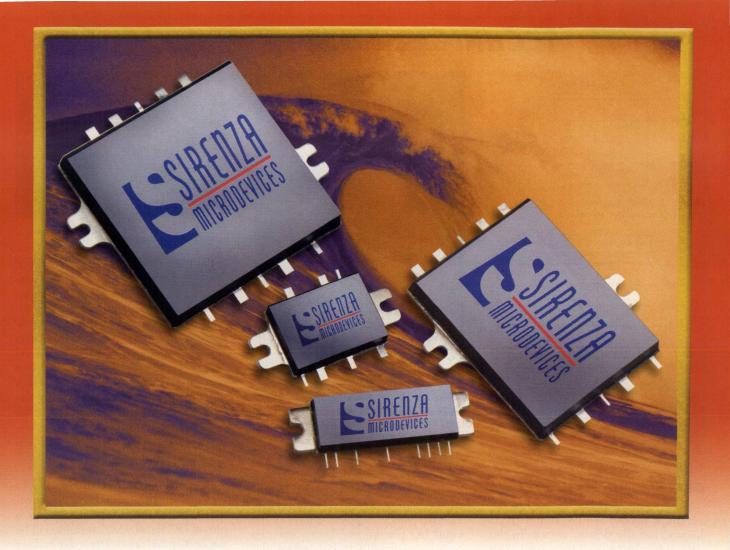
model to designers without giving away any information about the details of the device.

Behavioral models based on circuit simulation are limited to the accuracy of the underlying circuit model. However, a behavioral model may be based on measurements of the component, and has the advantage of capturing the actual nonlinear performance of the device. In order to get models that are of more general purpose, the devices need to be measured with a more complex stimulus to more fully characterize their nonlinear behavior. Electronic signal generators (ESG) and vector signal analyzers (VSA) can be used to generate these complex test signals, and capture the complex modulated response, from which the data to populate a behavioral model may be obtained.

This article extends the concept of behavioral modeling by creating a model structure for baseband I/Q-to-RF modulators, along with using real-world measurements as a method for filling in the data for such a model.

[Continued on page 84]

JOEL DUNSMORE, GREG JUE AND JOHN KIKUCHI Agilent Technologies Santa Rosa, CA



### **More Power to You**

### Sirenza adds integrated power modules to its comprehensive RF component line

Xemod is now part of Sirenza Microdevices. As the originator of 'plug-n-play' high-power solutions for linear power-amplifier designs, Xemod extends Sirenza's power-component product line to significantly higher power levels and operating voltages for wireless network-equipment applications.

Xemod originated the QuikPAC® line of matched modules for use as pre-drivers, drivers, and output stages in wireless power amplifiers. QuikPAC modules are offered in one- and two-stage configurations for medium-power (10–35 W) and high-power (60–200 W) applications. The module sizes are standardized so designers can easily design for multiple platforms with the same or similarly dimensioned modules.

Ramp-up times from design concept through production are

drastically reduced and time-to-market is greatly improved. As a result, the QuikPAC module significantly reduces design and manufacturing costs.

QuikPAC module features:

- Power levels between 10 and 200 Watts
- One- and two-stage configurations
- Discrete silicon LDMOS transistor technology
- Designed for 50-ohm systems
- No RF stage alignment and tuning
- Improved automated assembly
- No complex matching and bias circuitry

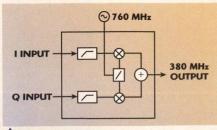
Contact Sirenza today to find out how its new integrated power products can satisfy your transmit-side power amplifier requirement.



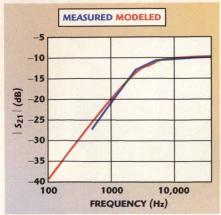
For more information, visit us at www.sirenza.com • 800.764.6642

© Copyright 2002 Sirenza Microdevices, Sirenza Microdevices, Xemod and QuikPAC are registered trademarks of Sirenza Microdevices. Other trademarks are the property of their respective holder. All rights reserved.

### TECHNICAL NOTE



▲ Fig. 1 Block diagram of the I/Q modulator model.



A Fig. 2 Frequency transfer function of I input to RF power out.

### **GRAY BOX MODELING**

The term "gray box" is used to describe a model whose structure is known, but the details are not. In this case, it is assumed that the model maps I/Q inputs to modulated RF outputs, and the model details the transfer function. In this model, the linear distortion effects (such as filtering) are separated from the nonlinear distortion effects. Thus, the behavioral model for the nonlinear effects is required to be

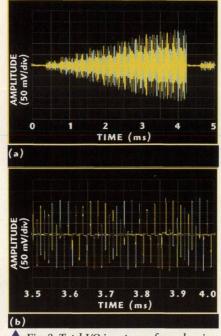


Fig. 3 Total I/Q input waveform showing steps in I/Q magnitude; (a) total range and (b) close up of the last 10 percent of the waveform.

memory-less. A memory-less assumption also implies a flat frequency response, and no PM-to-AM conversion. The frequency response effects of the input I/Q filtering will be represented by a linear frequency dependent element before the nonlinear element.

Figure 1 shows the behavioral model for the modulator. The I/Q input filters (which are caused by DC blocks and baluns in the test fixture) were evaluated using an ESG that has an arbitrary waveform generator

(AWG) for the baseband I/Q signals. A stepped sine wave was created for each of the I/Q inputs, and the output RF power measured on a VSA. Figure 2 shows the frequency response of the I input (Q is similar) as well as the modeled response for a filter function used in the behavioral model.

What is desired for the nonlinear transfer function is a function that describes the RF output amplitude and phase as a function

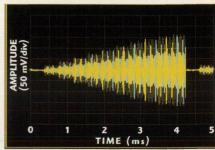


Fig. 4 Output response showing compression at higher I/Q drive levels.

of the I and Q voltages. A simple way of doing this might be to drive a DC voltage into I, and measure the RF output (magnitude and phase) for various input levels, then repeat the same measurement for Q. However, I and Q may have some interaction, so the next level of stimulus to consider is setting I to a particular level, then vary Q over a range of values, while measuring the RF output; this would be repeated for a variety of I values. Unfortunately, from the I and Q input response, it is clear that the response goes to zero at DC (the I and Q are DC blocked).

A specialized drive of I and Q to measure the transfer function is required. After much experimentation, a pulsed DC signal was determined to be the best-suited drive. The magnitude of I and Q,  $(M = \sqrt{(I^2 + Q^2)})$ , is held constant and the phase is changed in 170° increments until 36 data points (every 10°) is obtained. By changing the phase 170°, any charging of the blocking capacitor is nearly removed by the next pulse. Figure 3 shows the input signal, as measured on a VSA using the I/Q baseband inputs. The pulse was filtered to maintain a frequency content consistent with a W-CDMA signal, using a low pass filter of 2 MHz bandwidth. The spacing between pulses was set to allow any residual charge to leak off before the next pulse arrived. The last part of the stimulus is shown expanded, with I in yellow and Q in blue.

Figure 4 shows the output of the modulator, measured on a VSA using the RF input. The output modulated I/Q is compared to the input, and a transfer function is determined. This transfer function is used to populate a behavioral model that relates the input I/Q (magnitude and phase) to the output RF envelope. Figure 5 shows the behavioral model data used as an input to the simulation. A behavioral

[Continued on page 87]

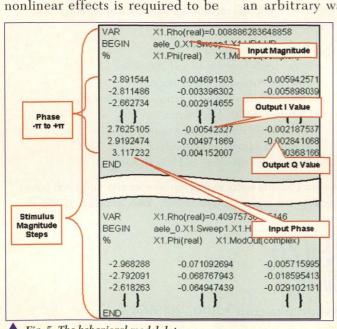


Fig. 5 The behavioral model data.

### Moderate & Octave Band Amplification



MODEL NUMBER	FREQ. (GHz)	GAIN (dB, Min.)	GAIN FLATNESS (±dB, Max.)	NOISE FIGURE (dB, Max.)	IN/OUT VSWR	POWER OUT (dBm, Min.)	CURRENT (mA, Typ.)
AFD2-010020-14-SP	1-2	20	1.50	1.4	2.0:1	+10	100
AFD3-010020-14-SP	1-2	34	1.25	1.4	2.0:1	+10	120
AFD3-022023-12-SP	2.2-2.3	30	0.50	1.2	1.5:1	+10	100
AFD3-023027-12-SP	2.3-2.7	30	0.50	1.2	1.5:1	+10	125
AFD3-027031-12-SP	2.7-3.1	30	0.50	1.2	1.5:1	+10	125
AFD3-031035-12-SP	3.1-3.5	30	0.50	1.2	1.5:1	+10	125
AFD3-037042-12-SP	3.7-4.2	30	0.50	1.2	1.5:1	+10	125
AFD3-040080-35-SP	4-8	24	1.25	3.5	2.0:1	+10	150
AFD3-020080-40-SP	2-8	23	1.50	4.0	2.0:1	+10	160
AFD3-040120-55-SP	4-12	18	1.50	5.5	2.0:1	+10	150
AFD3-080120-50-SP	8–12	18	1.25	5.0	2.0:1	+10	150
AFD1-010020-23P-SP	1–2	11	1.00	4.0	2.0:1	+23	200
AFD2-010020-23P-SP	1-2	25	1.50	3.5	2.0:1	+23	325
AFD3-020027-23P-SP	2.0-2.7	22	1.25	4.5	2.0:1	+23	350
AFD3-027031-23P-SP	2.7-3.1	22	1.25	4.5	2.0:1	+23	400
AFD3-031042-23P-SP	3.1-4.2	22	1.25	4.5	2.0:1	+23	350
AFD3-040080-23P-SP	4-8	20	1.25	5.5	2.0:1	+23	350
AFD3-020080-20P-SP	2-8	18	1.50	6.0	2.0:1	+20	350
AFD3-080120-20P-SP	8-12	15	1.25	5.0	2.0:1	+20	350
AFD3-040120-18P-SP	4-12	15	1.75	6.5	2.0:1	+18	350
Note: All specifications gr	uaranteed at	+23°C.					

For additional information, please contact Naseer Shaikh at (631) 439-9295 or nshaikh@miteq.com



100 Davids Drive, Hauppauge, NY 11788 TEL (631) 436-7400 • FAX (631) 436-7430

miteq.com

### DTI TECHNOLOGY FOR ALL YOUR SWITCHES



A I R B O R N E

M I S S I L E

High Performance

WIRELESS

Cell Site Systems

30 dB Attenuation

A

SPIOT

DUCOMMUN TECHNOLOGIES, INC.

vharter@ductech.com www.ductech.com Click LEADnet at mwjournal.com or Circle 21 on Reader Service Card

(310) 513-7200

### TECHNICAL NOTE

model simulation was created and the original pulsed input was used as a simulation stimulus. The response produced an output nearly identical to the measured output. Next, the model was stimulated with a W-CDMA signal, and the EVM response was obtained. As shown in Figure 6, there was remarkable agreement with an actual measurement of EVM on the modulator. A similar process was used to characterize an RF amplifier, with the characterization consisting of measuring the amplitude and phase compression from which a behavioral model of the amplifier was created.

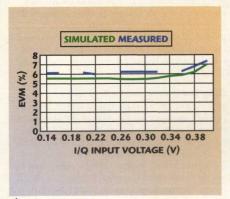


Fig. 6 EVM comparison between measured and simulated data.

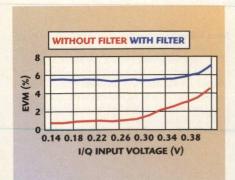
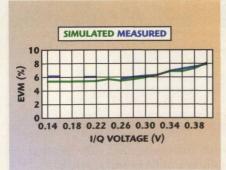


Fig. 7 Simulated EVM with and without filter.



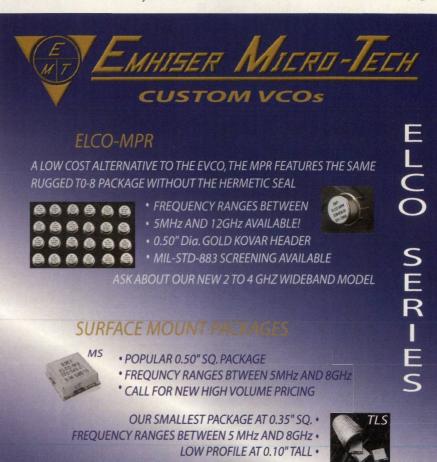
▲ Fig. 8 EVM of modulator and amplifier cascade.

The DC blocking of the I/Q is a result of the test fixturing. The goal was to determine the response of the modulator without the DC block, but such a measurement was not possible. However, the filtering function in the simulator could be de-embedded, and a complex modulation signal applied to the resulting model. *Figure* 7 shows the result of this experiment. The DC block has a strong effect on EVM, and it can be clearly seen that

the degradation of EVM of the modulator, although small, occurs at a much lower input drive that the preceding figure would indicate.

Finally, the modulator and amplifier were cascaded, both physically and in the simulation, and the measured and simulated EVM of the cascaded pair was compared. *Figure 8* shows

[Continued on page 88]





SK ABOUT OUR OTHER SURFACE MOUNT PACKAGES

LARGER FOOTPRINTS AND LOWER

PROFILE VERSIONS ARE AVAILABLE

TAPE AND REEL AVAILABLE FOR MOST SURFACE MOUNT PACKAGES



P.O. BOX 708
VERDI, NV. 89439
E-MAIL: VCO@EMHISER.COM
WWW.EMHISER.COM/VCO

CONTACT US TODAY WITH YOUR SPECIFICATION NEEDS!!

### TECHNICAL NOTE

this result. Similar comparisons were done for other modulated characteristics such as adjacent channel power ratio (ACPR) and alternate channel power ratio, with good results.

### CONCLUSION

For the first time, a method for creating measurementbased behavioral models has been presented as related to I/Q modulators. The model was validated using measurements of W-CDMA signals. Furthermore, the cascading of behavioral models was tested against a modulator and amplifier combination, and found to correctly predict the response to a complex modulated signal.

### References

- 1. Connected Simulation and Test Solutions Using the Advanced Design System, Agilent Technologies, Application Note Number 1394, Lit Number 5988-6044EN.
- "3GPP W-CDMA Systems: Design and Test," IEEE Microwave Magazine, June 2002; http://ieeexplore.ieee.org/iel5/6668/ 21676/01004052.pdf.
- 3. "The State of Wireless Networking Simulation and Verification," Applied Microwave and Wireless; www.amwireless.com/ archives/2001/v13n12/v13n12pg106.pdf.
- 4. The Design and Verification of IEEE 802.11a 5 GHz Wireless LAN Systems; http://www.chipcenter.com/networking/images/technote/ technote019.pdf.
- Blending Test Equipment into the Design Mix to Generate Custom, Real-world Waveforms (cdma2000); http://www.chipcenter.com/networking/technote/Agilent\_Wave\_Synth/.

### **MICROWAVE CONNECTORS** & CABLE ASSEMBLIES...



- 6. Terminal Conformance Specification; Radio Transmission and Reception (FDD) (Release 1999), 3GPP Technical Specification 34.121, v3.0.0 (2000-3); http://www.3gpp.org.
- 7. Agilent Solutions for Designing and Manufacturing Base Transceiver Stations and Their Components; http://www.agilent.com/find/
- 8. Agilent Solutions for Designing and Manufacturing Wireless Appliances; http://www.agilent.com/find/wirelessdesign.
- Agilent 3G Application Notes; http://www.agilent.com/find/3G.
   Agilent ADS Training Class: Designing W-CDMA/3GPP Communication Systems Using ADS; http://contact.tm.agilent.com/tmo/ eesof/education/



Joel Dunsmore received his BSEE and MSEE degrees from Oregon State University in 1982 and 1983, respectively. He is currently a senior design engineer working as a solution architect for the Component Test Market Solutions unit of Agilent Technologies (formerly Hewlett-Packard) at the Sonoma County site. He was a principle contributor to the HP 8753 and HP 8720 family of network analyzers, responsible for RF and microwave circuit designs in these products. He holds six patents related to this work, has published numerous articles on measurement

technology, and consults on measurement applications. He has taught electrical circuit fundamentals and presented several short courses and seminars through ARFTG, MTT and HP.



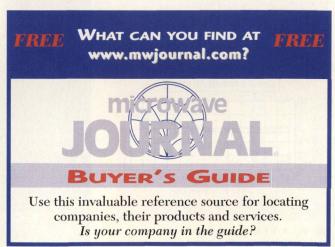
Greg Jue is a communications system application specialist at Agilent EEsof. He is the product manager for the ADS 3GPP W-CDMA design library, and also specializes in ADS links to Agilent test equipment. He created the ADS 3GPP W-CDMA course and ADS

Communications System Design course, and has taught numerous RF circuit design, communications system design and 3GPP W-CDMA design courses using ADS. He has been with Agilent EEsof for six years, and was at the Jet Propulsion Laboratory/Caltech University

working on system design for the Deep Space Network prior to joining Agilent Technologies.



John Kikuchi graduated from the University of California at Berkeley School of Engineering in 1979. He then joined the US Air Force as a research engineer. He is currently a solution planner for the Wireless Business Unit of Agilent Technologies, where he has worked since 1983. His experience at Agilent also includes work in R&D, QA, and, most recently, sales and marketing for Agilent EEsof EDA.





Electrically: There is almost no difference, compared to our straight connectors. We are having the most advanced tools available to always design state-of-the-art connectors.

Mechanically: They are small! And if we say small, we mean small! They are only as big as the connector series requires! We do not sell connectors by the pound! We design connectors

The management philosophy at Spectrum Elektrotechnik GmbH is based upon the innovative concept of "Entrepreneurship". A group of individuals act as a creative team within the corporate structure. Each team specializes in a particular product and completely understands and manages one of the product families. Spectrum Elektrotechnik GmbH has adopted the entrepreneurial system for one simple reason: Customer satisfaction. The effort of undivided attention is addressed to each single product, from design to manufacturing. No compromises are made, no details are overlooked. The team remains most alert to all customer requirements and is able to maintain complete communication with the customer. The result is complete understanding. Understanding begins already as the team studies the specifications. Goals are identified, a course is plotted. Questions are answered before they become problems; doubts are clarified before they are misunderstood. The team pilots each project through design, manufacturing and testing, until the ultimate objective is achieved: A quality product on time.

Please visit us @ www.spectrum-et.com



### **ANTENNAS**

Chuang, Huey-Ru, Liang-Chen Kuo, Chi-Chang Lin and Wen-Tzu Chen

A 2.4 GHz Polarization-diversity Planar Printed Dipole Antenna for WLAN and Wireless Communication Applications," No. 6, p. 50.

Gunnels, Robert

"Axial Ratio Measurements of Single Circularly Polarized Antennas," No. 1, p. 124.

Izadian, Jamal S.

'QFHA Antennas for Satellite Radio and Mobile Phone Applications," No. 7, p. 64.

Jang, Yong-Woong

Characteristics of a Large Bandwidth Rectangular Microstrip-fed Inserted Triangular Patch in a Circular Slot Antenna," No. 5, p. 288.

Jang, Yong-Woong, Jeong-Chull Yoon and Ho-Sub Shin

'A Large Bandwidth T-shaped Microstrip-fed Ground Plane Slot Antenna," No. 1, p. 92.

"Design of Wideband Patch Antennas for PCS and IMT-2000 Service," No. 7, p. 78.

Mathian, M., E. Korolkewicz, P. Gale and E.G. Lim

"Design of a Circularly Polarized 2 × 2 Patch Array Operating in the 2.45 GHz ISM Band," No. 5, p. 280.

Walker, Chris

"The Development of Wide Angle Base Station Antennas from Arrays," No. 7, p. 88.

Willey, Keith

Antenna Selection to Minimize Pointing Requirements," No. 1, p. 114.

### CAD/CAM

Blackwood, Charles

"Balancing the Budgets: The Importance of Dedicated Software for System Design," No. 11,

Borjak, Assaad and Taoufik Bourdi

"Intermodulation Products for a Mixer Subjected to a Multi-carrier Signal," No. 2, p. 130.

Dunsmore, Joel, Greg Jue and John Kikuchi

'A Measurement-based Behavioral Model for I/Q RF Modulators," No. 12, p. 82.

Faria, Daniel, Lawrence Dunleavy and Terje Svensen

"The Use of Intermodulation Tables for Mixer Simulations," No. 4, p. 60.

Maas, Stephen A.

"Fixing the Curtice FET Model," No. 3, p. 68.

Maas, Stephen A. and Ted Miracco

Using Load Pull Analysis and Device Model Validation to Improve MMIC Power Amplifier Design Methodologies," No. 11, p. 20.

Vye, David

Performing Transient Analysis on PLL Frequency Synthesizers," No. 1, p. 62.

Weller, Tom, David Markell, John Capwell and Vivi Cojocaru

'Considerations in Capacitor-pairing to Obtain Nonstandard Part Values," No. 11, p. 68.

Zhu, Yu, Jason Gerber and Qian Cai

'Simulating Multi-finger Power HBTs," No. 3, p. 96.

### **COMMERCIAL APPLICATIONS**

Bernardo, Robert P.

"SAW Voltage-controlled Oscillators," No. 9, p. 166.

### **COMPONENTS/SUBSYSTEMS**

Bahl, Inder J.

"Design of a Generic 2.5 W, 60 Percent Bandwidth, C-band MMIC Amplifier, No. 8, p. 54.

Chu, Yuan-Kai and Huey-Ru Chuang
"A Fully-integrated 5 GHz 0.18 µm CMOS
VCO for 802.11a WLAN Applications," No. 12, p. 74.

Devoe, Lambert and Alan Devoe

"Technology and Innovation in Single Layer Capacitors," No. 2, p. 144.

Han, Yongin and Ihn S. Kim

'Practical Design Consideration of a Modified Structure for a Planar Multiport Power Divider at 2 GHz," No. 11, p. 102.

Hwang, Hee-Yong, Sang-Won Yun and Joong-Sung Chung

A New Type of Amplitude Equalizer for In-band Flatness Improvement," No. 2, p. 116.

Jang, Byung-Jun, In-Bok Yom and Seong-Pal Lee 'Q- and V-band MMIC Low Noise Amplifiers," No. 6, p. 74.

Jeong, Yong-Chae

"A Feedforward Power Amplifier with Loops to Reduce RX Band Noise and Intermodulation Distortion," No. 1, p. 80.

Kim, Dong-Wook, In-Ho Jeong and Jong-Soo Lee Passive Miniaturization: Si Integrated Passive Devices for RF and Microwave Applications," No. 11, p. 78.

Kim, Ihn S., Chisung Jo and Yongin Han 'Output Power Improvement of a Push-push FET DRO by Using an Additional DR, No. 4, p. 104.

Sato, Tetsuo and Chris Grigorean

Design Advantages of CDMA Power Amplifiers Built with MOSFET Technology," No. 10, p. 64.

Seo, Munkyo, Joo-Yeol Lee, Kyung-Kuk Lee and Sangwook Nam

'A Varactor-tuned Oscillator with Linear Tuning Characteristic," No. 2, p. 100.

Shigematsu, H., M. Sato, T. Hirose and Y. Watanabe

"A Distributed Amplifier for 40 Gbps Fiber-optic Communications Systems," No. 4, p. 78.

Sun, Jwo-Shiun and Guan-Yu Chen

'A New Planar Coupled-line Balun for Microwave Applications," No. 5, p. 306.

Wang, Xudong, Dawn Wang, Chris Masse and Peter Bacon

"Low Phase Noise SiGe Voltage-controlled Oscillators for Wireless Applications," No. 2, p. 84.

Yue, Jerry and Jeff Kris

"SOI CMOS Technology for RF System-on-chip Applications," No. 1, p. 104.

### **COVERS**

CST of America Inc.

"A Revolution in the Time Domain," No. 8, p. 82.

Eagleware Corp.

'A Complete Spectral System Analysis for RF/Microwave Engineers," No. 3, p. 122.

**EMC Technology Inc.** 

"Temperature Variable Attenuator for Millimeterwave Applications," No. 4, p. 108.

Hittite Microwave Corp.

"Active Multipliers and Dividers to Simplify Synthesizers," No. 11, p. 118.

### EDITORIAL INDEX 2002 • Volume 45

M/A COM

"2.5 V GaAs pHEMT Switches for GSM Handsets," No. 1, p. 172.

MIG, Microwave Innovation Group

A CAD Tool Utilizing Fast Hybrid MM/FE/MoM/FD Techniques," No. 9, p. 178.

Mini-Circuits

'An LTCC Double-balanced Mixer," No. 10, p. 100.

**RF Micro Devices** 

A High Gain Power Amplifier with Variable Bias for Multi-mode WCMDA Applications," No. 2, p. 154.

Rogers Corp.

Diclad Liquid Crystalline Polymer Circuit Material for Multilayer PCBs," No. 7, p. 96.

United Monolithic Semiconductors S.A.S.

"Low Cost Millimeter-wave Packaged MMICs," No. 6, p. 100.

Unity Wireless Systems Corp.

"A Minimalist Approach to Feedforward Multicarrier Linear Power Amplifiers," No. 12, p. 94.

### **DESIGN**

Debaillie, B., B. Come, W. Eberle, S. Donnary and H. Minami

System-level Filter Design Methodology for WLAN-OFDM Transceivers," No. 5, p. 268.

Hausman, Howard

"Topics in Communication System Design: Carrier Triple Beats," No. 1, p. 20.

Hwang, Hee Yong and Sang-won Yun

The Design of Bandpass Filters Considering Frequency Dependence of Inverters," No. 9, p. 154.

Jeong, Yong-Chae and Sang-Young Yun

"Design of a Predistortive High Power Amplifier Using Carrier Complex Power Series Analysis," No. 4, p. 92.

Koupal, Bob, Marshall Wang and Cory Edelman "Designing a Bluetooth Transceiver in RF CMOS," No. 2, p. 62.

Krug, Florian and Jean Wilwert

Calculation and Measurement of Lock Time in a Phase-locked Loop Frequency Synthesizer," No. 4, p. 22.

Moghe, Sanjay

Design Considerations for Multimode Multiband WLANs," No. 9, p. 132.

Snodgrass, D.K.

"60 GHz Radio System Design Tradeoffs," No. 7, p. 50.

Staudinger, J.
"Effects of AM/AM and AM/PM Distortion on Spectral Regrowth in 3GPP W-CDMA BS Power Amplification," No. 11, p. 90.

Sundaram, K.R. and S. Sudha Rani

"Processing Techniques for Broadband DIFM Receivers," No. 6, p. 20.

Yoo, Hyung Joun and Ji-Hoon Kim

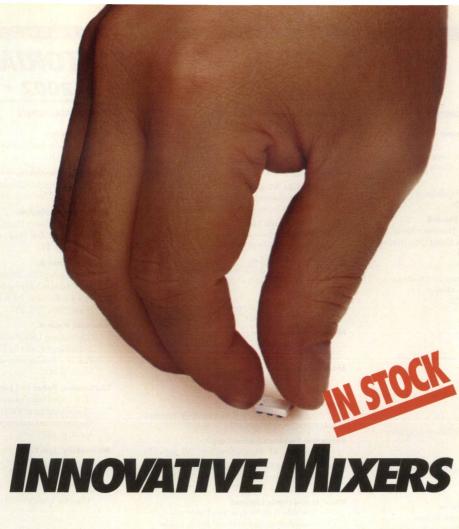
The Receiver Noise Equation: A Method for System Level Design of an RF Receiver," No. 8, p. 20.

### **DEVICE**

Rice, led

"LDMOS Linearity and Reliability," No. 6, p. 64.

[Continued on page 92]



### smaller size .better performance .lower cost 50kHz to 4200MHz



Searching high and low for a better frequency mixer? Then take a closer look at the innovative Innovative Technology built into Mini-Circuits technology ADE mixers. Smaller size is achieved using an

ultra-slim, patented package with a profile as low as 0.082 inches (2mm) in height. Electrically, ADE mixers deliver better performance than previous generation mixers through all welded connections with unique assembly construction which reduces parasitic inductance. The result is dramatically improved high frequency and IP2-IP3 performance. Plus, ADE's innovative package design allows water

wash to drain and eliminates the possibility of residue entrapment. Another ADE high point is the lower cost...priced from only \$1.99 each. So, if you've been searching high and low for a mixer to exceed expectations...ADE is it



ADE Mixers...Innovations Without Traditional Limitations!

ADE* TYP	ICAL SI	PECIFICATION					
MODEL L	O Power (dBm)		Conv. Loss Midband (dB)	L-R Isol. Midband (dB)	@Midband (dBm)	Height (mm)	Price (\$ea.) Qty. 10-49
ADE-1L ADE-3L ADEX-10L	+3 +3 +4	2-500 0.2-400 10-1000	5.2 5.3 7.2	55 47 60	16 10 16	3 4 3	3.95 4.25 2.95
ADE-1 ADE-1ASK ADE-2 ADE-2ASK ADE-6 ADEX-10	+7 +7 +7 +7 +7 +7	0.5-500 2-600 5-1000 1-1000 0.05-250 10-1000	5.0 5.3 6.67 5.4 4.6 6.8	55 50 47 45 40 60	15 16 20 12 10 16	4 3 3 3 5 3	1.99▲ 3.95 1.99▲ 4.25 4.95 2.95
ADE-12 ADE-4 ADE-14 ADE-901 ADE-5 ADE-5X	+7 +7 +7 +7 +7 +7	50-1000 200-1000 800-1000 800-1000 5-1500 5-1500	7.0 6.8 7.4 5.9 6.6 6.2	35 53 32 32 40 33	17 15 17 13 15	2 3 2 3 3 3	2.95 4.25 3.25 2.95 3.45 2.95
ADE-13 ADE-11X ADE-20	+7 +7 +7	50-1600 10-2000 1500-2000	8.1 7.1 5.4	40 36 31	11 9 14	3 3	3.10 1.99▲ 4.95
ADE-18 ADE-3GL ADE-3G ADE-28 ADE-30 ADE-32 ADE-35	+7 +7 +7 +7 +7 +7 +7 +7	1700-2500 2100-2600 2300-2700 1500-2800 200-3000 2500-3200 1600-3500	4.9 6.0 5.6 5.1 4.5 5.4 6.3	27 34 36 30 35 29 25	10 17 13 8 14 15	3 2 3 3 3 3 3 3	3.45 4.95 3.45 5.95 6.95 6.95 4.95
ADE-18W ADE-30W ADE-1LH ADE-1LHW ADE-1MH ADE-10MH ADE-10MH ADE-12MH ADE-25MH	+13	1750-3500 300-4000 0.5-500 2-750 2-500 0.5-600 800-1000 10-1200 5-2500	5.4 6.8 5.0 5.3 5.2 5.2 7.0 6.3 6.9	33 35 55 52 50 53 34 45 34	11 12 15 15 17 17 26 22 18	3 3 4 3 3 4 4 3 3	3.95 8.95 2.99 4.95 5.95 6.45 6.95 6.45 6.95
ADE-35MH ADE-42MH ADE-1H ADE-1HW ADEX-10H ADE-10H ADE-12H ADE-17H ADE-20H	+13 +13 +17 +17 +17 +17 +17 +17	5-3500 5-4200 0.5-500 5-750 10-1000 400-1000 500-1200 100-1700 1500-2000	6.9 7.5 5.3 6.0 7.0 7.0 6.7 7.2 5.2	33 29 52 48 55 39 34 36 29	18 17 23 26 22 30 28 25 24	3 3 4 3 3 3 3 3 3 3	9.95 14.95 4.95 6.45 3.45 7.95 8.95 8.95 8.95
		ting area on		PC board	is 0.320"x	0.290".	

Protected by U.S. patent 6133525. \$100 piece price.







CIRCLE READER SERVICE CARD

P.O. Box 350166, Brooklyn, New York 11235-0003 (718) 934-4500 Fax (718) 332-4661 For quick access to product information see MINI-CIRCUITS CATALOG & WEB SITE The Design Engineers Search Engine Provides ACTUAL Data Instantly From MINI-CIRCUITS At: www.minicircuits.com



### **■ INSTRUMENTS/MEASUREMENTS**

### Agahi, Darioush, William Domino and Nooshin Vakilian

"Two-tone vs. Single-tone Measurement of Second-order Nonlinearity," No. 3, p. 82.

### Iglesias, Marta

"Understanding W-CDMA Modulation Quality Measurements," No. 12, p. 56.

### Lázaro, A., M.C. Maya and L. Pradell

"Measurement of On-wafer Transistor Noise Parameters Without a Tuner Using Unrestricted Noise Sources," No. 3, p. 20.

'Specifications and Definitions for Quadrature Demodulators and Receiver Design Measurements," No. 10, p. 22.

### **PRODUCT FEATURES**

### **Amplifier Research**

'A Broadband Hybrid Solid-state and TWT Amplifier," No. 9, p. 184.

### **APLAC Solutions Oy**

"A Simulation Builder for Versatile Framework Integration," No. 8, p. 94.

### Celiant Corp.

"A High Power Multi-carrier Power Amplifier," No. 2, p. 172.

### Datum Inc.

"A Modern Militarized Rubidium Frequency Standard," No. 5, p. 317.

### Dow-Key Microwave Corp.

"Internally Terminated 12-throw Electromechanical Switches for Matrix Applications," No. 7, p. 104.

### e-tenna Corp.

"Low Cost Phased Array Antennas for BWA Applications," No. 5, p. 324.

### EiC Corp.

"WCDMA Application of Gain Blocks," No. 3, p. 140.

### EiC Corp.

'A Cost-effective 2 W GaAs MMIC Amplifier Solution," No. 11, p. 130.

### IFR Systems Inc.

"An RF Signal Generator Offering Full Digital, Vector and Analog Modulation," No. 10, p. 114.

### Lamina Ceramics

"New Substrate Technology for High Performance Circuits and Systems," No. 12, p. 104.

### **LPKF Laser & Electronics**

"Laser-activateable Plastics and Laser Devices that Deliver Flexible 3D MID Technology," No. 5, p. 329.

### **LPKF Laser & Electronics**

"A Fast and Flexible Circuit Board Plotter," No. 11, p. 144.

### **Marconi Applied Technologies**

"A Graded-gap Gunn Diode Voltage Controlled Oscillator for Adaptive Cruise Control," No. 7, p. 110.

### **MCE/KDI Integrated Products**

"A Compact W-CDMA RF Front End," No. 7, p. 117.

### **MEM Research**

"An EM Simulator for MEMS and Real Life MMICs," No. 5, p. 310.

### Merrimac Industries Inc.

"A Frequency Discriminator with a Small Footprint," No. 6, p. 110.

### **MI Technologies**

'Cost-effective Wireless Antenna Measurement Systems," No. 1, p. 182.

### Micro Lambda Wireless Inc.

"An Eight-channel YIG-tuned Frequency Synthesizer Array," No. 5, p. 336.

### Micro Metalsmiths Ltd.

"A Compact Monopulse Feed for Tracking Antennas," No. 9, p. 188.

### Micromanipulator Co.

"RF/Microwave Manipulators for Precise Test Probe Measurements," No. 12, p. 108.

"An X-band, High Power, MMIC-based Microwave Amplifier," No. 2, p. 168.

### Mimix Broadband Inc.

"A Highly Linear 17 to 24 GHz SMT Power Amplifier," No. 9, p. 192.

### Modelithics Inc.

"Advanced Microwave Chip Capacitor Models," No. 1, p. 190.

### Noise Com Inc.

"Precision Eb/No Generators for BER Testing to 44 GHz," No. 11, p. 147.

### Peregrine Semiconductor Corp.

"Monolithic RF Matrix Switches," No. 4, p. 114.

### Poseidon Scientific Instruments Pty Ltd.

"A Mobile Ultra-low Phase Noise Sapphire Oscillator," No. 1, p. 188.

Racal Instruments Limited
"A Portable Base Station Installation and Commissioning Test System," No. 3, p. 134.

### Rohde & Schwarz GmbH & Co. KG

'A Handheld Spectrum Analyzer Offering High Performance from a Small Footprint," No. 11, p. 140.

### **Taconic Advanced Dielectric Division**

"A Low Loss PTFE-based Bond Ply Material for Multilayer PCB Applications," No. 5, p. 333.

**TRAK Microwave Corp.**"A Low Cost Oscillator for Fiber-optic Applications," No. 4, p. 124.

### Valence Semiconductor

"A CMOS-based Front-end Downconverter for GPS Applications," No. 1, p. 176.

### Vari-L Co. Inc.

"A New Wideband Family of Oscillators," No. 3, p. 156.

### WJ Communications Inc.

"Single- and Dual-branch Downconverter ICs for Wireless Base Station Applications," No. 10, p. 106.

### Zeland Software Inc.

"Software for Optimizing the Design and Low Cost Production of Waveguide Filters," No. 3, p. 148.

### Zeland Software Inc.

"Design of Working Filters Using Both Analytical and Numerical Tools," No. 6, p. 114.

### SPECIAL REPORTS

### Howe, Harlan Jr.

"The Old Order Changeth — Again!," No. 10, p. 20.

### Mumford, Richard

'Research@mwjournal.com," No. 9, p. 22.

### **EDITORIAL INDEX** 2002 • Volume 45

### TUTORIAL SERIES

### Colin, Dennis

"Externally Induced VCO Phase Noise," No. 2, p. 20.

### Goldberg, Bar-Giora

"Fibercom Clock Timing — A Review of PLL Solutions," No. 6, p. 86.

### Grebennikov, Andrei

"High Efficiency Class B, E and F Power Amplifiers: The Magic of Parallel Circuits," No. 12, p. 20.

### Johnson, Kent K.

"Optimizing Link Performance, Cost and Interchangeability by Predicting Residual BER: Part I - Residual BER Overview and Phase Noise," No. 7, p. 20.

### Johnson, Kent K.

"Optimizing Link Performance, Cost and Interchangeability by Predicting Residual BER: Part II - Nonlinearity and System Budgeting," No. 9, p. 96.

### Ladbrooke, Peter and James Bridge

"The Importance of the Current-voltage Characteristics of FETs, HEMTs and Bipolar Transistors in Contemporary Circuit Design," No. 3, p. 106.

### Maloratsky, Leo G.

"Reviewing the Basics of Suspended Striplines," No. 10, p. 82.

### McCune, Earl

"Gain for Compressed Amplifiers," No. 5, p. 300.

### **■ WIRELESS SYMPOSIUM AND EXHIBITION**

### 2002 Penton Wireless Systems Design **Exhibition Showcase**

No. 1, p. 156.

### 2002 Penton Wireless Systems Design Exhibitors No. 1, p. 168.

### 2002 Penton Wireless Systems Design **Show Guide**

No. 1, p. 134.

### ■ 2002 MTT-S CONFERENCE

### Bashore, Frank

"A Seattle Surprise: IMS 2002," No. 8, p. 72.

Welcome to the 2002 International Microwave Symposium," No. 5, p. 24.

### Howe, Harlan Jr.

"Attending the Conference," No. 5, p. 30.

### Zarlingo, Ben, Allison Greco and James T. Walsh 'There's No Place Like... The Emerald City,"

### No. 5, p. 40. **Washington State Convention and Trade Center** Floor Plan

No. 5, p. 182.

### 2002 IEEE MTT-S IMS Exhibition Guide No. 5, p. 74.

### 2002 IEEE MTT-S IMS Technical Program No. 5, p. 186.

### 2002 IMS Exhibitors

No. 5, p. 172.

### HIGHperformance

### Microstrip cost

### MFC. VCO & VFC Series

Microstrip resonator based offering superb phase noise performance and bandwidth from optimized to over an octave frequency generation.

Frequency range: 40 MHz to 6100 MHz

### **TFC Series**

Microstrip resonator based and miniature style package for optimized bandwidth. Frequency range: 100 MHz to 3000 MHz

### Series 5

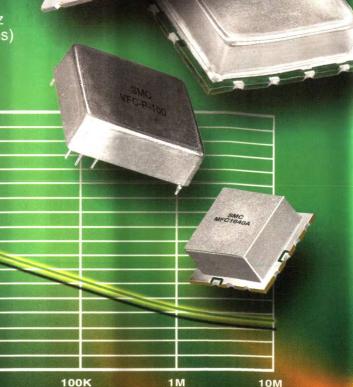
+ 0 -10 -20 -30 -40 -50 -60 -70 -80 -90 -100 -110 -120 -130 -140 -150 -160 -170 -180

100

Dual isolated output with excellent phase noise and good stability Frequency range: 50 MHz to 1000 MHz (optimized bandwidths)

Carrier: 1800.00E+6 Hz

1K

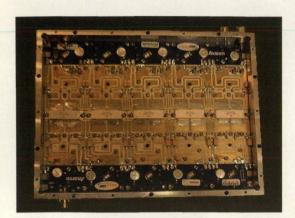


For additional information, contact Synergy's sales and application team.
201 McLean Boulevard, Paterson, NJ 07504
Phone: (973) 881-8800 Fax: (973) 881-8361 E-mail: sales@synergymwave.com
World Wide Web: www.synergymwave.com

10K



### **COVER FEATURE**



# A MINIMALIST APPROACH TO FEEDFORWARD MULTI-CARRIER LINEAR POWER AMPLIFIERS

A tmospheric propagation attenuation is known to be higher in the 2.1 GHz band than in the cellular band. Thus, to overcome this performance disadvantage and to maximize cell coverage and capacity, Unity Wireless System's first feedforward multi-carrier linear power amplifier (MCLPA) product has been designed with a high 60 W maximum

average output power. The new Tornado MCLPA has been developed to satisfy the emerging 3G W-CDMA market for applications requiring high power and high linearity at a relatively low cost.

The Tornado amplifier uses a classical adaptive control feedforward design (see Figure 1), where the main power amplifier (MPA) distortion components are extracted using carrier cancellation in Loop 1 and amplified by the error power amplifier (EPA). The output distortion is then cancelled at the error cancellation coupler in Loop 2 (the error loop).

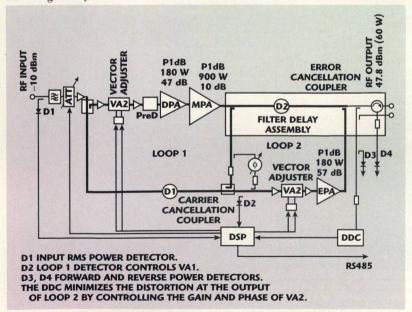
### **DIRECT DISTORTION CONTROL**

The distinguishing features of the Tornado design include a patent-pending direct distortion control (DDC) technology to control Loop 2. This technique is a low cost, ultra high selectivity, high linearity frequency tunable power detector. The DDC circuit works specifically with CDMA-type modulation schemes, including W-CDMA, cdma2000 and IS-95, and provides a number of useful advantages.

[Continued on page 96]

UNITY WIRELESS SYSTEMS CORP. Burnaby, BC, Canada

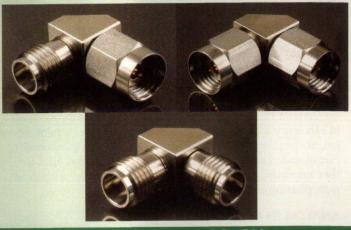
Fig. 1 The Tornado feedforward MCLPA's block diagram.



## Who has the Right Angle on RF, Microwave & Millimeterwave adapters?

2.4mm, DC to 50 GHz

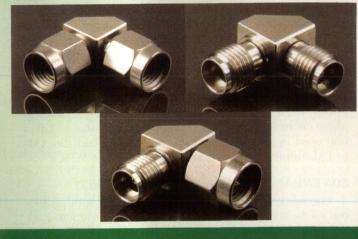
2.9mm, DC to 40 GHz



3.5mm, DC to 33 GHz



SMA, DC to 26.5 GHz







C.W. Swift & Associates, Inc., introduces S.G. McGeary Company's high-frequency coaxial adapters. Right-Angle In-Series configurations are available in 2.4mm, 2.9mm, 3.5mm and SMA interfaces. Straight In-Series and Between Series configurations are available in 1.85mm, 2.4mm, 2.9mm, 3.5mm, 7mm, SMA, SSMA, N & TNC Interfaces.

### C.W. SWIFT & Associates, Inc.

RF, Microwave and mm-Wave Stocking Distributors

15216 Burbank Blvd., Suite 300, Van Nuys, CA 91411 800-CW SWIFT • 818-989-1133 • 818-989-4784 (fax)

Click LEADnet at mwjournal.com or Circle 91 on Reader Service Card

### **COVER FEATURE**

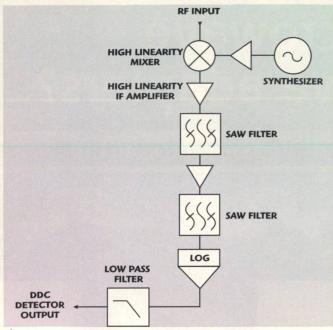


Fig. 2 Direct distortion control assembly.

The DDC, shown in *Figure 2*, first measures the carrier frequencies and then directly minimizes the MCLPA's intermodulation distortion (IMD) at the expected IMD frequencies. In addition to allowing the cancellation to be controlled, it is also possible to perform equalization of any asymmetric IMD components from the MPA, together with any asymmetric cancellation performance in the error loop. Therefore, the DDC approach ensures that the best possible level of IMD performance is obtained at all times and under all conditions.

The DDC is able to select the frequencies that are to be minimized, which means the error loop's instantaneous can-

TABLE I	
KEY PERFORMANCE SPECIF	ICATIONS
Frequency range (MHz) (any MCLPA can be used in any band, but only over 20 MHz instantaneously)	2110 to 2130 2130 to 2150 2150 to 2170
Average RF power output (dBm)	47.8
Multi-carrier intermodulation distortion (dBc with 1 to 4 W-CDMA carriers and 5 MHz spacing (measured with rms detector, 30 kHz R/b, 100 kHz V/b, 0.5s sweep time)	7-60 (Test Model 1 with 64 DPCH)
RF gain (includes variation due to frequency, power supply, temperature and unit-to-unit) (dB)	58 ±0.5
Input power supply range (V DC)	26 to 30 (800 W)
Power supply efficiency (%) (at maximum average RF output power and using Test Model 1 with 64 channels)	8
Operational ambient temperature range (°C)	0 to +50
RF connectors (front panel)	Input SMA-F Output SMA-F
External monitoring and control	RS 485
Alarms	over power, over temp, loop control fail, output VSWR, power supply
Mechanical dimensions Height Width	8 rack-units 4 units per 19" rack

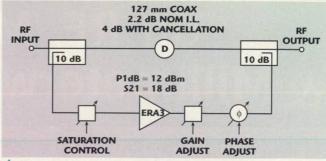


Fig. 3 Peak predistortion block diagram.

cellation bandwidth requirements are lower than that required with a fixed frequency pilot injection system, which improves produceability. The DDC method also does not require a pilot injection system, meaning there is no possibility of leakage or spurious at the MCLPA output. Having no pilot injection also means that there are no error loop offsets due to pilot RF leakage. There is also marginal improvement in efficiency by not having to amplify and cancel a pilot signal. Some pilot recovery schemes also require a third carrier cancellation loop that is not required in this design, thus further improving produceability by eliminating the additional gain, phase and delay matching.

### **ANALOG PEAK PREDISTORTION**

The analog peak predistortion method, shown in *Figure 3*, works by cancelling the main path RF with the output from a limiting amplifier and provides both gain and phase correction of the MPA LDMOS soft limiting characteristics near P1dB. The effect of this correction method is that the MPA output power capability is increased by as much as 20 percent for the same level of adjacent channel leakage ratio (ACLR) or, alternatively, for the same output power, the ACLR is improved by approximately 3 dB. By compensating for the nonlinear gain and phase characteristics of the MPA in this way the ACLR is improved by reducing both the AM-to-AM and the AM-to-PM distortion components produced in the MPA.

### **EPA ENHANCED OUTPUT CARRIER POWER**

Careful design of Loop 1 lined up together with pilotless control means that there is minimal noise and spurious loading on the EPA, and the total MPA distortion at the EPA output is only approximately 0.5 W rms. This allows the output power capability of the EPA to be put to good use by supplying carrier power in phase with the MPA output. The technique is similar to cross cancellation, but the implementation is simple and non-adaptive because the carrier power being supplied is only around 10 percent of the total MCLPA output power. The output contribution of around 5 W is approximately equal to the level of MPA carrier power that is typically lost into the 50  $\Omega$  load of the 10 dB error coupler.

### **KEY PERFORMANCE TARGETS**

**Table 1** lists the key performance specifications of the Tornado MCLPA. To improve propagation in the 2.1 GHz frequency band and maximize cellular communications coverage, the amplifier was designed with a high 60 W (47.8 dBm) maximum average output power.

[Continued on page 102]

## Wideband

# VCOS fora wireless WOLCA.

A broadband world requires broadband signal sources that offer low noise, linear tuning and load-insensitive performance. At Vari-L, we apply the same precision engineering and manufacturing to our Wideband VCOs as you have come to experience in our Narrow band VCOs. Excellent phase noise performance and tuning linearity enable consistent PLL loop bandwidths, settling time and low integrated noise. And, our wideband VCOs low frequency pulling will minimize your system phase error.

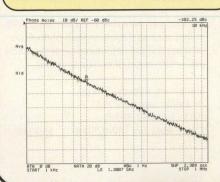
To find out how Vari-L's Wideband VCOs can be "a part in your future," please visit our website at www.vari-l.com, or send an email to sales@vari-l.com.

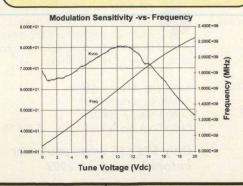
Part Number	Frequency Range(MHz)	Tuning Voltage	Typical 10 kHz Phase Noise	Supply Voltage	Output Power	Package Size
VC0790-600T	400-800	0.0 - 20.0	-102 dBc/Hz	+5 V	+3 dBm	0.5 x 0.5 x 0.18 in.
VC0790-1500T	1000-2000	0.0 - 20.0	-98 dBc/Hz	+5 V	+2 dBm	0.5 x 0.5 x 0.18 in.
VC0790-2300T	2100-2500	1.0 - 4.0	-89 dBc/Hz	+5 V	+3 dBm	0.5 x 0.5 x 0.18 in.
VC0793-600T	400-800	0.0 - 20.0	-104 dBc/Hz	+12 V	+7 dBm	0.5 x 0.5 x 0.18 in.
VC0793-1500T	1000-2000	0.0 - 20.0	-99 dBc/Hz	+12 V	+7 dBm	0.5 x 0.5 x 0.18 in.

Actual data for VC0793-1500T

Phase noise from HP3852 for 1000-2000 MHz VCO

Tuning Sensitivity from HP3852 for 1000-2000 MHz VCO









We Have A Part In Your Future

	489	95 Peoria Street	
7.	Den	ver, Colorado 80239	
	7	303.371.1560	
ď	fav	202 271 0845	Ī

sales @ vari-l.com

PRODUCTS INCLUDE:

OUR

PLL Synthesizer Modules

Narrow Band Voltage Controlled Oscillators

Wide Band Voltage Controlled Oscillators Couplers



ISO 9001 Certified

Contact the Vari-L Sales Department for custom solutions to your RF and microwave component assembly needs.

/ari-L Company, Inc.

www.vari-l.com

# NEW RESOURCES IN MICROWAVE DESIGN



### **NEW! SAVE 15%**

Nonlinear Microwave and RF Circuits, 2nd Edition

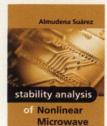
Stephen A. Maas



### **NEW! SAVE 15%**

Microwave Component Mechanics

Harri Eskelinen and Pekka Eskelinen



Circuits

### NEW!

Stability Analysis of Nonlinear Microwave Circuits

Almudena Suárez and Raymond Quéré

- Revises the 1988 Artech House classic, offering you a comprehensive, up-to-date treatment of nonlinear microwave and RF circuits
- Gives you a current, in-depth understanding of the theory of nonlinear circuit analysis with a focus on Volterra-series and harmonic-balance methods
- Delivers practical guidance in designing nonlinear circuits and modeling solid-state devices for nonlinear circuit analysis by computer
- Teaches how characteristics of such models affect the analysis of these circuits

Hardcover. Approx. 600 pp. Available February 2003 ISBN: 1-58053-484-8 Order Book No. MW024849

Only \$84/£58 when you order before January 31, 2003

**ONLINE** www.artechhouse.com

- Offers detailed guidance in the mechanical aspects of designing and manufacturing microwave components
- Takes an interdisciplinary approach that combines design and manufacturing, mechanical and electrical design, and microwave component performance and productivity
- Explores the immediate connection between electrical and mechanical quality, allowing you to more easily arrive at costeffective solutions and reduce the unnecessary use of "double-tolerancing"

**CD-ROM included!** This interactive disc features several 3-D models, informative PowerPoint presentations, and dxf files of selected microwave compo-

Hardcover. Approx. 410 pp. Available February 2003 ISBN: 1-58053-368-X Order Book No. MW023689 \$89/£65

nents for direct CNC-machining.

Only \$75 £55 when you order before January 31, 2003

- Provides you with an in-depth look at the very complex and often unforeseen behavior of nonlinear circuits
- Presents detailed coverage of circuits used in power amplifiers, voltage-controlled oscillators, frequency dividers, frequency multipliers, self oscillating mixers, and phasedlocked loops
- Gives you insight into the design solutions that nonlinear circuits offer, presenting explanations and detection techniques for many "anomalous" phenomena often encountered in practice
- Helps you overcome common design difficulties such as stability analysis of nonlinear regimes and the determination of the stable operation ranges of nonlinear circuits

Hardcover. Approx. 356 pp. Available January 2003 ISBN: 1-58053-303-5

Order Book No. MW023039 \$99/£69

### TO ORDER, CONTACT THE ARTECH HOUSE OFFICE NEAREST YOU

US FAX Purchase orders and credit card orders to 1-781-769-6334 PHONE Toll-Free 1-800-225-9977, ext. 4030 or 1-781-769-9750 E-MAIL artech@artechhouse.com
UK FAX Purchase orders and credit card orders 24 hours a day to +44 (0)20 7630-0166
PHONE +44 (0)20 7596-8750 E-MAIL artech-uk@artechhouse.com

\$99/£69

All orders plus shipping/handling and applicable taxes.

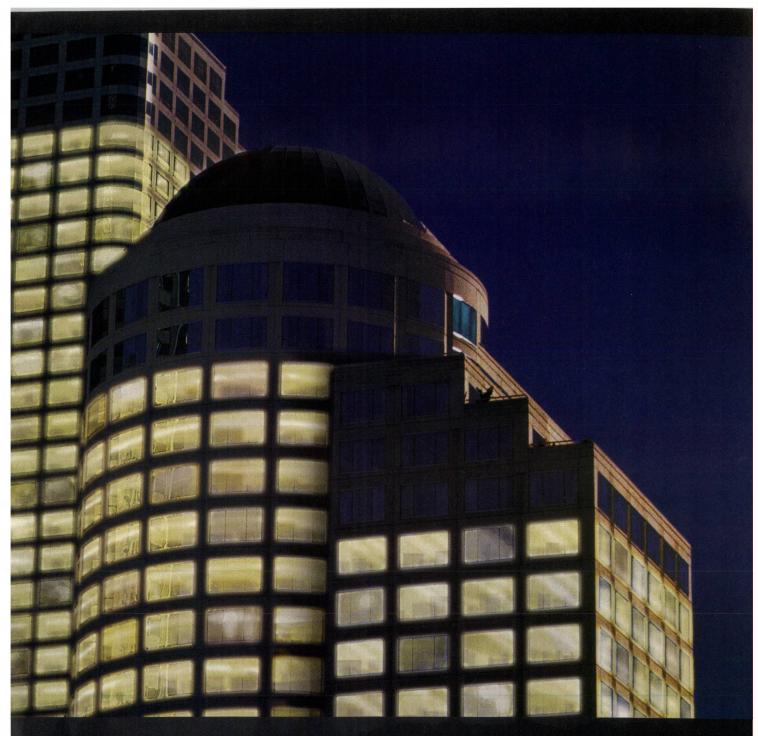
All orders are backed by the Artech House 100% Satisfaction Guarantee. If you're not completely satisfied, you may return any book in new condition with the invoice within 30 days for a full refund. Opened software is not returnable unless defective. All prices subject to change without notice; discounts are net and are available only on order placed directly with Artech House

Artech House Publishers

685 Canton Street, Norwood, MA 02062 USA 46 Gillingham Street, London, SW1V 1AH, UK

www.artechhouse.com

Click LEADnet at mwjournal.com or Circle 8 on Reader Service Card



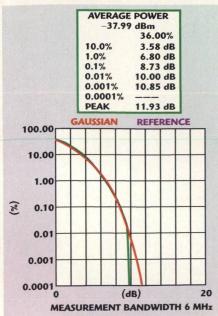
Where will you find the top floor people between 12-18 October? In Geneva, at ITU Telecom World 2003.



ITU TELECOM WORLD 2003 Geneva 12-18 October The world's telecommunications leaders in Government, Finance, Mobile, Satellite, Broadband and Legal sectors will come together in Geneva to make deals, display new technologies, discuss policies and shape the future of the industry. Organized by the International Telecommunication Union, ITU Telecom World 2003 offers unique access to the key players influencing our industry. In addition, our world-class Forum brings together the finest minds to share insights and exchange ideas. Join this top-quality group and make business happen. www.itu.int/world2003



### **COVER FEATURE**



▲ Fig. 4 CCDF of a single W-CDMA carrier using Test Model 1 with 64 channels.

The Tornado MCLPA is specified to operate with one to four W-CDMA carriers using Test Model 1 with 64 channels and no preclipping. By measuring the complementary cumulative

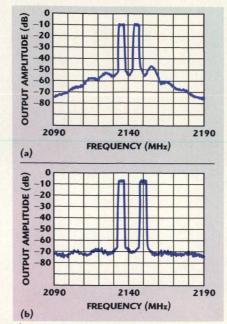


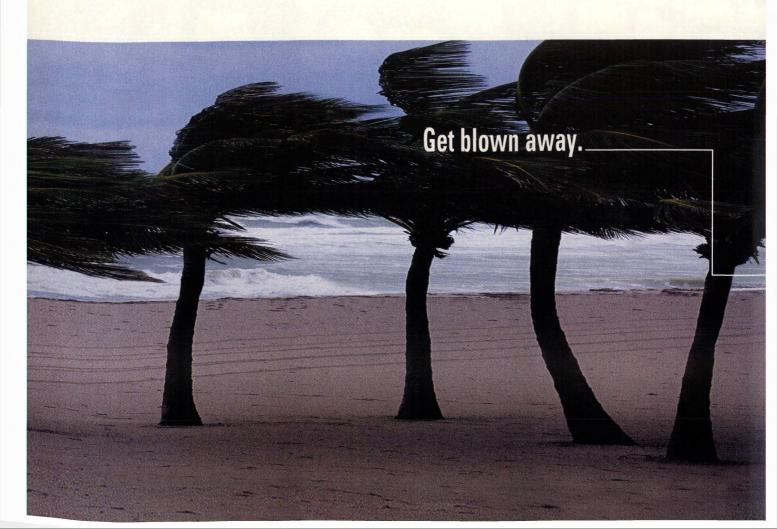
Fig. 5 MPA ACLR performance at 47.8 dBm (60 W) and 25°C (a) without and (b) with feedforward cancellation.

distribution function (CCDF) for a single carrier (see *Figure 4*) it can be seen that the peak-to-average ratio at 0.01 percent probability is as high as 10 dB.

The peak-to-average ratio or crest factor (CF) is defined as the quotient of peak envelope power (PEP) to average power (CF = PEP/ $P_{av}$ ), where PEP is defined as the power of the carrier sinusoid taken over one carrier period when its amplitude is at maximum and  $P_{av}$  is proportional to the mean value of the squares of the signal voltage over a long period of time. The required maximum average output power and the CF of 10 dB together determine the peak power capability and dimensions of the MPA, which for Tornado is 900 W P1dB.

### LINEARITY PERFORMANCE

Using feedforward techniques the ACLR of the MPA output is typically improved by approximately 25 dB to 60 dBc at the MCLPA output, as shown in *Figure 5*. Higher than 60 W output power levels would make satisfying the absolute power level requirements of the spectral emissions mask more problematic and further linearization would very likely have been necessary unless the peak-to-average requirements of the input signal were relaxed.



### **EFFICIENCY**

Efficiency has probably become the most important characteristic of an MCLPA as operators seek to reduce fixed operating costs, and governments and corporations seek to satisfy the Kyoto accord on greenhouse emissions. Just five years ago, before the advent of LDMOS and other efficiency enhancements, a bipolar feedforward MCLPA might have had an efficiency of just two to three percent. Using LDMOS transistors and using the worst-case W-CDMA carriers and Test Model 1 with 64 channels, Tornado achieves an efficiency of eight percent. However, using carriers with a more typical peak-to-average power of 8 dB, the MCLPA can be operated at 80 W average output power where the efficiency is close to

Further efficiency improvements, yielding up to 12 percent efficiency, may be obtained by accepting a reduction in ACLR performance of 5 dB and using the pre-feedforward architecture known as advanced cross cancellation. In this special case, the EPA has the same output power capability and char-

acteristics as the MPA, and is used to supply half of the output carrier power. The efficiency improvements are the result of 0.5 dB lower loss after the EPA compared to the MPA. Also, since the MPA and EPA are closely matched, the MPA provides very good predistortion of the EPA, which further improves the overall efficiency of the EPA and MCLPA.

### COST

It is a fact that today's competitive economic environment calls for the minimum possible dollars per watt. This need has been addressed by using three techniques that maximize the output power for a given set of transistors. These techniques include peak power predistortion, a high power, low loss filter delay line, and the use of the EPA to provide additional output carrier power in a similar fashion to cross cancellation. Feedforward amplifiers are also more cost-effective and more efficient at higher output power levels.

The cost of the bill of materials (BOM) was minimised by omitting any non-essential components. The

design was also simplified by reducing a DSP board to just a single chip 8051-based microcontroller. A common design for the EPA and driver power amplifier (DPA) was also used, and even something as small as the total number of high Q capacitors was minimised to reduce overall cost.

### CONCLUSION

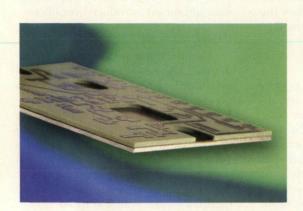
A minimalist approach in the Tornado MCLPA's unique design has yielded an amplifier that has achieved high power output, excellent linearity performance and low cost to satisfy today's tough requirements for the emerging 3G W-CDMA market. The Tornado MCLPA is available for demonstration on request, and the company's efficient and flexible design and manufacturing capabilities are available to undertake custom designs for similar sophisticated requirements.

Unity Wireless Systems Corp., Burnaby, BC, Canada (604) 267-2712, www.unitywireless.com, sales@unitywireless.com.

Circle No. 301



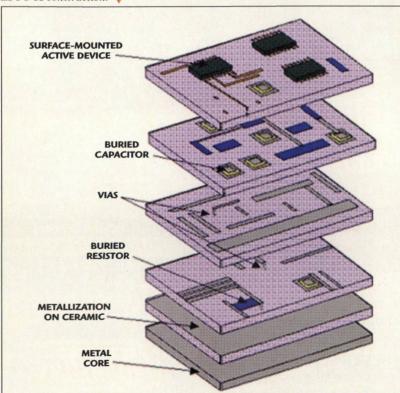
### PRODUCT FEATURE



# NEW SUBSTRATE TECHNOLOGY FOR HIGH PERFORMANCE CIRCUITS AND SYSTEMS

Fig. 1 Multi-layer LTCC-M construction.

new substrate technology has been developed that addresses the dense component placement, high heat dissipation, harsh environments and high frequencies associated with high performance devices



such as microwave amplifiers for base stations, broadband amplifiers designed into multi-media networks, and high power microwave power combiners with on-board terminations. The new technology — low temperature co-fired ceramic on metal (LTCC-M) — utilizes a patented process that bonds ceramic to metal to deliver improved performance and reliability at lower cost. An example of LTCC-M is shown in *Figure 1*.

The LTCC-M process shares some similarities to LTCC. However, LTCC-M bonds a multi-layer "green tape" board to a Kovar or CuMoCu metal base using special materials and a 900°C firing process. The addition of the bonded metal base provides several advantages. For example, open cavities that extend down to the metal base can be created with LTCC-M to allow direct component die mounting on the base (or one or two layers above). This eliminates the need to attach a fully packaged high power component on a large substrate-mounted heat sink, which requires machining of both the substrate and sink in conventional LTCC processing. The metal core in an LTCC-M substrate allows heat to be carried away from hundreds of watts of power dissipation with a thermal con-

[Continued on page 106]

Lamina Ceramics Westampton, NJ



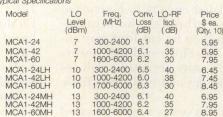
Commercial, Military, and Industrial Use

Mini-Circuits proudly introduces MCA1, the world's first commercially available line of *low temperature cofired ceramic (LTCC)* frequency mixers! Highly reliable, extremely broad band, and very low in cost, these patent pending double balanced mixers have excellent electrical performance and are available in level 7, 10, and 13 (LO) models for your 300MHz to 6GHz designs. As for ruggedness and reliability, MCA1 mixers have all circuitry hermetically embedded inside the ceramic making them impervious to most environmental conditions. The process also gives you superior stability under temperature, high repeatability, and compact 0.065" profile. They're ideal for the COTS program, as well as your commercial and industrial applications. So contact Mini-Circuits now. Our team is ready to handle your needs worldwide with quick shipments, custom designs, high volume production capability, and fast turn-around.

Mini-Circuits...we're redefining what VALUE is all about!

ea.(Qty.10)





Detailed Performance Data & Specs Online at: www.minicircuits.com/mixer2.html







CIRCLE READER SERVICE CARD

Actual Size

The Design Engineers Search Engine Provides ACTUAL Data Instantly From MINI-CIRCUITS At: www.minicircuits.com

### PRODUCT FEATURE

TABLE I
SUBSTRATE PROPERTY COMPARISON

Material Property**	Lamina Cera Kovar	mics LTCC-M CuMoCu (13/74/13)	Typical LTCC	Typical HTCC Alumina (96%)	Ceramic- filled PTFE	Typical FR4 Fiberglass
Range of part dimensions (inches)	up to 16×16	up to $16 \times 16$	up to $6 \times 6$	up to 6×6	up to 24 × 24 typically	up to 24 × 24 typically
Buried passives	yes	yes	yes	no	no°	no*
Buried resistor tolerance (%)	±10	±10	±10 to 30	n/a	n/a	n/a
High K tape	yes	yes	no	no	no	no
Ferrite tape	yes	no	no	no	no	no
Hermetic cavities	yes	yes	yes	yes	no	no
x-y shrinkage (%)	~±0.1	~±0.1	~12.7 to 14.8	~15	n/a	n/a
Thermal conductivity (W/m°C)	40	170	2 to 3	24.7	0.61	1.7
Expansion coefficient (TCE) (ppm/°C)	6.7 (up to 300°C)	5.5 (up to 400°C)	5.8 (up to 400°C)	8.2 (up to 400°C)	~1.7 to 24 (up to 400°C)	13 (up to 400°C)
Dielectric constant $(\epsilon_r)$	6.0 at 15 GHz	5.5 at 15 GHz	7.8 at 2 GHz	9 at 15 GHz	6.15 at 15 GHz	5.4 at 15 GHz
Loss tangent, 25°C	0.0015 at 15 GHz	0.0005 at 15 GHz	~0.002 at 16 GHz	0.001 at 15 GHz	0.0025 at 15 GHz	0.032 at 15 GHz
Microstripline loss	0.3 at 12 GHz	0.17 at 12 GHz	~0.2 to 0.5 at 12 GHz	0.25 at 12 GHz	0.4 at 12 GHz	1.5 at 12 GHz

°Some manufacturers offer buried resistors. See www.ohmega.com °°Data compiled from measurements, manufacturers product data and web sites

ductivity of 170 W/m°C. Furthermore, high frequency loss as low as 0.5 dB per inch of transmission line at 40 GHz is possible.

There are a number of other benefits associated with LTCC-M. Shrinkage in the x-y plane during firing is typically 0.1 percent, a significant improvement over LTCC, which has a typical shrinkage of 12.7 to 14.8 percent. LTCC-M boards can be as large as 16" × 16" and have greater component density than LTCC boards, which are limited to  $6" \times 6"$  wafer sizes. The larger wafers allow multiple populated circuits to be created in one pass through the furnace, which can then be cut from the finished wafer. This capability lowers production costs because it reduces parts handling and other repetitive

Production costs can also be saved in other ways using LTCC-M. To protect against environmental exposure, LTCC substrates often are placed in costly leaded Kovar packages. With LTCC-M, a hermetic package with lid can be produced for a savings of as much as 50 percent. LTCC-M also allows a variety of optical and electrical connection options that simplify integration and reduce assembly costs.

### LTCC-M PROCESS

All of this is made possible by an LTCC-M process that greatly reduces the number of production steps compared to standard LTCC. The first part of the process, production of a populated substrate, is similar to the one used for LTCC parts, except that LTCC-M parts have a bonded metal base. Both LTCC and LTCC-M start with a roll of "green tape" however LTCC-M bonds that tape to Kovar or CuMoCu. The populated multiplayer board is formed in a similar fashion to LTCC:

- Cutting the dielectric substrate into blanks for each layer
- Punching via holes for connections between layers
- Applying metallization, insulation and resistive pastes to each layer
- Bonding the layers
- Co-firing the "green" multiplayer assembly and metal base

Although both substrates share many of the same processing steps, the LTCC-M technology has advantages. One is that up to 24, 0.004" thick layers for traces and buried passives are possible at a price as low as \$2 per square inch per layer. For a given circuit design, such layering allows shrinkage in overall package dimensions. This combination of characteristics cannot be duplicated with conventional LTCC technology. A complete comparison of LTCC-M to LTCC and other substrates can be seen in *Table 1*.

### CONCLUSION

High performance systems pose difficult design problems, including circuit and system packaging. Conventional substrate technologies have been shown to either lack the performance or price point to meet the trend towards higher bandwidth and more feature-laden products in smaller packages. The new LTCC-M technology serves as a solution for these high performance circuits and systems.

Lamina Ceramics, Westampton, NJ 800-808-LTCC (5822), www.laminaceramics.com.

Circle No. 302



### **MODULE TYPES**

- Ultra-Broadband Amplifiers
- Medium Power Amplifiers
- High-Gain Amplifiers
- Low-Noise Amplifiers
- Frequency Multipliers
- High-Pass Filters
- Band-Pass Filters
- PIN Attenuators
- Power Dividers
- Input Limiters
- IF Amplifiers
- Couplers

- Proven JS amplifier technology
- Superior noise and phase performance
- All modules contain internal regulation
- Module sizes are 0.45" L x 0.40" W x 0.11" H
- Compact assembly sizes fit most system applications

### **OPTIONS**

- Combined isolated gain modules for up to 75 dB of total gain
- Integrated filtering to reduce noise bandwidth and I.M. distortion
- Ultra-low noise and medium power module pairings for high dynamic range
- PIN attenuators to enhance system flexibility
- Front-end RF limiters to protect against high level inputs
- A single-broadband input can be divided into multiple sub-bands



100 Davids Drive, Hauppauge, NY 11788 TEL.: (631) 436-7400 • FAX: (631) 435-7470/436-7430 miteg.com



For additional information, please contact Rosalie DeSousa at (631) 439-9458 or send an e-mail to rdesousa@miteg.com.

### PRODUCT FEATURE



# RF/MICROWAVE MANIPULATORS FOR PRECISE TEST PROBE MEASUREMENTS

In today's fast paced semiconductor industry making accurate and reliable measurements at microwave frequencies is critical to successful product development operations. Microwave measurements enable engineers to characterize both the linear and nonlinear behavior of devices, providing critical performance information. Precise probe contact is a necessity to obtain accurate test data. Precision microwave manipulators must be employed to properly position the probe contacts.

A series of new RF/microwave manipulators has been introduced that feature direct leadnut coupled drives and a number of base choices including a magnetic-assisted vacuum base. The WAVE100 and WAVE200 manipulators, and the PLF/PLS probe head link arms are two critical elements that assure mi-

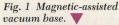
crowave system stability and probe planarity required for sensitive microwave circuit measurements. These rugged rectilinear manipulators have a lead screw pitch of 40 threadsper-inch and feature secure massive mounts to provide stability, even with semi-rigid coaxial cables attached to the probes. The rigid probe head link arms are available in two styles to permit simultaneous use of four probes, and theta and planarity adjustments of the probes are standard.

### **FIVE DEGREES OF FREEDOM**

The WAVE100 (left-handed) and WAVE200 (right-handed) manipulators are engineered with five degrees of freedom. The new manipulators feature five controls that are readily available for fingertip adjustment to obtain the precise probe contact required. The controls are up/down, forward/backward, side-to-side, planarity and 4° of theta control. Probing RF/microwave test structures is now easier than ever. In addition to maximum position control, the large  $4.8" \times 2.3"$  base is available in magnetic, magnetic-assisted vacuum, vacuum and mechanical lock mounts. The mechanical lock configuration is easy to use, requiring no tools for setup. Figure 1 shows the manipulator's magnetic-assisted vacuum base

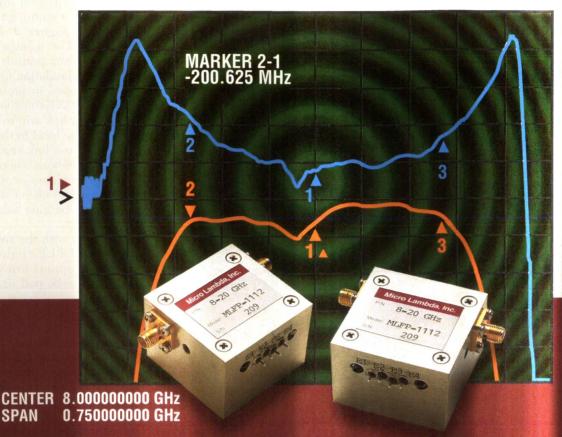
[Continued on page 110]

MICROMANIPULATOR CO. Carson City, NV





### Wide Bandwidth Filters Low Ripple, Low Group Delay



S<sub>21</sub> REF 0.0 s ▲ 1.0 ns/ 2 1.4546 ns

S<sub>21</sub> REF 0.0 dB 2 1.0 dB/ ▼ 0.0615 dB

Micro Lambda Wireless, Inc. offers "Next-Generation" YIG filters with extremely low passband ripple and low group delay covering the 6 GHz to 18 GHz frequency range. Designed to provide very wide passband bandwidths, these filters have been optimized for very low passband ripple over the 3 dB bandwidth while maintaining excellant group delay characteristics. Units are offered in 1.7" square x 1.2" low profile packages.

### MLFP BANDPASS FILTERS, L-SERIES

Available in multi-octive frequencies from 6 to 18 GHz. Units provide 3 dB bandwidths of 500 MHz minimum, while providing 1.5 dB maximum passband ripple over the center 85% of the 3 dB bandwidth. Low group delay of better than 3 nSec is provided for all models. Units are available covering 6 to 18 GHz, 8 to 18 GHz and 8 to 20 GHz tuning ranges. Off resonance isolation is 100 dB minimum for all models.

### **FEATURES**

- Wide 3 dB Bandwidths
- Low Bandpass Ripple
- Low Group Delay
- Low Profile Package

"Look to the leader in YIG-Technology"





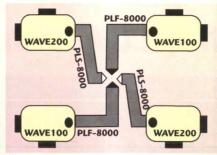




### PRODUCT FEATURE



A Fig. 2 Vacuum base.



A Fig. 3 Manipulator/link arm possibilities.

configuration. This base style is an excellent choice for occasional use on stations not designed for microwave work, as the magnetic base secures the manipulator from tipping and the addition of vacuum gives it rock-solid stability. Figure 2 shows the vacuum base. The manipulator assembly weighs four pounds and provides a secure foundation for the semi-rigid cables used in most applications. Each WAVE100/200 manipulator requires a link arm to hold and extend the probe head to the device under test. These link arms accommodate probe stations where the chuck is below the platen or where the chuck is above the platen simply by using different mounting holes on the planarity face plate.

When combined with the rugged PLS (straight) and PLF (right angle) probe head support arms the fixture can easily probe pad sizes of 2 µm with precision planarity and theta alignment, and no probe vibration. *Figure 3* shows a possible four-probe test configuration using both WAVE100 and WAVE200 manipulators with PLS and PLF arms.

The WAVE100/200 manipulators are compatible with most manufacturer's probing stations, including Micromanipulator's 9000 series with the RF option for 12" wafers, 4000 Tech Series, 6500 or 8000 series for 4", 6" and 8" wafers. With the proper manipulator base choice they can work with probe stations with or without the RF option.

The WAVE100/200 manipulators can support all manufacturer's microwave probe heads, including the industry leading Picoprobe® microwave probe head that can be used at frequencies up to 220 GHz, and features excellent insertion and return loss performance.

WAVE100 and WAVE200 manipulators are currently available with delivery times ranging from six to eight weeks. Additional information may be obtained by visiting the company's Web site at www.micromanipulator.com or by contacting the company's sales staff.

Micromanipulator Co., Carson City, NV (775) 882-2400, info@micromanipulator.com.

Circle No. 303

## Got RF? Endwave is your source 100 MHz – 100 GHz • Standard Products and Custom Capabilities • Commercial and Defense Applications • Commercial and Defense Applications • Wultipliers Freq. Range: 100 MHz – 75 GHz • Multipliers Active and Passive Options

Low Noise Amplifiers

Narrowband and Broadband

SMA, K and WG Connectors

P1dB: Up to +30 dBm

Gain: Up to 44 dB

VSWR: 2.0:1 (typ)

Freq. Range: 100 MHz – 75 GHz Narrowband and Broadband Single and Multi-Octave Gain: Up to 44 dB Noise Figure: As Low as 2.0 dB IP3: Up to +32 dBm VSWR: 2.0:1 (typ) SMA, K and WG Connectors



### Transceivers

11 – 58 GHz in Production 7 – 67 GHz Capabilities Low-Capacity [PDH] High-Capacity [SDH] Internal or External LO Integrated or Discrete TX and RX Modules

Multiplication: X2 to X28

Psat: Up to +30 dBm

Output Freq: 100 MHz - 67 GHz

SMA, K and WG Connectors

**Up/Down Converters** 

5 - 67 GHz Narrowband

Pout to +30 dBm

IF Range to 5 GHz

Optional Internal LO

Noise Figure 4 - 7 dB

Saturated or Linear Outputs

SMA. K and WG Connectors

Optional Gain Control & Power Detection

Input Power: -10 to +10 dBm (typ)



### **YIG** Synthesizers

**YIG Oscillators** 

Low Phase Noise:

Freq. Range: 3 – 11 GHz

Low Power Consumption

Wide Tuning Range: +/- 1 GHz

- 105 dBc/Hz @ 10KHz (typ)

Power Output: Up to +14 dBm

SMA or Board Mount Packages

- 128 dBc/Hz @ 100KHz (typ)

Freq. Range: 3 – 12 GHz Wide Tuning Range: +/- 1 GHz Low Phase Noise:

100 dBc/Hz @ 10 kHz (typ)130 dBc/Hz @ 100KHz (typ)

Single and Dual Output Options Robust Microphonics Performance Multiplication to 67GHz Available



Freq. Range: 800 MHz – 2.1 GHz
Active or Passive Options
2, 3 and 4-Way Configurations
Power: Up to 800 Watts
Loss: <.35 dB
VSWR: 1.3:1 (typ)
Integrated Power Dividers and Couplers
SMA, OSP, N and TNC Connectors

Call Endwave at 1-888-363-4283 for additional information or visit our web site at www.endwave.com for a list of domestic and international sales representatives.

Endwave Corporation 990 Almanor Avenue • Sunnyvale, CA • 94085 408-522-3100 main • 408-522-3102 fax





# 75 \$ 5 From 7

RF+DC

Easily combines RF+DC signals for your modulation or test requirements.

#### DC Now up to 500mA DC current 100kHz-6GHz

With Mini-Circuits Bias-Tees, you can DC connect to the RF port of an active device without effecting its RF properties...modulate a laser, apply DC to an amplifier output, and more! Using statistical process control plus combining magnetics and microstrip, large DC currents may pass

through the Bias-Tee without saturation and degradation of performance. At 1/3 to 1/4 the price of competitive units, these new Bias-Tees are available in surface mount, pin, and connectorized models. So why wait, solve your connection problems with Mini-Circuits Bias-Tees.

Mini-Circuits...we're redefining what VALUE is all about!

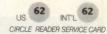


L = Low Range M = Mid Range U = Upper Range
NOTE: Isolation dB applies to DC to (RF) and DC to (RF+DC) ports.

▲ SMA Models, FT Models Have Feedthrough Terminal ★Type N. BNC Female at DC

▲ SMA Models, FT Models Have Feed ■ Pin Models • Surface Mount Models





P.O. Box 350166, Brooklyn, New York 11235-0003 (718) 934-4500 Fax (718) 332-4661 For quick access to product information see MINI-CIRCUITS CATALOG & WEB SITE The Design Engineers Search Engine Provides ACTUAL Data Instantly From MINI-CIRCUITS At: http://www.minicircuits.com

ZFBT-FT



## **WEB UPDATE**



#### Microwave Products

This Web site enables customers to efficiently gather information from the company's products catalog. Visitors can easily access detailed part descriptions, images and drawings of all the company's GPO™ and GPPO™ standard products. It also features product information, assembly instructions and recommended tools. Pull-down menus provide quick navigation through the company overview, literature requests and technical information sections.

Corning Gilbert Engineering, 5310 West Camelback Road, Glendale, AZ 85301

#### www.corning.com/ corninggilbert



# Commercial and Defense Products

This Web site details the company's design and manufacturing capabilities for commercial and defense products from 100 MHz to 100 GHz. Product information and downloadable data sheets for LNAs, PAs, multipliers, up/down converters, oscillators, synthesizers, transceivers and switch combiners. *Endvave Corp.*,

990 Almanor Ave., Sunnyvale, CA 94085

www.endwave.com



#### Antennas

In an effort to optimize marketing communications and shorten its new product launch cycle, the company has launched a new Web site. The site is now the central point for the company's marketing activities, including public relations, direct mail, up-to-date product catalogs, on-line advertising and other key supporting activities.

MAXRAD Inc., 4350 Chandler Drive, Hanover Park, IL 60133

www.maxrad.com



#### Microwave Transmission Line Products

This Web site makes it easier to locate and download information on the company's full line of microwave transmission line products designed for use in commercial, military and space applications. The site has been redesigned with improved functionality features and increased literature download capability so visitors can now easily download data sheets, application notes and other literature in PDF format.

MICRO-COAX, 206 Jones Blvd., Pottstown, PA 19464

www.micro-coax.com



#### Antenna and Radome Products

This updated and expanded Web site provides detailed information on antenna and radome products, technology and capabilities. Specific technical information is provided for airborne antennas for electronic warfare and communication, navigation and identification applications. The site also provides antenna and radome design aids and engineering data.

Nurad Technologies Inc., a division of Chelton Microwave Corp., 3310 Carlins Park Drive, Baltimore, MD 21215

www.nurad.org



#### RF Microwave Substrate Materials

This Web site features a new, faster-loading and easier to navigate look. Featured are product data tables, brochures, processing guides, technical bulletins and comparative tables. Information on all of the company's comprehensive substrate materials is available in the products section of the site, including the model N9000 RF microwave substrate material.

Park/Nelco–Neltec, 1420 West 12th Place, Tempe, AZ 85281

www.parknelco.com

# Gore Microwave Coaxial Test Assemblies... A Sure Bet.



#### **Gore Microwave Coaxial Test Assemblies:**

- NEXT GENERATION® Assemblies: Precise for Critical Measurements
- PHASEFLEX® Assemblies: Stable and Repeatable
- Operating Frequencies: DC to 65 GHz
- · Superior Phase and Amplitude Stability
- · Accurate and Repeatable Measurements
- Ruggedized Assemblies
- · Quick Delivery for Standard Configurations

Innovative Solutions, Defining Technology...



www.goreelectronics.com/info/test1

1 800 445-GORE



## **WEB UPDATE**

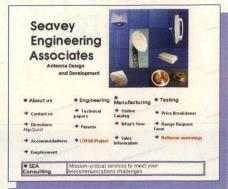


# RFICs for Wireless Communications Applications

This redesigned Web site focuses on enhancing customers' Web experiences. The site features an on-line product guide providing customers access to the company's extensive product portfolio and support documentation, such as data sheets, application notes, block diagrams, packaging types and performance details. It also includes a search engine that enables customers to search the product guide by product family, application, standard or part number.

RF Micro Devices Inc., 7628 Thorndike Rd., Greensboro, NC 27409

www.rfmd.com



#### Antenna Products

This web site provides information on the company's full range of products and services, including: antenna development, standard antenna products, EM modeling, antenna feeds, consulting, microwave components, antenna subsystems and test facilities. Seavey Engineering Associates Inc.,

North River Commerce Park, 28 Riverside Dr., Pembroke, MA 02359

www. SeaveyAntenna.com



#### Precision Coaxial Connectors

This site has recently been upgraded and features descriptions, specifications and drawings of the company's full line of precision coaxial connectors. Included are 1.85, 2.4, 2.9 and 3.5 mm series. Products are available for cable connectors, receptacles and adapters (both in-series and between series). A form requesting custom designs is also available.

S.G. McGeary Co., 525 Gus Hipp Blvd., Suite A, Rockledge, FL 32955

www.sgmcgeary.com



#### Programmable DC Power Supplies

This Web site features enhanced user-friendly features, providing visitors with greater technical content and graphic presentation. The home page features a product of the month, along with a breakdown of information available on the site. Users will find direct links to products, company news and information, sales and service support, and the company's new system outsourcing service. A complete section on articles, application notes and manuals is also available.

Sorensen, a division of Elgar, 9250 Brown Deer Road, San Diego, CA 92121

www.sorenson.com



#### RF Feedthrus and Packaging Solutions

This new Web site features a monthly product release of advanced feedthrus and direct seal and soldered assembly packaging solutions. It is set up for electrical and mechanical engineers looking for the latest housing components and modular packaging solutions. The site also offers a complete overview of the company's glass-to-metal RF feedthrus and packaging solutions and offers an easy Fast Quote form for submitting applications.

Thunderline-Z, 11 Hazel Dr., Hampstead, NH 03841

www.Thunderlinez.com



#### Test Solutions

This Web site features the company's test solutions, which can help customers get to market with next generation wireless devices. The company supports a broad range of innovative test solutions, services and support for components, devices and base stations. The wireless industry Web site features more information on accelerating the delivery of users' wireless products.

Agilent Technologies, 295 Page Mill Rd., Palo Alto, CA 94306

> www.agilent.com/ find/wireless

# UMTS / CDMA-3G Band

# SYNTHESIZER

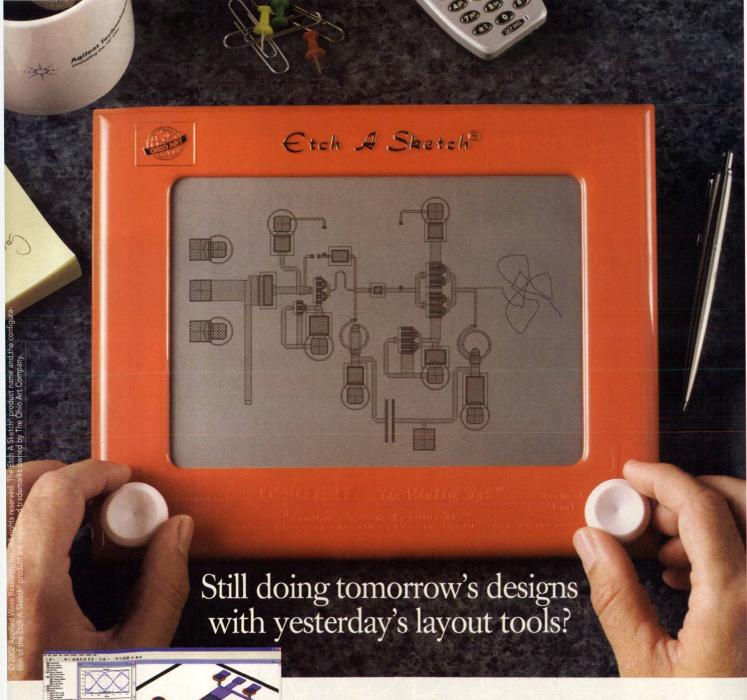
- 2110 to 2170 MHz
- Exceptional Phase Noise
- Compact Size
- Optimized Reference Sidebands



For additional information, contact Synergy's sales and application team.
201 McLean Boulevard, Paterson, NJ 07504
Phone: (973) 881-8800 Fax: (973) 881-8361 E-mail: sales@synergymwave.com
World Wide Web: http://www.synergymwave.com







Are you toying around with outdated layout tools that make you anything but agile? Have you considered switching to Microwave Office™ 2002? It was designed from the ground up to support complex layout problems like LTCCs, MMICs and RFICs, not to mention dense PCBs—with advanced capabilities like design rule checking, 3D views, and the industry's only truly unified database. Which means

you'll never have to deal with those problematic design synchronization steps or back annotations that can ruin your

day. It also comes with manufacturing interfaces like Gerber, DXF and GDSII that actually work! Stop playing around, and start getting your designs out in no time flat. Make the switch to Microwave Office 2002. Download a 30-day evaluation from www.mwoffice.com or call us at 310-726-3000 for more information.





#### INTERNATIONAL MICROWAVE SYMPOSIUM

#### PHILADELPHIA, PENNSYLVANIA



#### **IEEE MICROWAVE THEORY** AND TECHNIQUES SOCIETY JUNE 10-12, 2003



Liberty Through Microwaves

A-Alpha Waveguide Co. Accent Optical Technologies Accumet Engineering Corp. ACE Technology
Advance Reproductions Corp.
Advanced Control Components
Advanced Power Technology RF Aerowave Inc. Aethercomm Inc. Agile Materials & Technologies Agilent Technologies Air Precision/Sivers AKON Inc. Aliner Industries Inc. AMCOM Communications Inc. American Technical Ceramics Ametek Specialty Metal Products AML Communications Inc. Amplifier Research Amplifonix Amplitech Inc Analog Devices Inc. Anaren Microwave Inc. Andrew Corp. Anritsu Company Ansoft Corp.

Antenna Software Ltd. Aplac Solutions Inc. Applied Thin-Film Products Applied Wave Research Inc. ARC Technologies Artech House Ascor Incorporated Assemblies Inc. Astrolab Inc. Atlantic Microwave Avalon Equipment Corp.
Avitronics (a division of Grintron) Avnet RF & Microwave BAE Systems Barry Industries Base Station/Earth Station Besser Associates Inc. Bomar Interconnect Products Inc. Boonton Electronics BroadWave Technologies Inc. C-MAC MicroTechnology C.E. Precision Assemblies Inc. CAD Design Services Inc California Eastern Labs
CAP Wireless Inc.
Carleton University
Cascade Microtech
Celeritek Inc. Celerity System Channel Microwave Corp. Chelton Microwave China Wireless Technologies Co. Ltd Cirexx Corp.
ClearComm Technologies
Coilcraft Inc. Coleman Microwave Com Dev Ltd. Commercial Microwave Technology Communication Techniques Inc. Communications & Power Ind -Ontario Compac Development Corp. Compex Corp.
Component Distributors Inc.

Connectronics Inc.

Corning Gilbert Inc.

Corning IntelliSense

Cougar Components Coventor Inc.

CoorsTek

CRC Press

Coretec

Continental Microwave & Tool Co.

Credence Systems Corp Cree Microwave Inc CST of America Inc. CTT Inc Cuming Microwave Corp.
Custom Cable Assemblies Inc. Datum - Irvine DBP Microwave Delta Electronics Mnfg Corp. Diamond Discovery Semiconductors DiTom Microwave Inc. DLI (Dieletric Laboratories) Dorado International Corp. Dow-Key Microwave Ducommun Technologies Inc. DuPont Microcircuit Materials Dynawave Inc. Eagleware Corp. Ecliptek EE – Evaluation Engineering EiC Corp.
Elcom Technologies Inc. Electro Rent Corp.
Electronic Component News
Elisra Electronic Systems Ltd. Elva-1 Ltd. EMC Technology Inc.
Emerson & Cuming Microwave Prod. EMF Systems
Emhiser Micro-Tech Endwave Corp. Ericsson Microelectronics ETS – Lindgren Excelics Semiconductor Inc. EZ Form Cable Corp. F&K Delvotec Inc. Farran Technology, Ind. FCT Electronics The Ferrite Company In Filtel Microwave Inc. Filtran Microcircuits Inc Filtronic Solid State First Technology
Flexco Microwave Inc.
Florida RF Labs Inc.
Focus Microwaves Inc.
Frequency Management
FSY Microwave Inc. Fujitsu Compound Semicond. In Fujitsu Microelectronics Ame G.T. Microwave Inc. Gaiser Tool Co. Gavish Inc.
Gawell Technologies Corp.
GGB Industries Inc.
Giga Solution Tech Co. Ltd. Giga-tronics W. L. Gore & Associates Inc. Gowanda Electronics Harbour Industries
Haverhill Cable & Mfg. Co HCC Industries Inc Herley Industries Herotek Inc. Hexawave Inc. High Frequency Electronics Hitachi Metals America Ltd. Hitachi Semiconductor America Hittite Microwave Corp. Huber + Suhner Hybond Inc. IEEE Microwave Magazine IKE Micro IMI Printed Circuit Boards IMST GmbH In-Phase Technologies Inc. Infineon Technologies Innovative Micro Technology (IMT) Inphi Corp. Integra Technologies Inc. Integrated Microwave Corp.

International Manufacturing Svcs. Interpoint, A Crane Co. Company Ion Beam Milling Inc. ITT Industries IW Inc. Ixion Technologies J MicroTechnology Inc. JCA Technology, a NEW FOCUS company ersey Microwaye FW Industries Inc. ohanson Manufacturing Corp. ohanson Technology Inc. ohnson Components Inc ohnstech International Corp. ye Bao Co. Ltd. K&L Microwave Inc. Keithley Instruments Inc. Kemac Technology Inc. Keragis Kevlin Corp. Knowledge°on Inc Krytar Inc. KW Microwave Corp. Kyocera America In Labtech Limited Lamina Ceramics Inc. Laser Process Mfg. Inc. Laser Processing Technology Linearizer Technology Inc Litron Inc. Logus Microwave Corp. Logus Microwave Corp.
Lorch Microwave Corp.
LUCAS Signatone Corp.
Lucix Corp.
M/A-COM.
M/2 Global Technology Ltd.
Maury Microwave Corp.
MCE/DML Microwave Ltd.
MCE/DML Microwave Ltd. MCE/DML Microwave Ltd.
MCE/Inmet Corp.
MCE/KDI-Integrated Product
MCE/KDI-Resistor Products
MCE/Metelics Corp. MCE/Metelies Corp. MCF/Weinschel Corp. MCV Technologies Inc. MECA Electronies Inc. Megal Phase Megal Phase Megal Phase Merghase Megal Phase Merminae Industries Metalla Inc. Metallix Inc. MH&W International Corp.
MI Technologies
MICA Microwave Corp. Mician GbR Micralyne Inc. Micro Lambda Wireless Inc. Micro-Coax Inc. Micro-Mode Products Inc. Microlab/FXB MicroMetrics Inc Micronetics Wireless Microphase Corp. Microsemi Corp. Microsource Inc. Microtech Inc. Microwave Comm. Labs Inc. Microwave Development Co.Inc. Microwave Development Labs Inc. Microwave Device Technology Corp. Microwave Devices Inc. Microwave Dynamics Microwave Innovation Group Microwave Journal Microwave Product Digest Microwave Solutions Ltd. Microwave Technology Inc. (MWT) Mid-Atlantic RF Systems Millitech, LLC

Mimix Broadband Mini-Circuits Mini-Systems Inc. MITEQ Inc.
Mitsubishi Electric & Electronics MMCOMM Inc. Modeo Inc. Modular Components National Inc Molex RF/Microwave Connector Div. Morgan Advanced Ceramics Morgan Electro Ceramics Motorola Murata Electronics N.A. Inc. Narda, an L-3 Communications Co. National Semiconductor Netcom Inc. Nextec Microwave & RF Inc. Noise Com Inc. Northeast Electronics Corp Northern Technologies Inc. Northrop Grumman NTK Technologies Inc. Nurad Technologies Octagon Communications OEwaves Inc. Olin Aegis eida Research Services Inc OPHIR RF Inc. OPHIR RF Inc.
P/M Industries Inc.
Pacific Aerospace & Electroni
Park Nelco/Neltec Corp. Park Nelco/Neltec Corp.
Pascall Electronics Ltd.
Passive Microwave Technolo
Penton Technology Media
Reregrine Semiconductor Co Reregrine Semiconductor Corp.
Philips Semiconductors
Piconics Inc.
Piezo Technology Inc. (PT.L)
Poly Circuits Inc.
Polyfet RF Devices
Polyflon Company
Precision Photo Pab Inc.
Prisidio Components Inc.
Princeton Microwave Tech Inc.
Pulsar Microwave Corp.
O Microwave Q Microwave QinetiQ QUEST Microwave Inc. QuinStar Technology Inc. OWED R & K Company Limited Racal Instruments Raytheon RF Components Reactel Inc.
RelComm Technologies REMEC Inc. Remtec Inc. Renaissance Electronics Corp. Resin Systems Corp. RF Depot.com RF Design RF Industries RF Integrated Corp. RF Micro Devices RFHIC Richardson Electronics RJR Polymers Inc. RLC Electronics Inc. Rogers Corp. Roos Instruments Inc. Rosenberger Roswin Co. Ltd. Salisbury Engineering Inc. Sawcom Tech Inc. (STI) Sawtek Inc Scientific Microwave Corp. SDP Components Inc. Semflex Inc Semi Dice Inc. Sigma Systems Corp. Signal Technology

Simulation Technology & Applied Res Sinclair Manufacturing Sirenza Microdevices Skyworks Sonnet Software Inc. Sophia Wireless Inc. Soshin Electronics Southwest Microwave Spectra-Mat Inc. Spectrum Control Inc. Spectrum Elektrotechnik Gmbh Sprague-Goodman Electronics Inc.
SRC Cable Inc.
SSI Cable Corp.
SSPA Microwave Corp.
State Of The Art Inc.
Stellar Industries Corp. Stetco Inc Storm Products Storm Products
StratEdge Corp.
Sumitomo Electric USA Inc.
Sumitomo Metal (SMI) Electronics
Sunte Compound Semicond. Co.
SUSS MicroTec SV Microwave C.W. Swift & Associates Synergy Microwave Corp. Taconic Advanced Dielectric Tecdia Inc. Technical Research & Mfg. Inc. Tektronix Telegartner Inc Telephus Inc. Temptronic Corp. Temwell Corp. Tensolite Test & Measurement World Thales Components Corp.
Thin Film Concepts Inc. Thunderline-Z Times Microwave Systems TLC Precision Wafer Technology TRAK Communications Inc. Transcom Inc.
TransTech sub of Skyworks Solutions Trilithic Inc. TriQuint Semiconductor Tronser Inc. Tru-Connector Corp. TTE Inc.
A. J. Tuck Co.
U.S. Monolithics UltraSource Inc. United Monolithic Semiconductors UTE Microwave Inc. Vacuum Engineering & Materials Co. Vari-L Co. Inc. Vectron International Velocium, A TRW Company Vishay Electro-Films Voltronics Corp. VXI Technology Inc. A.T. Wall Company Wenzel Associates Werlatone Inc. Wessex Electronics Ltd. West Bond Inc. John Wiley & Sons Inc. WIN Semiconductors Corp. Wireless Design & Development WiseWave Technologies Inc. WJ Communications Inc. Xemod Xpedion Design Systems Xytrans Inc. Zeland Software Inc Zentrix Technologies Zeta Communication Systems/IDT ZIFOR Enterprise Co. Ltd

To request exhibiting information, please send your name, address, phone and fax number to: kdednah@mwjournal.com or fax to: 781-769-5037.



#### COMPONENTS

#### ■ Surface-mount Balun

This miniaturized version of the company's 2.4 GHz Xinger-brand surface-mount balun has an



insertion loss of 0.35 dB (max), making it an ideal companion for 802.11b and 802.11g access point and embedded WLAN chipsets. Other advantages include optimization for impedance matching and guaranteed

phase and amplitude performance.

Anaren Microwave Inc.,

East Syracuse, NY (315) 432-8909.

Circle No. 216

#### **DPDT Switch**

The model HMC436MS8G low insertion loss, +3 V double-pole double throw (DPDT)



switch is designed for 802.11a/HiperLAN WLAN and UNII point to-point/multipoint 5.1 to 5.9 GHz applications. It is an integrated antenna diversity and transmit/receive switch that provides 1 dB insertion loss while handling up to

+30 dBm RF input power from 0/+3 V DC control inputs. Port-to-port isolation is over 20 dB with better than 20 dB return loss on any port. Packaged in a low profile, 1 mm high 8 lead MSOP surface-mount package, the switch is ideally suited for 802.11a and access point front-end switching.

Hittite Microwave Corp., Chelmsford, MA (978) 250-3343.

Circle No. 218

#### **■ Single Layer Capacitors**

The Maxi-Plus Series of single layer capacitors exhibits a dielectric constant of 30,000. They



feature X7R temperature characteristics and are ideal for decoupling around electro-optical amplifiers and trans-im-

pedance amplifiers. The series is also designed to operate in the millimeter bands with an ultra low equivalent series resistance specifically for the RF/microwave, optical and cellular market. Exhibiting a very high or non-definable self-resonant frequency, these capacitors feature ultrawide band capabilities. The high dielectric constant featured in the Maxi-Plus Series allows for a compact package that is 60 percent smaller than previously offered packages. The series

features capacitance values from 100 to 10,000 pF. Typical measurement coefficient for these capacitors is ±15 percent over the operating temperature range from -55° to +125°C. Rated from 50 V, the series is offered in length and width size ranges from 0.010" to 0.100" with custom sizes available.

AVX Corp., Myrtle Beach, SC (843) 946-0414. Circle No. 217

#### **■ TETRA Hybrid Combiners**

The model WSC2-00015 and WSC4-00014 TETRA band high power transmit hybrid com-



biners allow either two carriers to be combined onto a single transmission line with the WSC2-00015 or four carriers with the WSC4-00014. With an operating frequency band of 380 to 430 MHz, these combiners offer

low insertion loss of 3.7 dB (max) (WSC2-00015) and 7.2 dB (max) (WSC4-00014) and high transmit input to input isolation of 40 dB (min) for the WSC2-00015 and 60 dB (min) for the WSC4-00014. Minimum power handling is specified as 25 W CW TETRA carriers per input for either 2:1 or 4:1 models. Passband return loss is specified at 15 dB (min) at all ports. Operating temperature range is -30° to +50°C. **K&L Microwave Inc.**,

Salisbury, MD (410) 749-2424.

Circle No. 219

#### **■ Capacitive Feedthrus**



These feedthrus are designed for eliminating noise and frequency interference in discoidal capacitance filtering applications such as in modulators, switches, amplifiers, filters, multifunction assemblies and other active devices. Utilizing premium glass and proprietary soldering techniques, the series of single pin design styles can be custom manufactured for unique applications up to 300°C. These hermetic capacitive feedthrus are designed to meet or exceed MIL-F-28861 by providing a guaranteed hermeticity of 1×E<sup>-8</sup> cc/sec at 1 atm or better. Capacitance values range from 5 to 27,000 pF with tolerances as tight as ±10 percent. They are ideal for designers seeking ultra-pure DC signals at higher frequencies. They eliminate the need for externally mounted capacitor chips, freeing board and/or package space.

Thunderline-Z, Hampstead, NH (603) 329-4050.

Circle No. 225

## **NEW PRODUCTS**

#### Mixer



The model M2-0243 mixer covers 2 to 43 GHz with a 400 MHz to 43 GHz IF. Designed for fiber-optic clock-recover/acquisition applications requiring an ultra-broadband IF, the unit is a unique triple-balanced mixer design, available in 2.92 mm connectorized outline. Local oscillator drive levels are +12 to +15 dBm. Typical conversion loss is 10 to 20 dB.

Marki Microwave Inc., Morgan Hill, CA (408) 778-4200.

Circle No. 221

#### ■ Semi-rigid Cable Connectors

These 2.8 mm male and female connectors are designed for RG-405 (0.085) semi-rigid cable.



Available in both direct solder or solder clamp attachment, these designs exhibit low SWR and perform to 40 GHz. Other 2.9 mm connectors are available for 0.085 low loss, 0.118 and 0.141

diameter semi-rigid cable. The connectors feature a DC to 40 GHz frequency range and SWR of 1.25 (max), and are air dielectric and mechanically compatible with SMA and 3.5 mm connector series.

S.G. McGeary Co., Rockledge, FL (321) 636-0909.

Circle No. 223

#### **BMA Connectors**

The BMA Series connectors feature a high integrity push-on SMA interface that is suitable



for dense modular connector arrays requiring fast and reliable connections. This line of high frequency BMA connectors has been expanded to fit many types of cables including semi-rigid sizes from 0.0865" to 0.1410" and flexi-

ble cables from 0.190" to .240" with crimp and solder attachment. The connectors accommo-

[Continued on page 122]

Patent Protected Technology

- Harmonic Tuners
- · High SWR (Prematching) Tuners
- Low Loss Test Fixtures
   On Wafer Solutions



**Our Technology stands out** 



At Focus, we have been developing and manufacturing Load Pull and Noise measurement systems since 1988. Nearly 1000 Focus tuners are serving in various R &D and production labs worldwide.

We use proprietary, patented designs and software. Our fundamental and harmonic programmable tuners reach from 0.2 to 110 GHz and have gained a reputation of precision and dependability. Over 120 application, product and technical notes support our products.

Focus is recognized for our Innovative Technology and Dedication to our Customer's needs. Because of our specialization in Load Pull and Noise

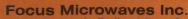
metrology we closely pursue our customer's requests and have always succeeded in providing solutions to their requirements.

Our staff of Engineers and Technicians will assist you through the entire process from the procurement to the installation and successful operation of your measurement system.

Focus system users tell us that our customer support has been a key selling feature when choosing our products.

Detailed information about Focus and its products can be found at:

www.focus-microwaves.com



1603 St. Regis Dollard-Des-Ormeaux, Montreal, Quebec H9B 3H7 Tel: 1(514) 684-4554 Fax: 1(514) 684-8581 Email: info@focus-microwaves.com

Click LEADnet at mwjournal.com or Circle 31 on Reader Service Card

# NEW PRODUCTS

date a maximum of 0.60" (0.120" custom) axial-and  $\pm 0.020$ " radial misalignment. Designed for DC to 22 GHz applications, these 50  $\Omega$  connectors have a 1000 Vrms dielectric withstanding voltage and 5000 megohms insulation resistance. Price: from \$12.45 each.

TRU Corp., Peabody, MA (800) 262-9878.

Circle No. 226

## **AMPLIFIERS**

#### ■ Power Thin Film Amplifier



The model AML618P3301 low noise, 1 W wide band amplifier operates in the 6 to 18 GHz frequency range and provides 33 dB (min) gain with an output power at 1 dB gain compression of +30 dBm (min). Noise figure is below 3 dB across the entire bandwidth. Input and output SWR is 1.8 nominal. Operating at +15 V DC this amplifier draws 1050 mA (typ) current. Internal DC regulator, reverse voltage protection and field removable SMA (f) connector shells are standard. Modules are also available as carrier mounted substrates. Size: 2.00" × 0.75". Delivery: 10 days (ARO).

AML Communications Inc., Camarillo, CA (805) 388-1345.

Circle No. 227

#### Low Noise Amplifier

The model NLC00361 low noise power amplifier is designed for mobile communications



systems operating from 1920 to 1990 GHz. The gain at room temperature is 25 dB with noise figure over operating temperature range of 1.2

dB (max). The output third order intercept point at 10 dBm output power/tone at room temperature is 35 dBm (min). 1 dB compression point at room temperature is 18 dBm (typ).

Nextec Microwave & RF Inc., Santa Clara, CA (408) 727-1189.

Circle No. 229

#### ■ Broadband Laboratory Amplifier

The model TPT5001200-6 broadband laboratory amplifier is a linear, class A lab unit cover-

ing 500 to 1200 MHz, producing a typical power of 38 dBm at 1 dB compression with 25 dB of gain. The 6 W amplifier offers typical IP3 of 48 dBm, input and output SWR < 2 and prime power of 110 V AC. Size:  $6.00" \times 5.50" \times 3.25"$ 

Transistor Power Technology Inc., Huntington, NY (631) 491-0265.

Circle No. 231

#### ANTENNA

# ■ Broadband Dual Linear Antenna

This broadband dual linear antenna was designed for polarization diverse applications. High power handling and good isolation help with power on target and good polarization purity. The antenna is capable of functioning in airborne environments without degradation. It features SWR of 2.5 (max), port-to-port isolation of 25 dB (min) and operates over the 6 to 18 GHz frequency range.

Nurad Technologies Inc., a division of Chelton Microwave, Baltimore, MD (410) 542-1700.

Circle No. 233

# INTEGRATED CIRCUIT

#### Quadrature Modulator

The model AD8349 I/Q quadrature modulator is designed to enable a single-stage upconver-



sion for wireless infrastructure equipment. The device covers the 800 MHz to 2.7 GHz band,

allowing designers to specify the AD8349, and to standardize on it across multiple operating bands and cellular standards. It is designed to ease direct upconversion for CDMA, WCD-MA, GSM EDGE and TDMA transmitters. A direct upconversion architecture significantly reduces the cost compared to traditional multistage IF approach. The noise floor is specified at -156 dBm/Hz and the PldB output compression point is specified at +5 dBm, thereby allowing the user to attain a higher output for a given adjacent channel power. With improved quadrature accuracy of 0.2 dB and phase balance of 0.5°, this component achieves a sideband rejection of -42 dBc. Price: \$4.50 (10.000)

Analog Devices Inc., Norwood, MA (800) 262-5643.

Circle No. 234

#### **MATERIALS**

#### ■ High Reliability, FR-4 Epoxy Material

The N4000-11 series of laminate and prepreg materials are being introduced to provide printed circuit board fabricators with a nextgeneration, high Tg FR-4 product that is designed to meet the difficult performance specifications currently being proposed by a variety

of multinational OEMs. The N4000-11 is designed to provide a conductive anodic filament resistant, dimensionally stable material with superior thermal performance. With a Tg of 175°C, these materials are designed for use in a broad range of printed circuit board applications requiring very low Z-axis expansion, outstanding thermal stability and superior holewall integrity. The material also features improved process latitude when compared to similar high Tg dielectric materials currently under investigation for their thermal superiority. This material set is recommended for high density designs in the network storage, telecommunications infrastructure, enterprise server, and Internet connectivity segments.

Park Electrochemical Corp., Lake Success, NY (516) 354-4100.

Circle No. 235

#### ■ Copper-manganese-nickel Alloy

Wieland-LV7 is a copper-manganese-nickel alloy with an almost silvery color. Its chemical composition is Ni 20 percent, Mn 20 percent and Cu balance. The material has a good corrosion resistance (comparable to lead-free nickelsilvers) and excellent formability, joining (brazing, soldering) and plating characteristics. High strength and outstanding spring properties are achieved by special heat treatment. Stress relaxation at 150°C is less than 20 percent. It is also cost-effective, and ideal for special electrical applications such as high frequency connectors. *Wieland Werke AG*,

Ulm, Germany +49 (0) 741 9440.

Circle No. 236

#### SERVICE

#### Aluminum Nitride Clean Via Technology

This newly developed process renders laser drilled vias in aluminum nitride (AlN) slag-



free. Clean Via Technology (CVT™) creates a perfectly clean AlN grain structure on laser drilled via walls. Exposing this vir-

gin grain structure provides strong mechanical footholds as well as a chemically active surface for chemical bonds. This proprietary process makes it possible for both thick and thin film circuit manufacturers to use laser drilled AlN with a degree of success previously not possible.

P/M Industries, Portland, OR (800) 462-0439.

Circle No. 237

### SOFTWARE

#### Simulation Software

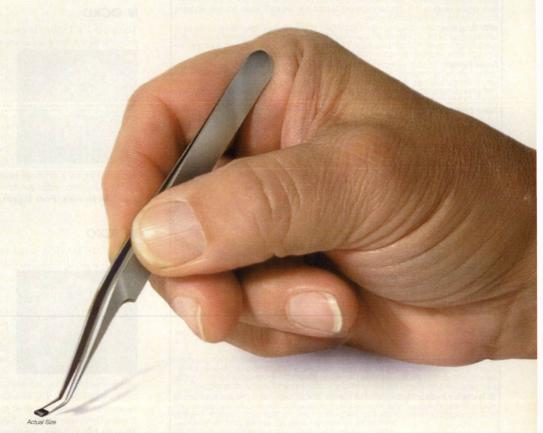
Version 1.1 of APLAC Simulation Builder (ASB) is designed for the Mentor Graphics design frameworks. It enables seamless cooperation of the APLAC Simulator and Mentor Graphics Design Architect, RF Architect and PowerLogic. ASB connects directly to frame-

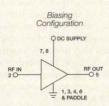
[Continued on page 124]

# MNA AMPLIFIERS

MMICs from 500MHz to 5.9GHz \$ 35

as low as ea.(gty. 1000)





## Built-In RF Choke, Resistors, Bypass & Coupling Capacitors

Simplify your 500MHz to 5.9GHz designs with Mini-Circuits easy to use MNA amplifiers. With DC blocking capacitors and a biasing network builtin, all you do is drop the amplifier in place on your PC board, connect, and the job is done! There's no biasing to figure out and no external components to connect. Broadband, low and high power models offer 10 to 23dB (typ) gain, 7 to 18dBm (typ) power output, and more than 40dB isolation, which makes them terrific for use as an isolator. But these

amplifiers go on to feature a minuscule 3x3mm MCLP™ SM package with exposed metal bottom for excellent grounding and heat dissipation. If

you're looking for versatility, MNAs operate from a +5V to 2.8V DC supply, making them indispensable for use in today's miniature battery operated hand-held devices. And if you're looking for value, prices start from only \$1.60 ea. (qty. 30). So simplify your design, your manufacturing, and your life with Mini-Circuits all-in-one MNAs!

MNA-2         0.5-2.5         5.0 2.8         12.8 11.5         12.9 1.90           MNA-3         0.5-2.5         5.0 16.2 9.7         16.4 12.9           MNA-4         0.5-2.5 5.0 16.6 17.0 19.0         17.0 19.0           MNA-5         0.5-2.5 5.0 22.8 14.6 13.4 10.1         10.1 10.1           MNA-6         0.5-2.5 5.0 23.5 18.0 2.5         18.0 2.25           MNA-6         0.5-2.5 5.0 23.5 14.1         14.1 2.25           MNA-7         1.5-5.9 5.0 17.2 15.6 2.25           2.8 21.5 15.4 12.7         12.6 2.25	MODEL	Freq. (GHz)	DC Volts (V)	Gain Midband (dB) Typ.	Pwr. Out 1dB Comp. (dBm) Typ.	Price \$ea. (qty.30)
MNA-5 0.5-2.5 5.0 16.6 17.0 1.90 MNA-5 0.5-2.5 5.0 22.8 14.4 10.1 1.60 MNA-6 0.5-2.5 5.0 22.8 12.2 1.60 MNA-6 0.5-2.5 5.0 22.8 21.4 10.1 1.60 MNA-6 0.5-2.5 5.0 22.8 21.4 10.1 2.25 MNA-7 1.5-5.9 5.0 17.2 15.6 2.25	MNA-2	0.5-2.5				1.90
MNA-4 0.5-2.5 2.8 14.6 13.4 1.90  MNA-5 0.5-2.5 5.0 22.8 12.2 1.60  MNA-6 0.5-2.5 5.0 22.8 21.4 10.1  MNA-6 0.5-2.5 5.0 22.8 21.5 14.1  MNA-7 15-5.9 5.0 17.2 15.6 2.55	MNA-3	0.5-2.5				1.60
MNA-6 0.5-2.5 5.0 23.5 18.0 2.25 MNA-7 15-5.9 5.0 17.2 15.6 2.55 MNA-7 15-5.9 5.0 17.2 15.6 2.55	MNA-4	0.5-2.5	212			1.90
MNA-7 1.5-5.9 5.0 17.2 15.6 2.25	MNA-5	0.5-2.5				1.60
	MNA-6	0.5-2.5				2.25
	MNA-7	1.5-5.9				2.25

Amplifier Designer's Kits
K1-MNA: 10 of ea. MNA-2, 3, 5, 6...\$69.95
K2-MNA: 10 of ea. MNA-2, 3, 4, 5, 6, 7...\$99.95
Application note for PCB layout included.

Detailed Performance Data Online at: www.minicircuits.com/amplifier.html



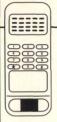




CIRCLE READER SERVICE CARD

P.O. Box 350166, Brooklyn, New York 11235-0003 (718) 934-4500 Fax (718) 332-4661 For quick access to product information see MINI-CIRCUITS CATALOG & WEB SITE

The Design Engineers Search Engine Provides ACTUAL Data Instantly From MINI-CIRCUITS At: www.minicircuits.com



## ... Your Career

Director of Engineering: A manufacturer of RF/Microwave components in the DC-60 GHz range, is looking for a seasoned, degreed and energetic Microwave Engineer to run a developmental team. Responsibilities include the creation of new products and the administration of the Engineering Department. Experience should include the design-for-production of Microwave & RF Filters.

Regional Sales Manager: The position entails planning the growth within the designated sales territories, aggressive customer interaction, including quotation follow-ups, and all phases of account service. Approximately 20% travel expected as well as the management of outside sales representatives. The company supports the selling function with engineering expertise and a high level of consistent quality.

Product Engineer: Responsible for performing complete electrical characterization on new products including worst-case analysis, resolve correlation issues, support on-going sample test, set specification compliance matrix, monitor product flow, work on yield improvements and maintain up-to-date documentation. Re quires BSEE/MSEE with 3 to 5 years experience as a product engineer. Experience in RF design/product/applica

Process Engineer-III-V Material: Responsible for fabrication and monitoring progress of HEMT/wafer lots, in-cluding making pass/fail decisions. Develop new processes by running fabrication experiments including Stepper Lithography, Etching, E-beam Metallization, Dielectric Deposition and Annealing for HEMT devices and circuits. Assist with process documentation and test database management. Demonstrated capability to develop photolitho-Assist will processes, processing experimentation and experience with managing process flow. Minimum BS +2–5 years of experience or MS +0–3 years of experience in semiconductor device fabrication/process development preferred. Degrees should be in EE, Chemical Engineering, Materials/other Physical Sciences. Familiarity with testing and interpretation of test results of FETs a plus.

RFIC Designers: Hands-on engineers specializing in GaAs, Si, SiGe etc. circuit design. Design centers are located throughout the US and internationally. The companies we represent will sponsor clitzenship. All our client companies are successful RFIC technology leaders. All levels of engineering technology positions are open. Design, applications, project engineering, manufacturing/production. BSEE or equal experience minimum.

Device Engineer: The position is responsible for designing GaN-based HEMTs. Working closely with wafer pro cessing engineers and product engineers, the Device Engineer translates product requirements into HEMT designs using available process rules. Extraction of linear and nonlinear device models. Analysis of DC, microwave and thermal characterization data to optimize device design. Design of process control monitor (PCM) structures. Inter-face with CAD engineer in layout and mask generation.

Power Amplifier IC Design Engineer: Responsible for carrying a design from concept through manufacturing and providing sufficient engineering documentation to fully describe the circuit, specifications and performance Requires BSEE/MSEE with 5 to 10 years commercial design experience, preferably dealing with power amplifiers experience with Silicon Bipolar, GaAs MESFET, or GaAs HBT integrated circuits; familiarity with test equipment required for amplifier test and characterization; and experience in wireless systems such as cellular, cordless or ISM band equipment.

Principal Engineer Power Amps: Principal Engineer, with minimum 10 years experience designing high power RF Amplifiers using GaAs FETs, HBTs and LDMOS from 2 to 10 GHz, with power levels of 10 to 300 W for commercial amplifiers. Circuit design and simulation background using Agilent ADS or Microwave Office. Demonstrated expertise in the field. Prefer experience with Linear PAs: feedforward, predistortion for CDMA, W-CDMA. Must have the ability to lead a team. MSEE/PhD.

Antenna Design Manager: Microwave antenna systems company, concentrating on advanced technology prod-ucts for the wireless communications industry, is seeking a talented RF Engineer to lead its team. This hands-on posi-tion requires a minimum of 5 years practical design, test and analysis experience. Responsibilities include design, test and development of existing and future products.

SR Staff T/R Modules: You will join a development team designing microwave monolithic transmit/ modules. Qualified applicants will have experience in microwave receiver technology, specifically in GaAs FET MMIC applications. Requires a BSEE (MSEE preferred) and 5+ years directly related experience.

Sr. MMIC Design: Design highly integrated GaAs MMICs for advanced cellular products. Circuits to be designed include: power amplifiers, chiver amplifiers, LNAs, mixers, IF amplifiers, buffer amplifiers. RF frequencies are 900 and 1800 MHz. Circuitry will be designed for advance MMIC wafer process technologies.

Regional Field Sales: Aggressive individuals to create and serve new accounts. Positions are located throughout the U.S.A. An engineer who wants to enter sales world is acceptable. Base salary, commission and car. With experience with one of the following: LNAs, VCOs, power amps, mixers and frequency synthesizers.

Filter Design Engineer: MS. Minimum 3 years experience in the design and development of Broad Band comb-line, strip line, interdigital, low pass and high pass filters, multiplexers, diode switches (phase shifters) at tenuators and microwave subsystems desirable.

Senior RFIC Design Engineer (Tx/Rx): Responsible for all phases of the product development from product definition to device qualification of the RF and mixed signal functions included in highly integrated, low-power, low-voltage wireless transceivers (transmitter and receiver). Activities include system study, architectural definition block specification and the detailed circuit design including simulation, layout and laboratory characterization.

Sr. Synthesizer Engineer: The ideal candidate will have a BS in Electrical Engineering and five years experience in the 5.5. Symmesizer Engineer: The local canodials with lave a St in Econocial Engineering and the years expensive in design of RF and microwave symbesizer products. In particular, he or she should have hands-on design experience with VCOs, frequency/phase detectors, dividers, phase lock amplifiers, mixers, quadrature search circuitry, combine filter and multipliers. Familiarity with design techniques that permit low microphonics and minimum phase hits are a must. In addition, experience in the use of commercial commercial control of the production of the production

cial and/or custom PLL chips and microcontrollers would be an advantage.

cial and/or custom PLL chips and microcontrollers would be an advantage. Applications Engineers: Responsible for providing customers with RF technical product support at the RF system and component level; participating with new standard and custom RFIC product development; developing application notes and data sheets. Requires BSEF/MSEE with minimum 3 years RF design/product experience, strong RF/Microwave measurement skills; design experience with analog and digital modulation schemes (AMPS, GSM, TDMA, CDMA); strong written and customer relation skills.

Principal Analog/Mixed Signal IC Design Engineer: Lead projects from product definition to production release. BSEE, MSEE 7+ years experience in analog/mixed signal IC design. Lead design engineer in the development of highly integrated analog/mixed signal IC solutions for wireless and broadband telecom applications. Specific experience in CMOS/BiCMOS design with development of PLL/frequency synthesizers, A/D and D/A converters and continuous time filters desirable.

Senior RF IC Design Engineer: BSEE, MSEE. 10+ years experience in integrated circuit development with 5 years in RFIC development. Prefer experience in Si, GaAs and CMOS. Demonstrated record of product development success. Specific experience in LNAs, mixers, up and down-converters, filters and AHDL models is desired Experience with products for CDMA, GSM, DECT, Bluetooth or other wireless applications highly desirable.

VISIT OUR WEBSITE AT WWW.MICSEARCH.COM

#### COMMUNICATIONS **EXECUTIVE SEARCH**

We specialize in the placement of wireless, RF, microwave communications professionals both nationally and internationally

35 New England Business Center Ste. 205 Andover, MA 01810 Call Collect: Tel: (978) 685-2272 • Fax: (978) 794-JOBS

## **NEW PRODUCTS**

works schematic database, and reads out netlist information that can be completely tailored to create a specific netlist. The software features multiple mapping library support, better mapping error reporting, support for measurement templates and an online help system. With its foundation on proven PCB design systems, ASB eliminates additional interfaces, database conversion and error prone manual re-design of RF blocks.

APLAC Solutions Corp., Helsinki, Finland +358-9-54045000.

Circle No. 238

#### SOURCES

#### OCXO

The model FTS501AH oven compensated crystal oscillator (OCXO) meets stratum level accuracy requirements for telecommunications ap-



plications, making it ideal for use in base stations, telecom switching, GPS and LAN/WAN applications as well as in test and satellite equipment. It offers a frequency stability of ±250 ppb over the 0° to 70°C temperature range and an overall accuracy of ±4.6 ppm for all conditions over 10 years. The frequency range of the new OCXO is 10 to 40 MHz. Supply voltage is 5.0 V, with 3.3 V available, and control volt-

age is 0.5 to 5.0 V. Storage tmperature range is -40° to +85°C. Price: \$68 (1000). Delivery: eight weeks (ARO).

Fox Electronics, Fort Myers, FL (888) 438-2369.

Circle No. 240

#### TCXO

The VC-TCXO HFX series temperature-compensated crystal oscillator (TCXO) is designed to increase performance for GSM and CDMA prod-



ucts. The small size, coupled with several new features, enables engineers to produce high performance compact designs for GSM and CDMA products, such as mobile phones and handheld devices. The series also employs analog transistors to reduce phase noise, which improves effective data rates on handsets. The frequency in production has also been trimmed, yielding

high accuracy rates. Additional benefits include low current consumptions and a built-in DC blocking capacitor. The series also features measurement technology that guarantees more temperature points for greater frequency stability. Size: 3.2 × 2.5 × 1.2 mm.

Murata Electronics, Smyrna, GA (770) 436-1300.

Circle No. 242

#### S-band VCO

The model V844ME02 S-band VCO is designed for the point-to-point radio market. This device covers from 3430 to 3610 MHz within 0.5 to



4.5 V DC of control voltage while covering 180 MHz bandwidth with an average tuning sensitivity of 87 MHz/V. The VCO also realizes spectral purity of -88 dBc/Hz (typ) at 10 kHz from the carrier. It will strengthen any phase-locked loop (PLL) with its 1.1:1 linearity over frequency and temperature and suppresses the second harmonic to better than -15 dBc. The V844ME02 draws 18 mA off a 5 V DC supply and furnishes the end user with 2.25±1.25 dBm of output power into a 50  $\Omega$  load and is guaranteed to operate over the extended commercial temperature range of -40° to +85°C. It is fur-

ther heightened by pushing less than 1 MHz within 5 percent of the nominal supply voltage and pulls less than 8 MHz with a 14 dB return loss, any phase. Size: 0.50" × 0.50" × 0.13". Price: \$15.95 each.

Z-Communications, San Diego, CA (858) 621-2700.

Circle No. 244

E-Mail: nicsearch@

aol.com

#### ■ Phase-locked Oscillator

This 20 GHz phase-locked oscillator locks to a 5 MHz reference input in a single loop. Its low power consumption, along with its compact size, sturdy structure and low phase noise offer an attractive solution for various defense applications. The unit offers 20 GHz output frequency, +12 dBm (min) output power, an operating temperature range from  $-45^{\circ}$  to +75°C, +12 to +24 V DC, < 400 mA power consumption and < -120 dBc phase noise at 100 kHz offset. Size:  $2.25^{\circ} \times 2.25^{\circ} \times 0.62^{\circ}$ .

Elcom Technologies Inc., Rockleigh, NJ (201) 767-8030.

Circle No. 239

#### **SUBSYSTEMS**

#### ■ Solid-state Power Supply

The PowerMod™ high voltage, solid-state power supply combines reliable switching



technology at high voltage and high power in a rack-mount unit for use in manufacturing and laboratory applications. It features up to 200 kHz switching speeds

with < 1 percent voltage regulation, < 1 percent ripple and maintains regulation when the load is changing. Capable of operating in constant voltage mode, constant current mode, or constant power mode, this switching power supply is offered in 30 and 40 kW 19" units. Providing full over-voltage and over-current protection and high immunity for operation near pulse discharges, the PowerMod supports demanding applications such as magnet control, ion implantation, magnetron heating, lasers, electron beams and RF transmitters. Price: \$36,000 (30 kW) and \$50,000 (40 kW).

Diversified Technologies Inc., Bedford, MA (781) 275-9444.

Circle No. 245

#### ■ Low Profile Power Supply



This new series of the company's PowerBank family of low profile power supplies adds power-factor correction capability. From inputs of 115/230 V AC, it provides up to six configurable main outputs and two low power auxiliary outputs. Designated PowerBank PB15056PFC, output power is 1200 W at 110 V AC and 1500 W at 220 V AC. This unit is designed with 19" rack applications in mind, but it can also be used as a stand-alone box. Many mounting options make it suitable for a variety of applications. Internal fans provide cooling. Size: 16.84" × 12.60" × 1.75". Price: \$1.42/W (100). Delivery: one to eight weeks.

Northwest Power Integrations (NPI), a Vicor Integrations Architect, Milwaukie, OR (503) 652-6161.

Circle No. 247



Circle 22

# 

Circle 84

# Powerful Performance Precision Technology

(631) 242-2300 • FAX: (631) 242-8158
REQUEST YOUR "RF SWITCH SLIDE GUIDE" TODAY!

Circle 85

SWITCH OVER TO:

SECTOR MICROWAVE INDUSTRIES, INC.

**WAVEGUIDE & COAXIAL** 

SWITCH SPECIALISTS

**Retary Step Attenuators** 

Excellent Repeatability and Switch Life Flexible Design Configurations Very Competitive Prices High Accuracy Wide Frequency

Contact Us for Off-the-shelf & Custom Needs 800-344-2412 317-895-3600

Low VSWR





www.TrilithicWireless.com

Circle 95



#### Personal Probe Station

Very Low Cost High Function

A compact full featured, modestly priced, manually operated probe station developed for engineers and scientists.

Measure Microwave, RF and DC parameters of Semiconductor Devices, Packages and Assemblies with NIST traceability.

- BenchtopSize(<1ft²) Vacuum chuck X-Y-Ø stage •
   X-Y-Z probe positioners Top Plate Z-lift Vacuum Accessory Manifold •
- 7x-40X Stereo Zoom Microscope Adjustable Halogen Illuminator •
   Vacuum Accessories Compatible with 40GHz+ probes •
- Adapter Kits for Thermal Chucks and Probe Cards
   Test wafers, substrates, packages and surface mount components

Jmicro Technology

J microTechnology 3744 NW Bluegrass Pl Portland, OR 97229 (503) 614-9509

A Probe Station On Every Bench





To see one's work in print is the rightful reward of every creative engineer and scientist. The editors of Microwave Journal invite you to submit your technical manuscripts for consideration to be published in one of our upcoming issues. Technical articles, application notes and tutorial articles based on the monthly editorial themes are encouraged. Editorial themes include wireless, radar and antennas; RF components and systems: test and measurement; amplifiers and oscillators; semiconductors and MMICs; commercial applications; IVHS and ITS; dual technologies; communications and PCN; passive components; and control devices, modulation and DSP.



Design features should contain new and innovative technical ideas of practical use and interest to our predominantly engineering readers. Papers should be 14 to 16 double-spaced pages and contain 8 to 12 visual aids in the form of sketches, graphs, photographs or tables.

Papers should be submitted to the attention of the Technical Editor and will be reviewed promptly by our Editorial Review Board prior to acceptance. Articles outside of the monthy themes also will be considered.

SEND ALL MATERIAL TO:

Microwave Journal
685 Canton Street
Norwood, MA 02062
(781) 769-9750
Fax (781) 769-5037
e-mail fbashore@mwjournal.com



## DC/DC CONVERTER GUIDE

This 29-page catalog is completely user/applications-oriented. Each of 425 standard products is listed according to its output configuration (single, dual, triple, etc.), its output voltage (from 1 to 48 V), its output current (up to 40 A), its input voltage range (typically centered around 3.3, 5.0, 12.0, 24.0 or 48.0 V) and then its package.

DATEL Inc., Mansfield, MA (508) 339-3000.

Circle No. 200

#### PRODUCT BROCHURE

This brochure features the company's model ELCO-MPR-208/408-00 wideband VCO. The VCO tunes a 2000 to 4000 MHz octave from 0 to 24 V. Product information including common instrumentation/telecommunications specifications, packaging information and performance characteristics are included.

Emhiser Micro-Tech, Reno, NV (775) 345-0461.

Circle No. 201

## RFIC/MMIC PRODUCT SELECTION GUIDE

This selection guide contains a reorganization of over 190 products by market segments, broadband DC-6 GHz, cellular/PCS/3G, microwave/millimeter-wave and fiber optics. Application block diagrams, package information and a new section entitled "Specialty Products" are also included.

Hittite Microwave Corp., Chelmsford, MA (978) 250-3343.

Circle No. 202

# POWER SUPPLY CATALOG AND HANDBOOK

This 164-page power supply catalog features a revised and updated applications handbook and glossary, as well as full specifications on the company's current products. Included are specifications of many new products, including bipolar, four quadrant power supplies.

Kepco Inc., Flushing, NY (718) 461-7000. Circle No. 203

## MILLIMETER-WAVE TECHNOLOGY AND SOLUTIONS

This 41-page catalog features the company's millimeter-wave products and services, such as: antennas and quasioptical products, mixers and detectors, oscillator and amplifier products, multiplier products, control components, filters and ferrite products, passive waveguide products, and test and measurement products. *Millitech LLC*,

Northampton, MA (800) 664-5548.

Circle No. 204

#### CD-ROM CATALOG

This CD-ROM catalog includes new products, updated datasheets with more comprehensive information and measurement curves, application notes, and a complete listing of the company's international sales representative network.

Mimix Broadband Inc.,

Webster, TX (281) 526-0536.

Circle No. 205

## **NEW LITERATURE**

#### LC AND CRYSTAL FILTERS BROCHURE

This brochure features an extensive line of cost-effective crystal filters in all polynomials from 100 kHz to 300 MHz with fractional bandwidths of 0.002 to 3 percent, LC RF filters in all polynomials from 1 kHz to 2.5 GHz, and crystal-based frequency discriminators from 100 kHz to 80 MHz.

Network Sciences, c/o Sierra Microwave Marketing Technology, Citrus Heights, CA (916) 339-0170.

Circle No. 206

# ANALOG/MIXED SIGNAL FOUNDRY SERVICES BROCHURE

This four-page brochure is an easy reference guide for companies that are evaluating out-sourced foundry services to reduce the time-to-market volume to bring new products to market. The company's history and core competencies are also included as well as a brief overview of the bipolar and BiCMOS wafer fabrication technologies.

PolarFab, Bloomington, MN 55425.

Circle No. 207

#### ■ BROADBAND WIRELESS COMPONENTS

This 132-page product catalog for microwave components provides information on the company's products, including detailed data sheets on mixers, VCOs and microwave frequency sources for commercial telecommunications, instrumentation, defense and space applications.

REMEC Broadband Wireless, Milpitas, CA (408) 432-9898.

Circle No. 208

#### SPECIALTY MATERIALS BROCHURE

This new product capabilities brochure offers an array of specialty materials including high frequency circuit materials, laminates, photoimageable covercoats, high performance foams, busbars, EL lamps and drivers, elastomer components, nitrile floats, nonwoven materials, and moldable composite materials.

Rogers Corp., Rogers, CT (860) 774-9605. Circle No. 209

#### **CONNECTORS CATALOG**

The connectors featured in this catalog offer a high contact reliability due to their design and the selection of materials as well as their surface treatment, providing excellent corrosion resistance. For all connector sizes listed the company supplies measuring equipment, including directional couplers, terminations, attenuators, high power loads as well as switches.

Spinner GmbH,

Munich, Germany +49 89 126 01 257.

Circle No. 210

#### **ENGINEERING BULLETIN**

The engineering bulletin (SG-207F) describes the company's line of microwave Sapphire PIS-TONCAP® trimmer capacitors. It adds data for a new wide lead version of the vertical surfacemount series. The other series include two configurations and five more mounting styles to suit all RF structures.

Sprague-Goodman Electronics Inc., Westbury, NY (516) 334-8700.

Circle No. 211

# MDD FIBER OPTIC LINK

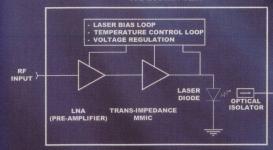
# 11 GHz Direct Modulation Microwave Fiber Optic Link

- Small Size
- Bandwidth to 11 GHz
- Low Noise Figure
- Plug-In Optical Connector
- No External Control Circuits Required
- Custom Configurations Available

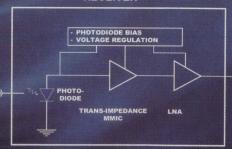
# **Applications Include:**

- Antenna Remoting
- Local Oscillator Remoting
- Interfacility Communication Links
- Aircraft and Shipboard

#### TRANSMITTER



RECEIVER



For additional information, contact

Dan Sundberg at (631) 439-9269 or e-mail dsundberg@miteq.com

OPTICAL FIBER



100 Davids Drive Hauppauge, NY 11788 TEL.: (631) 436-7400 • FAX: (631) 436-7430

miteq.com

₹ RF



## THE BOOK END

# Wireless Communications — Principles and Practice, Second Edition

Theodore S. Rappaport
Prentice Hall PTR
707 pages; \$92
ISBN: 0-13-042232-0

The second edition of this book has been written to initiate the newcomer to wireless personal communications, one of the fastest growing fields in the engineering world. Technical concepts which are at the core of design, implementation, research and invention of wireless communication systems are presented in an order that is con-

"...this book has been written to initiate the newcomer to wireless personal communications..." ducive to understanding general concepts, as well as those specific to current and evolving wireless communication systems and standards. The text continues to evolve and has been updated and modified since its first edition, making it a useful book for practicing engineers, as well as for researchers, and graduate and

undergraduate students. The second edition contains dozens of new homework problems and examples, as well as up to the minute technical details of the many emerginal and the state of the many emerginal and the state of the sta

ing wireless standards throughout the world.

Chapter 1 demonstrates the historic evolution of the wireless communication industry and documents the rapid growth of cellular radio. Chapter 2 provides an overview of the major modern wireless communication systems of the 21st century. Chapter 3 covers the fundamental cellular radio concepts and demonstrates the principle of trunking efficiency. Chapter 4 presents radio propagation path loss, link budgets and log-normal shadowing. Chapter 5 covers small-scale propagation effects such as fading, time delay spread and Doppler spread. Chapter 6 provides extensive coverage of the most common analog and digital modulation techniques used in wireless communications and demonstrates tradeoffs that must be made in selecting a method. Channel coding, adaptive equalization and antenna diversity concepts are presented in Chapter 7. Chapter 8 provides an introduction to speech coding. Chapter 9 introduces time, frequency and code division multiple access as well as more recent multiple access techniques such as packet reservation and space division multiple access. Chapter 10 describes networking considerations for wide area wireless communication systems. Chapter 11 unites all the material from the first nine chapters by describing and comparing the major existing, second generation cellular, cordless and personal communication systems throughout the world.

To order this book, contact: Prentice Hall PTR, Upper Saddle River, NJ 07458 (800) 922-0579.

#### Feedforward Linear Power Amplifiers

Nick Pothecary
Artech House Inc.
204 pages; \$99, £73
ISBN: 1-58053-022-2

With the evolution of existing and new standards for mobile communication systems and wireless multimedia services, the quantity and complexity of the signals to be transmitted from a single location is increasing. There is a growing need for amplifiers that amplify all types of signals without adding significant distortion and are capable of operating over a wide bandwidth at potentially high levels of output power.

The general subject of this book is linear amplification for radio frequency transmitters. Specifically, the book is concerned with the use of feedforward as a linearization technique for radio frequency power amplifiers and is primarily aimed at engineers and technicians but is suitable for anyone wishing to learn about linear amplifiers in gen-

eral, and feedforward in particular.

Chapter 1 begins with an overview of feedforward techniques and includes an introduction to a typical radio system for cellular, PCS, or IMT-2000/UMTS systems. Some con-

cepts specific to operation at radio frequencies are also discussed. In Chapter 2, a mathematical-based approach is used to discuss amplifier input-output characteristics, signal modulation formats, signal envelopes, peak-to-average ratios and statistical analysis. Power amplifiers and system design are discussed in Chapter 3; topics include

"The general subject of this book is linear amplification for radio frequency transmitters."

transistors for RF power amplifiers, amplifier efficiency and class of operation, intermodulation performance and system design issues such as combining RF signals. The concept of a linear amplifier is introduced and practical examples are given for different system configurations. Chapter 4 reviews different linearization techniques including feedback (RF feedback, envelope feedback, Cartesian loop and polar loop feedback), RF synthesis, envelope elimination and restoration, predistortion and feedforward. The discussion on feedforward includes the principles of operation, signal cancellation and loop control; dual-loop feedforward is also described. In Chapter 5, a detailed analysis of feedforward performance is given, with topics such as gain, input/output match, noise figure, broadband signal cancellation, error amplifier performance and system efficiency.

To order this book, contact: Artech House Inc., 685 Canton St., Norwood, MA 02062 (781) 769-9750 ext. 4002; or 46 Gilligham St., London SW1V 1HH,

UK +44 (0) 207 596-8750.

Dan Massé

Dan Massé is a member of the Microwave Journal staff.

# To live well,

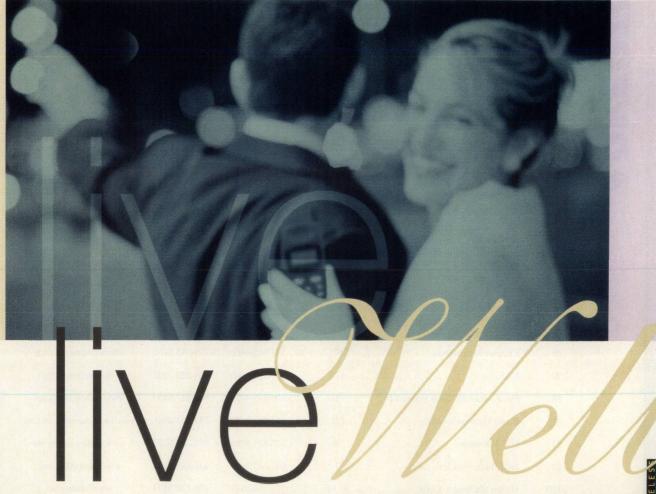
24 carat, first-class, top drawer, "I'll take them both" well. You have to work for it.

In wireless that means knowing what's hot and happening on the horizon; gizmos that would make James Bond's head spin. One show, CTIA WIRELESS, with over 1,000 exhibitors, has more wireless and mobile computing product announcements than any other.

Whether you have seen it on BBC, CNN, in the Wall Street Journal, Wireless Week & RCR-when it's news in wireless, it's out of CTIA WIRELESS.

Cashmere, silk, mahogany, platinum, single malt. Distinctions of living well. Miniature, sleek, sexy, connected, multi-functional. Distinctions of how wireless makes it possible.

CTIA WIRELESS 2003 is where you start.



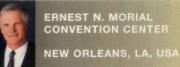
CTIAWIRELESS 2003

March 16, 2003 \* Pre-Convention Seminars

March 17-19, 2003 \* Exhibits, CTIA Educational Sessions & Special Interest Seminars

www.ctiashow.com Register NOW and save up to \$345





# ADVERTISING INDEX

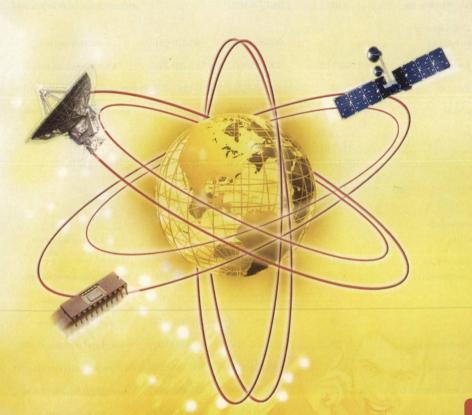
CIRCLE NO.	Advertiser	PAGE No.	PHONE	FAX	Web/E-Mail Address
1	Agilent Technologies Inc	COV 2	800-452-4844	415-857-5518	www.agilent.com
2	AML Communications	28	805-388-1345	805-484-2191	www.amlj.com
3	Amplifier Research	44	215-723-8181	215-723-5688	www.amplifiers.com
4	Anaren Microwave	57	800-411-6596	315-432-9121	www.anaren.com
5	Ansoft Corp	71,72–73	412-261-3200	412-471-9427	www.ansoft.com
6	Applied Wave Research Inc	116	310-726-3000		www.appwave.com
7,8	Artech House	70,98	800-225-9977	781-769-6334	www.artechhouse.com
9	Atlantic Microwave Ltd	88	.44-1376-550220	44-1376-552145	e-mail: sales@
					atlanticmicrowave.co.uk
10	BroadWave Technologies		317-346-6101	317-346-6995	www. BroadWaveTechnologies.com
11,12	Cascade Microtech	COV 4	503-601-1000	503-601-1002	www.cascademicrotech.com
13	Chin Nan	54	886-6-2678303	886-6-2678337	www.chinnan.com.tw
14	Com Dev Saw Products	34	647-887-SAWS	519-622-1691	www.saw-device.com
15	Corning-Gilbert	32	800-651-8869		www.corning.com/corninggilbert
16	CTIA WIRELESS	129	202-736-3664	202-785-0721	www.ctiashow.com
17	CTT Inc		408-988-2999	408-986-9097	www.ettinc.com
18	DBP Microwave				
	(formerly DB Products Inc.)	17	626-449-3790	626-449-7169	www.dbp4switches.com
19,20	Delta Microwave			805-240-9544	www.deltamicrowave.com
21	Ducommun Technologies Inc		310-513-7200	310-513-7298	www.ductech.com
22	Dvina Co LTd	125	.886-2-2683-7387	886-2-2682-2039	http://netcity.hinet.net/dvina
23	Dynawave		978-469-0555	978-521-4589	www.dynawave.com
24	Eagleware Corp		678-291-0995	678-291-0971	www.eagleware.com
25	EiC Corp	78	510-979-8999	510-979-8902	www.eiccorp.com
26	Elektrobit Ltd		.358-40-344-2000	358-8-551-4515	www.elektrobit.com
27	EMC Technology Inc	15	856-429-7800	856-429-6814	www.emct.com
28	Emhiser Micro-Tech	87	775-345-0461	775-345-1152	www.emhiser.com/vco
29	Endwave	110	408-522-3100	408-522-3102	www.endwave.com
30	Environmental Stress Systems In	c	800-735-6473	800-317-8430	www.esshotplates.com
31	Focus Microwaves Inc	121	514-684-4554	514-684-8581	www.focus-microwaves.com
32	G.T. Microwave	76	973-361-5700	973-361-5722	www.gtmicrowave.com
33	GGB Industries Inc	3	941-643-4400	941-643-4403	www.picoprobe.com
34,35	Hittite Microwave Corp	51,81	978-250-3343	978-250-3373	www.hittite.com
36	Huber + Suhner AG		41-71-353-41-11	41-71-353-45-90	www.hubersuhner.com
	IEEE MTT-S International Microwave Symposium	119	781-769-9750	781-769-5037	www.ims2003.org
37	ITT Industries, Microwave Systems	79	978-441-0200		www.ittmicrowave.com
38	ITU-Shows	101	+41 22 730 6161	+41 22 730 6444	www.itu.int/world2003
39	ITU-Shows		+41 22 730 6161	+41 22 730 6444	www.itu.int
40	J microTechnology	125	503-614-9509	503-531-9325	www.jmicrotechnology.com



The trade show dedicated to radiofrequencies, microwaves, wireless, optical fibre and their applications.

# EUROPE

# A strategic gathering!



Despite market fluctuations, the RF & HYPER EUROPE trade show is staying right on course, never losing sight of its mission; which is to showcase the latest technological advances and innovations in Radio frequencies, Hyper frequencies, Wireless and Fiber Optics.

- 8,000 sq.m of exhibition space, featuring 200 exhibitors, so visitors can DISCOVER the most recent developments;
- EMC conferences to GET AN UPDATE on the latest guidelines and standards being enforced;
- Conferences with more tangible applications for a better UNDERSTANDING:
- And keep in mind the Antenna zone and the Recruiting area.

RF & HYPER EUROPE is without doubt the most widely attended meeting of its kind, drawing numerous visitors and nearly 5,000 highly qualified professionals and exhibitors; those with the most expertise.

Find information 24 hours a day at:

www.birp.com/hyper

# 1, 2 & 3 APRIL 2003 - PARIS EXPO - PORTE DE VERSAILLES

Organised by :



11, rue du Perche - 75003 Paris - France - Tél. : + 33 1 44 78 99 30 - Fax : + 33 1 44 78 99 49 - e-mail : hyper@birp.fr

#### REQUEST FOR INFORMATION

ob Title:

Country:

Business activity:

Phone:

Fax:
E-mail:

Click LEADnet at mwjournal.com or Circle 80 on Reader Service Card

X
INDEX
7
15
VERTISING
NO
AD

CIRCLE No.	ADVERTISER	PAGE No.	PHONE	FAX	WEB/E-MAIL ADDRESS
42	JFW Industries Inc		317-887-1340	317-881-6790	www.jfwindustries.com
43	Johanson Technology	50	805-389-1166	805-389-1821	www.johansontechnology.com
44	K&L Microwave Inc	7	410-749-2424	410-749-5725	www.klmicrowave.com
45	Knowledge On Ltd	26	82-63-839-1150		www.knowledge-on.com
46	Lucix Corp	22	805-987-6645	805-987-6145	www.lucix.com
47	Marki Microwave	30	408-778-4200	408-778-4300	www.markimicrowave.com
48	Maury Microwave Corp	9	909-987-4715	909-987-1112	www.maurymw.com
49	MegaPhase	58	877-MegaPhase		www.MegaPhase.com
	Micro Comm	124	978-685-2272	978-794-5627	www.micsearch.com
50	Micro Lambda Wireless Inc	109	510-770-9221		www.microlambdawireless.com
52	Microwave Development				
	Company Inc			603-870-6210	www.mdc-inc.net
	Microwave Journal			781-769-5037	www.mwjournal.com
53	Midwest Microwave			44-0-1245-358938	www.midwest-microwave.ltd.uk
54	Mimix Broadband	54	281-526-0536		www.mimixbroadband.com
55,56,57,	Mini-Circuits				
58,59,60, 61,62,63	Corp		718-934-4500	718-332-4661	www.minicircuits.com
64,65,	MITEQ Inc				
66,67		107,127	631-436-7400	631-436-7430	www.miteq.com
68	Modular Components  National Inc	24	410-879-6553	410-838-7629	www.mcn-mmpc.com
69,70,71, 72,73	Narda Microwave-East, an L3 Communications Co		631-231-1700	631-231-1711	www.nardamicrowave.com
41	New Focus	23	805-445-9888	805-987-6990	www.jcatech.com
74	Noisecom	19	201-261-8797	201-261-8339	www.noisecom.com
75	Phase One Microwave Inc	38	916-660-1447	916-660-1698	www.phase1microwave.com
76	Presidio Components Inc		858-578-9390	800-538-3880	www.presidiocomponents.com
77	Programmed Test Sources Inc.		978-486-3400	978-486-4495	www.programmedtest.com
78	Quasar Microwave Technology	Ltd 52	44-1626-834222	44-1626-832994	www.qmtl.com
79	Reactel Inc.		301-519-3660	301-519-2447	www.reactel.com
80	RF & Hyper Europe		33-1-53-17-11-40	33-1-53-17-11-45	www.birp.com/hyper
81	RF Micro Devices	27,29	336-664-1233	336-931-7454	www.rfmd.com
82	RLC Electronics Inc		914-241-1334	914-241-1753	www.rlcelectronics.com
83	Salisbury Engineering Inc	39	800-989-2141	302-846-3888	www.salisbury-engineering.com
84	Satellink	125	972-487-1434	972-487-1204	e-mail: info@satellink.com
85	Sector Microwave Industries In	nc	631-242-2300	631-242-8158	www.sectormicrowave.com
86	Sirenza Microdevices		800-764-6642		www.sirenza.com
87	Sofimation		+358-9-670 370	+358-9-670 208	www.sofimation.com
88	Sonnet Software	COV 3	315-453-3096	315-451-1694	www.sonnetusa.com
89	Spectrum		49-89-354-804-0	49-89-354-804-90	www.spectrum-et.com
90	SV Microwave	60	561-840-1800	561-842-6277	www.svmicrowave.com
91	Swift & Associates		818-989-1133	818-989-4784	e-mail: sales@cwswift.com



Communication has always been a human need.



#### We believe it is also a human right.

At the International Telecommunication Union (ITU), we believe that no human right, including the right to communicate, can survive unless it is made real and relevant. As the United Nations specialized agency for telecommunications, it is our mission to bring the benefits of information and communication technologies to as many of the world's people as possible. This is why our 189 Member States and 660 private sector members work together to set universal telecommunication standards, establish international agreements and promote global development. Everyone has the right to communicate. We help give them the means. www.itu.int

Helping the world communicate



# ADVERTISING INDEX

CIRCLE No.	Advertiser	PAGE NO.	PHONE	FAX	WEB/E-MAIL ADDRESS
92,93,94	Synergy Microwave Corp		973-881-8800	973-881-8361	www.synergymwave.com
95	Trilithic Inc.	125	317-895-3600	317-895-3612	www.trilithic.com
96	Tru-Connector	53	978-532-0775	978-531-6993	www.tru-con.com
97	Vari-L Company Inc	97	303-371-1560	303-371-0845	www.vari-l.com
98	Velocium, a TRW Company	102–103	310-814-5749	310-812-7011	www.velocium.com
99	W.L. Gore & Associates Inc	113	800-445-4673	302-738-5993	www.gore.com
100	Werlatone Inc	62	845-279-6187	845-279-7404	www.werlatone.com
101	Wessex Electronics Ltd	80	(0) 117-957-1404	(0) 117-957-3843	www.wessexelectronics.co.uk
102	WJ Communications	25	800-WJ1-4401	408-577-6620	www.wj.com
103	Zeland Software Inc	36	510-623-7162	510-623-7135	www.zeland.com

Visit Microwave Journal on the Web at www.mwjournal.com

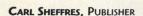
Click LEADnet<sup>™</sup> for information from our advertisers



JANUARY 2003 ISSUE

- Wireless Show Preview
- Antennas for Wireless Communications
- ► Advanced Airborne Precipitation Radar

## SALES REPRESENTATIVES



Eastern and Central Time Zones Carl Sheffres Publisher 685 Canton Street Norwood, MA 02062 Tel: (781) 769-5037 FAX: (781) 769-5037 csheffres@mwjournal.com

Tim O'Callaghan
Eastern Reg. Sales Mgr.
685 Canton Street
Norwood, MA 02062
Tel: (781) 769-9750
FAX: (781) 769-5037
tocallaghan@mvjournal.com

Eastern and Central Time Zones

Ed Johnson Associate Publisher PO Box 5962 Ocala, FL 34478-5962 Tel: (352) 620-2442 FAX: (352) 620-2443

Pacific and Mountain Time Zones

Wynn Cook Western Reg. Sales Mgr. PO Box 23200 San Jose, CA 95153 Tel: (408) 224-9060 FAX: (408) 224-6106 wynncook@ix.netcom.com

#### ED JOHNSON, ASSOCIATE PUBLISHER

International Sales Sam Baird Manager – Europe Michel Zoghob

Bill Porter 46 Gillingham Street London SWIV 1HH, England Tel: +44 207 596 8740 FAX: +44 207 596 8749 sbaird@horizonhouse.co.uk

Australia

James Tonkin Tonkin Media Pty. Ltd. 300 Scenic Highway Terrigal NSW 2260, Australia Tel: +61 43 85 1746 FAX: +61 43 85 2017 tonkinmedia@ozemail.com.au

Germany, Austria, and Switzerland

(German-speaking) Juergen Wissling Wissling Marketing Services Riedstrasse 5 72813 St. Johann-Wuertingen Germany Tel: +49 7122 828140 FAX: +49 7122 828145 j.wissling@wms-marketing.de

Israel

Oreet Ben Yaacov Oreet International Media 15 Kineret Street 51201 Bene-Berak, Israel Tel: +972 3 570 6527 FAX: +972 3 570 6526 michal@oreet-marcom.com the microwave journal

#### KEN HERNANDEZ, TRAFFIC ADMINISTRATOR

Japan Kenichi Takefusa Appeal Inc. Arpus Hiroo, 2F, 5-17-11 Hiroo, Shibuya-ku, Tokyo 150, Japan Tel: +81 3 3443 0895 FAX: +81 3 3443 0871

takefusa@mxb.mesh.ne.jp

Young-Seoh Chinn JES Media International 2nd Floor, ANA Bldg. 257-1, Myungil-Dong Kangdong-Gu Seoul, 134-070 Korea Tel: +82 2 481-3411 FAX: +82 2 481-3414

jesmedia@unitel.co.kr

Singapore

Hoong-Mun Koo Publicitas 02-01 Wellington Bldg. 20 Bideford Road Singapore 229921 Tel: +65 6836 2272 FAX: +65 6735 9653

Taiwan

Hiram Lai Arco Infocomm 4 F, No. 5, Sec. 1, Pa-Te Road Taipei, Taiwan ROC Tel: +886-2 396 5128 FAX: +886-2 396 4511

# Easy as ABS!

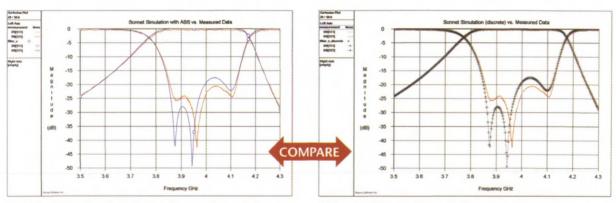
# NEW! in Sonnet 8.0

# Adaptive Band Synthesis for 3D Planar EM Simulation

With Sonnet's NEW Adaptive Band Synthesis (ABS) technique, you can achieve detailed simulation results in a small fraction of the time required by point-by-point EM simulation:

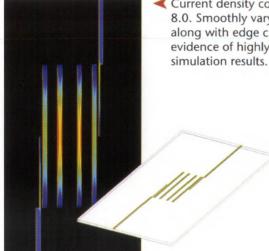
- 1. You enter Start and Stop Frequencies
- 2. Sonnet's ABS fills in the rest of the band for you with the shortest simulation possible

ABS uses the smallest number of discrete EM simulation samples possible, and provides a broadband S-, Y- or Z-parameter data sweep, cutting overall simulation time dramatically and filling in the fine spectral behavior with no reduction in accuracy! And it's reliable and stable for bandwidths exceeding 100x. Compare the results below between measured and calculated using an ABS sweep based on 4 discrete EM analysis frequencies on the left, and a full discrete frequency by frequency simulation on the right.



ABS simulation data based on 4 discrete EM analysis frequencies and measured data

300-point Discrete EM analysis and measured data



Superconducting Filter
—Superconductor Technologies,
courtesy Dr. George Matthaei.

 Current density computed by Sonnet 8.0. Smoothly varying current density along with edge current singularities are evidence of highly accurate EM simulation results





Toll-free in North America 877.776.6638 Phone: 315.453.3096

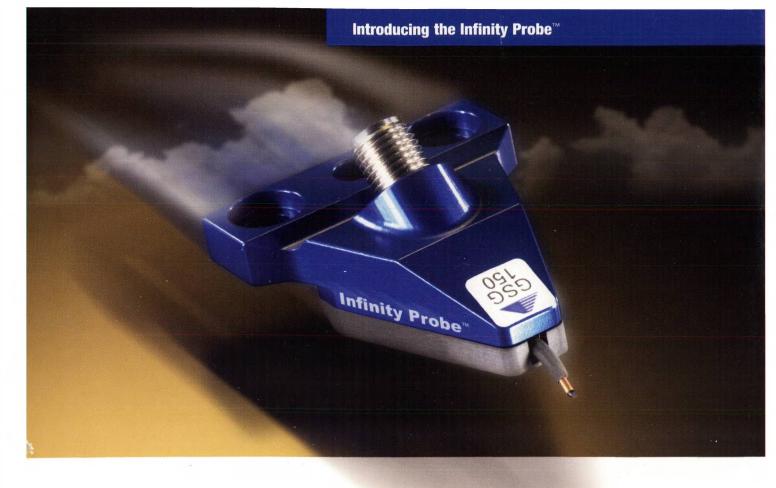
Fax: 315.451.1694

It's not just a demo, it's real software.

Download **Sonnet Lite**— A fully functional EM solver.

visit us at www.sonnetusa.com

1020 Seventh North Street, Suite 210 Liverpool, NY 13088 USA



# Follow the Path of Least Resistance.



- contact resistance of <0.1  $\Omega$  on aluminum pads
- probe device pads down to 50 x 50 μm
- 40, 50, 67 or 110 GHz versions
- · GSG, GS/SG
- 100 to 250 µm pitch

Introducing the Infinity Probe for high-performance, high-frequency device characterization and modeling. This revolutionary probe combines extremely low and stable contact resistance on aluminum pads with unsurpassed RF calibration and measurement accuracy to give you highly reliable and repeatable measurements in less time. The Infinity Probe achieves this incredible performance through the merging of Cascade Microtech's thin film technology and its 20-year RF probing expertise. The Infinity Probe is part of the family of turnkey RF probing solutions from Cascade Microtech, the company that made on-wafer, high-frequency probing possible.

How can you resist?

For a personal tour, visit us at: www.cascademicrotech.com/infinityprobe Or call 503-601-1000 or 1-800-550-3279 (USA & Canada). Japan: 03-5478-6100. Europe: +44 1295-812828.



©2002 Cascade Microtech, Inc. The Cascade Microtech logo and Infinity Probe are trademarks of Cascade Microtech, Inc.



CIRCLE 11: HAVE A SALES ENGINEER CONTACT ME
CIRCLE 12: SEND INFORMATION ON INFINITY PROBES

Innovating Test Technologies®